CO/Gas Detector Flash MCU

BA45F6720

Revision: V1.00 Date: August 21, 2020

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Features

CPU Features

- Operating voltage
  - f_{SYS}=8MHz: 2.2V~5.5V
- Up to 0.5μs instruction cycle with 8MHz system clock at V_{DD}=5V
- Power down and wake-up functions to reduce power consumption
- Oscillator types:
  - Internal High Speed 8MHz RC – HIRC
  - Internal Low Speed 32kHz RC – LIRC
- Multi-mode operation: FAST, SLOW, IDLE and SLEEP
- Fully integrated internal oscillators require no external components
- All instructions executed in one or two instruction cycles
- Table read instructions
- 61 powerful instructions
- 4-level subroutine nesting
- Bit manipulation instruction

Peripheral Features

- Flash Program Memory: 1K×14
- RAM Data Memory: 64×8
- True EEPROM Memory: 32×8
- Watchdog Timer function
- 4 bidirectional I/O lines
- One pin-shared external interrupt
- One Timer Module for time measurement, input capture, compare match output or PWM output or single pulse output function
- 4 external channel 12-bit resolution A/D converter with internal reference voltage V_{BGREF}
- CO/Gas detector AFE including an operational amplifier
- Dual Time-Base functions for generation of fixed time interrupt signals
- Internal LDO: 2.2V/2.5V/3.0V output
- Temperature sensor with internal reference voltage
- Low voltage rest function
- Package types: 8/10-pin SOP

General Description

The BA45F6720 device is a Flash Memory A/D type 8-bit high performance RISC architecture microcontroller, specifically designed for CO/Gas detector applications.

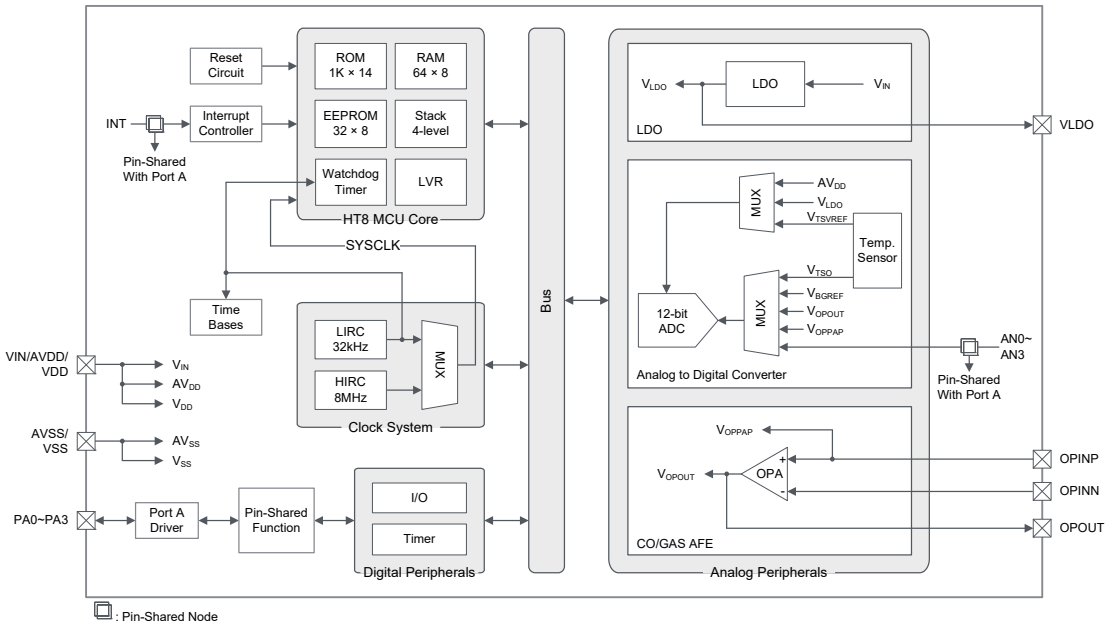
For memory features, the Flash Memory offers users the convenience of multi-programming features. Other memory includes an area of RAM Data Memory as well as an area of true EEPROM memory for storage of non-volatile data such as serial numbers, calibration data etc.

Analog features include a multi-channel 12-bit A/D converter with temperature sensor function and an operational amplifier. One extremely flexible Timer Module provides timing, pulse generation and PWM generation functions. In addition, an internal LDO function provides various power options to the internal modules and external devices. Protective features such as an internal Watchdog Timer and Low Voltage Reset coupled with excellent noise immunity and ESD protection ensure that reliable operation is maintained in hostile electrical environments.

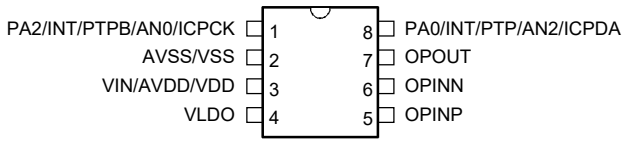
A full choice of internal high and low oscillators is provided including two fully integrated system oscillators which require no external components for their implementation. The ability to operate and switch dynamically between a range of operating modes using different clock sources gives users the ability to optimize microcontroller operation and minimize power consumption.

The inclusion of flexible I/O programming features, Time-Base functions along with many other features ensure that the device will find excellent use in CO/Gas detector applications.

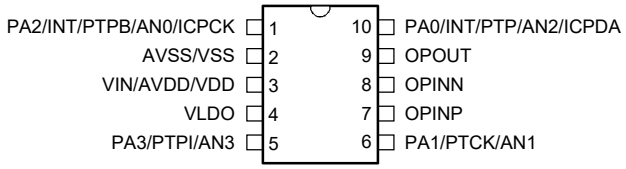
Block Diagram



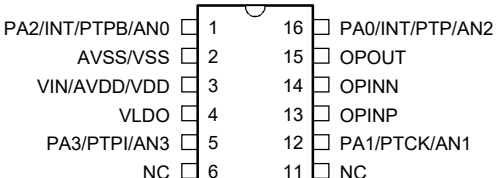
Pin Assignment



BA45F6720
8 SOP-A



BA45F6720
10 SOP-A



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Note: 1. If the pin-shared pin functions have multiple outputs simultaneously, the desired pin-shared function is determined by the corresponding software control bits.
2. The OCDSDA and OCDSCK pins are supplied for the OCDS dedicated pins and as such only available for the BA45V6720 device which is the OCDS EV chip for the BA45F6720 device.
3. For the less pin count package type there will be unbounded pins which should be properly configured to avoid unwanted power consumption resulting from floating input conditions. Refer to the "Standby Current Considerations" and "Input/Output Ports" sections.

Pin Description

The function of each pin is listed in the following table, however the details behind how each pin is configured is contained in other sections of the datasheet. As the Pin Description table shows the situation for the package with the most pins, not all pins in the table will be available on smaller package sizes.

Pin Name	Function	OPT	I/T	O/T	Description
PA0/INT/PTP/AN2/ICPDA	PA0	PAPU PAWU PAS0	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	INT	PAS0 IFS INTEG INTC0	ST	—	External interrupt input
	PTP	PAS0	—	CMOS	PTM output
	AN2	PAS0	AN	—	A/D Converter external input 2
	ICPDA	—	ST	CMOS	ICP address/data

Pin Name	Function	OPT	I/T	O/T	Description
PA1/PTCK/AN1	PA1	PAPU PAWU PAS0	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	PTCK	PAS0	ST	—	PTM clock input
	AN1	PAS0	AN	—	A/D Converter external input 1
PA2/INT/PTPB/AN0/ICPCK	PA2	PAPU PAWU PAS0	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	INT	PAS0 IFS INTEG INTC0	ST	—	External interrupt input
	PTPB	PAS0	—	CMOS	PTM inverted output
	AN0	PAS0	AN	—	A/D Converter external input 0
	ICPCK	—	ST	—	ICP clock
PA3/PTPI/AN3	PA3	PAPU PAWU PAS0	ST	CMOS	General purpose I/O. Register enabled pull-up and wake-up
	PTPI	PAS0	ST	—	PTM capture input
	AN3	PAS0	AN	—	A/D Converter external input 3
OPINP	OPINP	—	AN	—	OPA positive input
OPINN	OPINN	—	AN	—	OPA negative input
OPOUT	OPOUT	—	—	AN	OPA output
OCDSCK	OCDSCK	—	ST	—	OCDS clock pin, for EV chip only
OCDSDA	OCDSDA	—	ST	CMOS	OCDS data/address pin, for EV chip only
VLDO	VLDO	—	—	PWR	LDO output
VIN/AVDD/VDD	VIN	—	PWR	—	LDO positive power supply
	AVDD	—	PWR	—	A/D Converter positive power supply
	VDD	—	PWR	—	Digital positive power supply
AVSS/VSS	AVSS	—	PWR	—	A/D Converter negative power supply, ground
	VSS	—	PWR	—	Digital negative power supply, ground

Legend: I/T: Input type;
OPT: Optional by register option;
ST: Schmitt Trigger input;
NMOS: NMOS output;
O/T: Output type;
PWR: Power;
CMOS: CMOS output;
AN: Analog signal

Absolute Maximum Ratings

Supply Voltage ..... V_{SS}-0.3V to 6.0V

Input Voltage ..... V_{SS}-0.3V to V_{DD}+0.3V

Storage Temperature ..... -50°C to 125°C

Operating Temperature ..... -40°C to 85°C

I_{OH} Total ..... -80mA

I_{OL} Total 80mA

Total Power Dissipation 500mW

Note: These are stress ratings only. Stresses exceeding the range specified under “Absolute Maximum Ratings” may cause substantial damage to the device. Functional operation of the device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

D.C. Characteristics

For data in the following tables, note that factors such as oscillator type, operating voltage, operating frequency, pin load conditions, temperature and program instruction type, etc., can all exert an influence on the measured values.

Operating Voltage Characteristics

Ta=-40°C~85°C

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_{DD}	Operating Voltage – HIRC	$f_{SYS}=f_{HIRC}$=8MHz	2.2	—	5.5	V
	Operating Voltage – LIRC	$f_{SYS}=f_{LIRC}$=32kHz	2.2	—	5.5	V

Operating Current Characteristics

Ta=-40°C~85°C

Symbol	Operating Mode	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
I_{DD}	SLOW Mode – LIRC	2.2V	f_{SYS}=32kHz	—	8	16	μA
		3V		—	10	20	
		5V		—	30	50	
	FAST Mode – HIRC	2.2V	f_{SYS}=8MHz	—	0.6	1.0	mA
		3V		—	0.8	1.2	
		5V		—	1.6	2.4	

Note: When using the characteristic table data, the following notes should be taken into consideration:
1. Any digital inputs are setup in a non-floating condition.
2. All measurements are taken under conditions of no load and with all peripherals in an off state.
3. There are no DC current paths.
4. All Operating Current values are measured using a continuous NOP instruction program loop.

Standby Current Characteristics

Ta=-40°C~85°C, unless otherwise specified

Symbol	Standby Mode	Test Conditions		Min.	Typ.	Max.	Max. @85°C	Unit
		V_{DD}	Conditions					
I_{STB}	SLEEP Mode	2.2V	WDT off	—	0.2	0.6	0.7	μA
		3V		—	0.2	0.8	1.0	
		5V		—	0.5	1.0	1.2	
		2.2V	WDT on	—	1.2	2.4	2.9	μA
		3V		—	1.5	3.0	3.6	
		5V		—	3	5	6	
	IDLE0 Mode – LIRC	2.2V	f_{SUB} on	—	2.4	4.0	4.8	μA
		3V		—	3	5	6	
		5V		—	5	10	12	
	IDLE1 Mode – HIRC	2.2V	f_{SUB} on, f_{SYS}=8MHz	—	288	400	480	μA
		3		—	360	500	600	
		5V		—	600	800	960	

Note: When using the characteristic table data, the following notes should be taken into consideration:
1. Any digital inputs are setup in a non-floating condition.
2. All measurements are taken under conditions of no load and with all peripherals in an off state.
3. There are no DC current paths.

4. All Standby Current values are taken after a HALT instruction execution thus stopping all instruction execution.

A.C. Characteristics

For data in the following tables, note that factors such as oscillator type, operating voltage, operating frequency and temperature etc., can all exert an influence on the measured values.

High Speed Internal Oscillator – HIRC – Frequency Accuracy

During the program writing operation the writer will trim the HIRC oscillator at a user selected HIRC frequency and user selected voltage of either 3V or 5V.

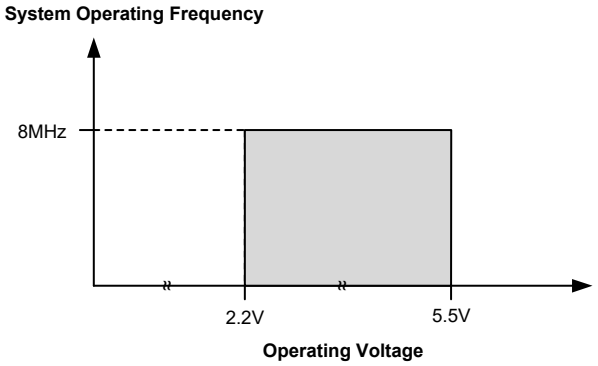
Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Temp.				
f_{HIRC}	8MHz Writer Trimmed HIRC Frequency	3V/5V	25°C	-1%	8	+1%	MHz
			-40°C~85°C	-2%	8	+2%	
		2.2V~5.5V	25°C	-2.5%	8	+2.5%	
			-40°C~85°C	-3%	8	+3%	

Note: 1. The 3V/5V values for V_{DD} are provided as these are the two selectable fixed voltages at which the HIRC frequency is trimmed by the writer.
2. The row below the 3V/5V trim voltage row is provided to show the values for the full V_{DD} range operating voltage. It is recommended that the trim voltage is fixed at 3V for application voltage ranges from 2.2V to 3.6V and fixed at 5V for application voltage ranges from 3.3V to 5.5V.

Low Speed Internal Oscillator Characteristics – LIRC

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Temp.				
f_{LIRC}	Oscillator Frequency	2.2V~5.5V	-40°C~85°C	-7%	32	+7%	kHz
t_{START}	LIRC Start Up Time	—	-40°C~85°C	—	—	100	μs

Operating Frequency Characteristic Curves



System Start Up Time Characteristics

Ta=-40°C~85°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
t_{SST}	System Start-up Time Wake-up from condition where f_{SYS} is off	—	$f_{SYS}=f_H\sim f_H/64$, $f_H=f_{HIRC}$	—	16	—	t_{HIRC}
		—	$f_{SYS}=f_{SUB}=f_{LIRC}$	—	2	—	t_{LIRC}
	System Start-up Time Wake-up from condition where f_{SYS} is on	—	$f_{SYS}=f_H\sim f_H/64$, $f_H=f_{HIRC}$	—	2	—	t_H
		—	$f_{SYS}=f_{SUB}=f_{LIRC}$	—	2	—	t_{SUB}
	System Speed Switch Time FAST to SLOW Mode or SLOW to FAST Mode	—	f_{HIRC} switches from off → on	—	16	—	t_{HIRC}
t_{RSTD}	System Reset Delay Time Reset source from Power-on Reset or LVR Hardware Reset	—	RR_{POR}=5V/ms	14	16	18	ms
	System Reset Delay Time LVRC/WDTC Software Reset	—	—				
	System Reset Delay Time Reset source from WDT Overflow	—	—	14	16	18	ms
t_{SRESET}	Minimum Software Reset Width to Reset	—	—	45	90	120	μs

Note: 1. For the System Start-up time values, whether f_{SYS} is on or off depends upon the mode type and the chosen f_{SYS} system oscillator. Details are provided in the System Operating Modes section.
2. The time units, shown by the symbol t_{HIRC} etc. are the inverse of the corresponding frequency values as provided in the frequency tables. For example $t_{HIRC}=1/f_{HIRC}$, $t_{SYS}=1/f_{SYS}$ etc.
3. If the LIRC is used as the system clock and if it is off when in the SLEEP Mode, then an additional LIRC start up time, t_{START}, as provided in the LIRC frequency table, must be added to the t_{SST} time in the table above.
4. The System Speed Switch Time is effectively the time taken for the newly activated oscillator to start up.

Input/Output Characteristics

Ta=-40°C~85°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{IL}	Input Low Voltage for I/O Ports or Input Pins	5V	—	0	—	1.5	V
		—	—	0	—	$0.2V_{DD}$	
V_{IH}	Input High Voltage for I/O Ports or Input Pins	5V	—	3.5	—	5.0	V
		—	—	$0.8V_{DD}$	—	V_{DD}	
I_{OL}	Sink Current for I/O Ports	3V	$V_{OL}=0.1V_{DD}$	16	32	—	mA
		5V		32	65	—	
I_{OH}	Source Current for I/O Ports	3V	$V_{OH}=0.9V_{DD}$	-4	-8	—	mA
		5V		-8	-16	—	
R_{PH}	Pull-high Resistance for I/O Ports (Note)	3V	—	20	60	100	kΩ
		5V	—	10	30	50	
I_{LEAK}	Input Leakage Current	5V	$V_{IN}=V_{DD}$ or $V_{IN}=V_{SS}$	—	—	±1	μA
t_{TPI}	PTM Capture Input Minimum Pulse Width	—	—	0.1	—	—	μs
t_{TCK}	PTM Clock Input Minimum Pulse Width	—	—	0.3	—	—	μs
f_{TMCLK}	PTM Maximum Timer Clock Source Frequency	5V	—	—	—	1	f_{SYS}
t_{CPW}	PTM Minimum Capture Pulse Width	—	—	2	—	—	t_{TMCLK}

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
t_{INT}	External Interrupt Input Minimum Pulse Width	—	—	10	—	—	μs

Note: 1. The R_{PH} internal pull high resistance value is calculated by connecting to ground and enabling the input pin with a pull-high resistor and then measuring the pin current at the specified supply voltage level. Dividing the voltage by this measured current provides the R_{PH} value.
2. $t_{TMCLK}=1/f_{TMCLK}$.

Memory Characteristics

Ta=-40°C~85°C, unless otherwise specified

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{DD}	Operating Voltage for Read/Write	—	—	V_{DDmin}	—	V_{DDmax}	V
Flash Program Memory / Data EEPROM Memory							
t_{DEW}	Erase / Write Cycle Time – Flash Program Memory	5.0V	—	—	2	3	ms
	Write Cycle Time – Data EEPROM Memory	—	—	—	4	6	ms
I_{DDPGM}	Programming / Erase Current on V_{DD}	5.0V	—	—	—	5.0	mA
E_P	Cell Endurance – Flash Program Memory	—	—	10K	—	—	E/W
	Cell Endurance – Data EEPROM Memory	—	—	100K	—	—	
t_{RETD}	ROM Data Retention time	—	Ta=25°C	—	40	—	Year
RAM Data Memory							
V_{DR}	RAM Data Retention Voltage	—	Device in SLEEP Mode	1.0	—	—	V

LVR Electrical Characteristics

Ta=25°C, unless otherwise specified

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{LVR}	Low Voltage Reset Voltage	—	LVR enable, voltage select 2.1V, Ta=-40°C~85°C	-5%	2.1	+5%	V
I_{LVR}	Operating Current	3V	LVR enable, V_{LVR}=2.1V	—	—	15	μA
		5V		—	15	25	
t_{LVR}	Minimum Low Voltage Width to Reset	—	—	120	240	480	μs

A/D Converter Electrical Characteristics

Ta=-40°C~85°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{DD}	A/D Converter Operating Voltage	—	—	2.2	—	5.5	V
V_{ADI}	A/D Converter Input Voltage	—	—	0	—	V_{REF}	V
V_{REF}	A/D Converter Reference Voltage	—	—	2.2	—	V_{DD}	V
N_R	Resolution	—	—	—	—	12	Bit
DNL	A/D Differential Non-linearity	—	$V_{REF}=V_{DD}$, t_{ADCK}=0.5μs	-3	—	3	LSB
INL	A/D Integral Non-linearity	—	$V_{REF}=V_{DD}$, t_{ADCK}=0.5μs	-4	—	4	LSB

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
I_{ADC}	Additional Current Consumption for A/D Converter Enable	2.2V	No load, t_{ADCK}=0.5μs	—	300	420	μA
		3V		—	340	500	μA
		5V		—	500	700	μA
t_{ADCK}	A/D Converter Clock Period	—	AN≠Temperature sensor output	0.5	—	10.0	μs
		2.2V~5.5V	AN=Temperature sensor output	1	—	2	μs
t_{ON2ST}	A/D Converter On-to-Start Time	—	—	4	—	—	μs
t_{ADS}	A/D Sampling Time	—	AN≠Temperature sensor output	—	4	—	t_{ADCK}
		2.2V~5.5V	AN=Temperature sensor output	—	46	—	t_{ADCK}
t_{ADC}	A/D Conversion Time (Including A/D Sample and Hold Time)	—	AN≠Temperature sensor output	—	16	—	t_{ADCK}
		2.2V~5.5V	AN=Temperature sensor output	—	58	—	t_{ADCK}
GERR	A/D Conversion Gain Error	—	V_{REF}=V_{DD}	-4	—	4	LSB
OSRR	A/D Conversion Offset Error	—	V_{REF}=V_{DD}	-4	—	4	LSB

Reference Voltage Electrical Characteristics

Ta=-40°C~85°C, unless otherwise specified

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{DD}	Operating Voltage	—	—	2.2	—	5.5	V
V_{BGREF}	Bandgap Reference Voltage	—	Ta=-40°C~85°C	-1%	1.2	+1%	V
I_{BGREF}	Operating Current	5.5V	—	—	25	40	μA
PSRR	Power Supply Rejection Ratio	—	Ta=25°C, V_{RIPPLE}=1V_{P-P}, f_{RIPPLE}=100Hz	75	—	—	dB
En	Output Noise	—	Ta=25°C, no load current, f=0.1Hz~10Hz	—	300	—	μV_{RMS}
I_{DRV}	Buffer Driving Capability	—	ΔV_{BGREF}=-1%	1	—	—	mA
I_{SD}	Shutdown Current	—	VBGREN=0	—	—	0.1	μA
t_{START}	Startup Time	2.2V~5.5V	Ta=25°C	—	—	400	μs

Note: 1. All the above parameters are measured under conditions of no load condition unless otherwise described.
2. A 0.1μF ceramic capacitor should be connected between VDD and ground.
3. The V_{BGREF} voltage is used as the A/D converter internal input.

Temperature Sensor Electrical Characteristics

Ta=25°C, unless otherwise specified

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{DD}	Temperature Sensor Operating Voltage	—	—	2.2	—	5.5	V
I_{TS}	Temperature Sensor Operating Current	3V	TSEN=ADCEN=1, t_{ADCK}=1μs, A/D Converter included	—	1260	1950	μA
		5V		—	1490	2250	μA
t_{TSS}	Temperature Sensor Turn On Stable Time	3V	—	—	—	100	μs
		5V		—	—	100	μs
V_{TSVREF}	Temperature Sensor Reference Voltage	3V	—	-5%	2.01	+5%	V
		5V		-5%	2.01	+5%	V
T_{LE}	Temperature Linearity Error	—	—	—	±1	±2	°C
T_{ACC}	Temperature Accuracy (Error)	2.7V~4.5V	V_{REF}=V_{TSVREF}, Ta=0°C~70°C (After linear calibration) (Note)	-2.0	—	+2.0	°C
		2.7V~5.5V		-2.5	—	+2.5	
		—		—	±4.0	—	
		2.7V~5.5V	V_{REF}=V_{TSVREF}, Ta=-40°C~85°C (After linear calibration) (Note)	-4.0	—	+4.0	
		—		—	±5.0	—	
$TS_{\_Noise}$	Temperature Noise	3V	No average	—	0.4	—	°C (p-p)
		5V		—	0.6	—	°C (p-p)

Note: Linear calibration is implemented using the linear formula which is established on the relation between the two calibrated temperatures and their corresponding ADC code. The temperature accuracy T_{ACC} is defined as the error between the actual temperature and the temperature obtained by the conversion of the ADC code through the formula.

Operational Amplifier Electrical Characteristics

V_{DD}=5V, Ta=25°C

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{OPA}	Operating Current	No load, OPBW[1:0]=00B	—	3.0	5.0	μA
		No load, OPBW[1:0]=01B	—	10	16	
		No load, OPBW[1:0]=10B	—	80	128	
		No load, OPBW[1:0]=11B	—	200	320	
V_{OS}	Input Offset Voltage	Without calibration (OPOF[5:0]=100000B)	-15	—	+15	mV
		With calibration	-4	—	+4	
I_{OS}	Input Offset Current	V_{IN}=(1/2)V_{CM}	—	1	10	nA
V_{CM}	Common Mode Voltage Range	OPBW[1:0]=00B/01B/10B/11B	V_{SS}	—	V_{DD}-1.4	V
PSRR	Power Supply Rejection Ratio	OPBW[1:0]=00B/01B/10B/11B	50	70	—	dB
CMRR	Common Mode Rejection Ratio	OPBW[1:0]=00B/01B/10B/11B	50	80	—	dB
A_{OL}	Open Loop Gain	OPBW[1:0]=00B/01B/10B/11B	60	80	—	dB
SR	Slew Rate	R_{LOAD}=1MΩ, C_{LOAD}=60pF, OPBW[1:0]=00B	0.5	1.5	—	V/ms
		R_{LOAD}=1MΩ, C_{LOAD}=60pF, OPBW[1:0]=01B	5	15	—	
		R_{LOAD}=1MΩ, C_{LOAD}=60pF, OPBW[1:0]=10B	180	500	—	
		R_{LOAD}=1MΩ, C_{LOAD}=60pF, OPBW[1:0]=11B	600	1800	—	

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
GBW	Gain Bandwidth	R_{LOAD}=1MΩ, C_{LOAD}=60pF, OPBW[1:0]=00B	1.5	5.0	—	kHz
		R_{LOAD}=1MΩ, C_{LOAD}=60pF, OPBW[1:0]=01B	15	40	—	
		R_{LOAD}=1MΩ, C_{LOAD}=60pF, OPBW[1:0]=10B	400	600	—	
		R_{LOAD}=1MΩ, C_{LOAD}=60pF, OPBW[1:0]=11B	1000	2000	—	
V_{OR}	Maximum Output Voltage Range	OPBW[1:0]=00B/01B, R_{LOAD}=10kΩ to V_{DD}/2	V_{SS}+140	—	V_{DD}-160	mV
		OPBW[1:0]=10B/11B, R_{LOAD}=10kΩ to V_{DD}/2	V_{SS}+120	—	V_{DD}-140	
I_{SC}	Output Short Circuit Current	R_{LOAD}=5.1Ω, OPBW[1:0]=00B/01B	±6	±12	—	mA
		R_{LOAD}=5.1Ω, OPBW[1:0]=10B/11B	±10	±20	—	

Note: These parameters are characterized but not tested.

V_{DD}=2.2V~5.5V, Ta=25°C

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{OPA}	Operating Current	No load, OPBW[1:0]=00B	—	2.5	4.0	μA
		No load, OPBW[1:0]=01B	—	10	16	
		No load, OPBW[1:0]=10B	—	80	128	
		No load, OPBW[1:0]=11B	—	200	320	
V_{OS}	Input Offset Voltage	Without calibration (OPOF[5:0]=100000B)	-15	—	+15	mV
		With calibration	-6	—	+6	
I_{OS}	Input Offset Current	V_{IN}=(1/2)V_{CM}	—	1	10	nA
V_{CM}	Common Mode Voltage Range	OPBW[1:0]=00B/01B/10B/11B	V_{SS}	—	V_{DD}-1.4	V
PSRR	Power Supply Rejection Ratio	OPBW[1:0]=00B/01B/10B/11B	50	70	—	dB
CMRR	Common Mode Rejection Ratio	OPBW[1:0]=00B/01B/10B/11B	50	80	—	dB
A_{OL}	Open Loop Gain	OPBW[1:0]=00B/01B/10B/11B	60	80	—	dB
SR	Slew Rate	R_{LOAD}=1MΩ, C_{LOAD}=60pF, OPBW[1:0]=00B	0.5	1.5	—	V/ms
		R_{LOAD}=1MΩ, C_{LOAD}=60pF, OPBW[1:0]=01B	5	15	—	
		R_{LOAD}=1MΩ, C_{LOAD}=60pF, OPBW[1:0]=10B	180	500	—	
		R_{LOAD}=1MΩ, C_{LOAD}=60pF, OPBW[1:0]=11B	600	1800	—	
GBW	Gain Bandwidth	R_{LOAD}=1MΩ, C_{LOAD}=60pF, OPBW[1:0]=00B	1	5	—	kHz
		R_{LOAD}=1MΩ, C_{LOAD}=60pF, OPBW[1:0]=01B	10	40	—	
		R_{LOAD}=1MΩ, C_{LOAD}=60pF, OPBW[1:0]=10B	250	600	—	
		R_{LOAD}=1MΩ, C_{LOAD}=60pF, OPBW[1:0]=11B	800	2000	—	
V_{OR}	Maximum Output Voltage Range	OPBW[1:0]=00B/01B, R_{LOAD}=10kΩ to V_{DD}/2	V_{SS}+140	—	V_{DD}-160	mV
		OPBW[1:0]=10B/11B, R_{LOAD}=10kΩ to V_{DD}/2	V_{SS}+120	—	V_{DD}-140	
I_{SC}	Output Short Circuit Current	R_{LOAD}=5.1Ω, OPBW[1:0]=00B/01B	±1.2	±12.0	—	mA
		R_{LOAD}=5.1Ω, OPBW[1:0]=10B/11B	±2	±20	—	

Note: These parameters are characterized but not tested.

LDO Electrical Characteristics

V_{IN}=V_{OUT}+0.3V, C_{LOAD}=4.7μF, Ta=-40°C~85°C, unless otherwise specified

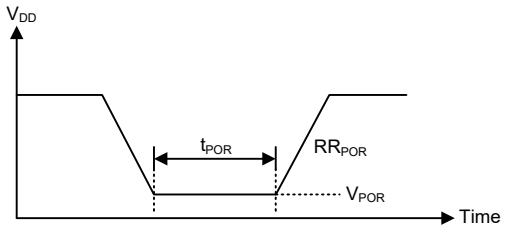
Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{IN}	Input Voltage	—	—	2.5	—	5.5	V
V_{OUT}	Output Voltage	—	Ta=25°C, I_{LOAD}=1mA, V_{OUT}=2.2V	-3%	2.2	+3%	V
			Ta=-40°C~85°C, I_{LOAD}=1mA, V_{OUT}=2.2V	-5%	2.2	+5%	
		—	Ta=25°C, I_{LOAD}=1mA, V_{OUT}=2.5V	-2%	2.5	+2%	V
			Ta=-40°C~85°C, I_{LOAD}=1mA, V_{OUT}=2.5V	-5%	2.5	+5%	
		—	Ta=25°C, I_{LOAD}=1mA, V_{OUT}=3.0V	-2%	3.0	+2%	V
			Ta=-40°C~85°C, I_{LOAD}=1mA, V_{OUT}=3.0V	-5%	3.0	+5%	
I_Q	Quiescent Current	5V	No load	—	2.3	5.0	μA
I_{OUT}	Output Current	—	V_{IN}=2.5V, ΔV_{OUT}=0.1V, V_{OUT}=2.2V	10	—	—	mA
		—	V_{IN}=2.8V, ΔV_{OUT}=0.1V, V_{OUT}=2.5V	15	—	—	mA
		—	V_{IN}=3.4V, ΔV_{OUT}=0.1V, V_{OUT}=3.0V	30	—	—	mA
TC	Temperature Coefficient	—	Ta=-40°C~85°C, I_{LOAD}=10mA	—	±1.5	±2.0	mV/°C

Note: Load regulation is measured at a constant junction temperature, using pulse testing with a low ON time and is guaranteed up to the maximum power dissipation. Power dissipation is determined by the input/output differential voltage and the output current. Guaranteed maximum power dissipation will not be available over the full input/output range. The maximum allowable power dissipation at any ambient temperature is P_D=($T_{J(MAX)}$-Ta)/θ_{JA}.

Power-on Reset Characteristics

Ta=25°C

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		V_{DD}	Conditions				
V_{POR}	V_{DD} Start Voltage to Ensure Power-on Reset	—	—	—	—	100	mV
RR_{POR}	V_{DD} Rising Rate to Ensure Power-on Reset	—	—	0.035	—	—	V/ms
t_{POR}	Minimum Time for V_{DD} Stays at V_{POR} to Ensure Power-on Reset	—	—	1	—	—	ms



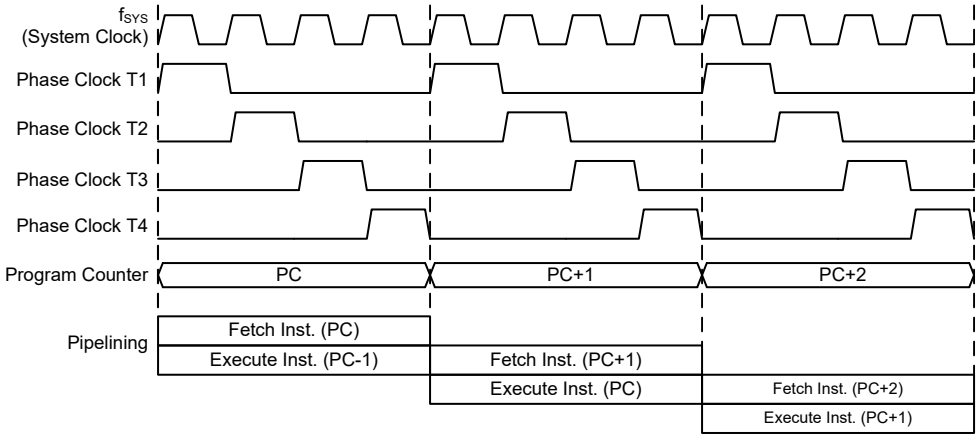
System Architecture

A key factor in the high-performance features of the range of microcontrollers is attributed to their internal system architecture. The device takes advantage of the usual features found within RISC microcontrollers providing increased speed of operation and enhanced performance. The pipelining scheme is implemented in such a way that instruction fetching and instruction execution are overlapped, hence instructions are effectively executed in one cycle, with the exception of branch or call instructions which need one more cycle. An 8-bit wide ALU is used in practically all instruction set operations, which carries out arithmetic operations, logic operations, rotation, increment, decrement, branch decisions, etc. The internal data path is simplified by moving data through the Accumulator and the ALU. Certain internal registers are implemented in the Data Memory and can be directly or indirectly addressed. The simple addressing methods of these registers along with additional architectural features ensure that a minimum of external components is required to provide a functional I/O and A/D control system with maximum reliability and flexibility. This makes the device suitable for low-cost, high-volume production for controller applications.

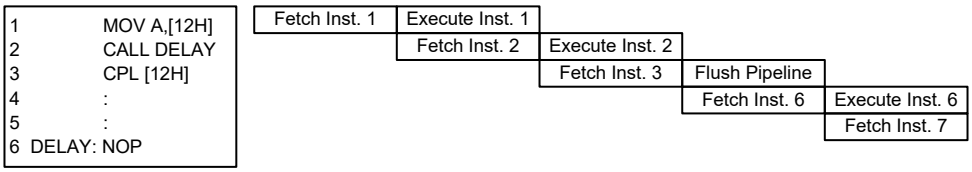
Clocking and Pipelining

The main system clock, derived from either an HIRC or LIRC oscillator is subdivided into four internally generated non-overlapping clocks, T1~T4. The Program Counter is incremented at the beginning of the T1 clock during which time a new instruction is fetched. The remaining T2~T4 clocks carry out the decoding and execution functions. In this way, one T1~T4 clock cycle forms one instruction cycle. Although the fetching and execution of instructions takes place in consecutive instruction cycles, the pipelining structure of the microcontroller ensures that instructions are effectively executed in one instruction cycle. The exception to this are instructions where the contents of the Program Counter are changed, such as subroutine calls or jumps, in which case the instruction will take one more instruction cycle to execute.

For instructions involving branches, such as jump or call instructions, two machine cycles are required to complete instruction execution. An extra cycle is required as the program takes one cycle to first obtain the actual jump or call address and then another cycle to actually execute the branch. The requirement for this extra cycle should be taken into account by programmers in timing sensitive applications.



System Clocking and Pipelining



Instruction Fetching

Program Counter

During program execution, the Program Counter is used to keep track of the address of the next instruction to be executed. It is automatically incremented by one each time an instruction is executed except for instructions, such as "JMP" or "CALL" that demands a jump to a non-consecutive Program Memory address. Only the lower 8 bits, known as the Program Counter Low Register, are directly addressable by the application program.

When executing instructions requiring jumps to non-consecutive addresses such as a jump instruction, a subroutine call, interrupt or reset, etc., the microcontroller manages program control by loading the required address into the Program Counter. For conditional skip instructions, once the condition has been met, the next instruction, which has already been fetched during the present instruction execution, is discarded and a dummy cycle takes its place while the correct instruction is obtained.

Program Counter	
High Byte	**Low Byte (PCL)**
PC9~PC8	PCL7~PCL0

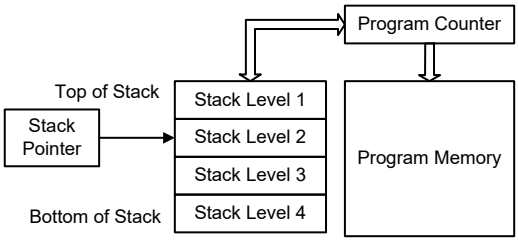
Program Counter

The lower byte of the Program Counter, known as the Program Counter Low register or PCL, is available for program control and is a readable and writeable register. By transferring data directly into this register, a short program jump can be executed directly. However, as only this low byte is available for manipulation, the jumps are limited to the present page of memory, that is 256 locations. When such program jumps are executed it should also be noted that a dummy cycle will be inserted. Manipulating the PCL register may cause program branching, so an extra cycle is needed to pre-fetch.

Stack

This is a special part of the memory which is used to save the contents of the Program Counter only. The stack is organized into 4 levels and neither part of the data nor part of the program space, and is neither readable nor writeable. The activated level is indexed by the Stack Pointer, and is neither readable nor writeable. At a subroutine call or interrupt acknowledge signal, the contents of the Program Counter are pushed onto the stack. At the end of a subroutine or an interrupt routine, signaled by a return instruction, RET or RETI, the Program Counter is restored to its previous value from the stack. After a device reset, the Stack Pointer will point to the top of the stack.

If the stack is full and an enabled interrupt takes place, the interrupt request flag will be recorded but the acknowledge signal will be inhibited. When the Stack Pointer is decremented, by RET or RETI, the interrupt will be serviced. This feature prevents stack overflow allowing the programmer to use the structure more easily. However, when the stack is full, a CALL subroutine instruction can still be executed which will result in a stack overflow. Precautions should be taken to avoid such cases which might cause unpredictable program branching. If the stack is overflow, the first Program Counter save in the stack will be lost.



Arithmetic and Logic Unit – ALU

The arithmetic-logic unit or ALU is a critical area of the microcontroller that carries out arithmetic and logic operations of the instruction set. Connected to the main microcontroller data bus, the ALU receives related instruction codes and performs the required arithmetic or logical operations after which the result will be placed in the specified register. As these ALU calculation or operations may result in carry, borrow or other status changes, the status register will be correspondingly updated to reflect these changes. The ALU supports the following functions:

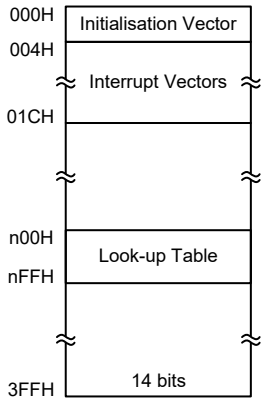
- Arithmetic operations: ADD, ADDM, ADC, ADCM, SUB, SUBM, SBC, SBCM, DAA
- Logic operations: AND, OR, XOR, ANDM, ORM, XORM, CPL, CPLA
- Rotation: RRA, RR, RRCA, RRC, RLA, RL, RLCA, RLC
- Increment and Decrement: INCA, INC, DECA, DEC
- Branch decision: JMP, SZ, SZA, SNZ, SIZ, SDZ, SIZA, SDZA, CALL, RET, RETI

Flash Program Memory

The Program Memory is the location where the user code or program is stored. For this device the Program Memory is Flash type, which means it can be programmed and re-programmed a large number of times, allowing the user the convenience of code modification on the same device. By using the appropriate programming tools, the Flash device offer users the flexibility to conveniently debug and develop their applications while also offering a means of field programming and updating.

Structure

The Program Memory has a capacity of 1K×14 bits. The Program Memory is addressed by the Program Counter and also contains data, table information and interrupt entries. Table data, which can be setup in any location within the Program Memory, is addressed by a separate table pointer register.



Program Memory Structure

Special Vectors

Within the Program Memory, certain locations are reserved for the reset and interrupts. The location 000H is reserved for use by the device reset for program initialisation. After a device reset is initiated, the program will jump to this location and begin execution.

Look-up Table

Any location within the Program Memory can be defined as a look-up table where programmers can store fixed data. To use the look-up table, the table pointer must first be setup by placing the address of the look up data to be retrieved in the table pointer register, TBLP. The register defines the total address of the look-up table.

After setting up the table pointer, the table data can be retrieved from the Program Memory using the "TABRD [m]" or "TABRDL [m]" instructions, respectively. When the instruction is executed, the lower order table byte from the Program Memory will be transferred to the user defined Data Memory register [m] as specified in the instruction. The higher order table data byte from the Program Memory will be transferred to the TBLH special register. Any unused bits in this transferred higher order byte will be read as 0.

The accompanying diagram illustrates the addressing data flow of the look-up table.

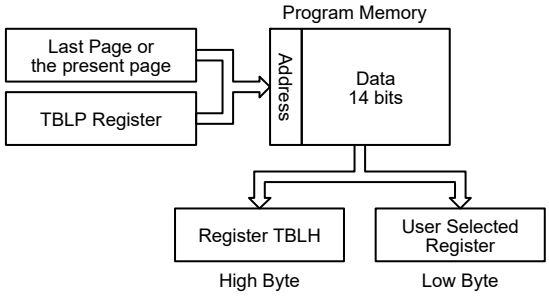


Table Program Example

The following example shows how the table pointer and table data is defined and retrieved from the microcontroller. This example uses raw table data located in the Program Memory which is stored there using the ORG statement. The value at this ORG statement is "300H" which refers to the start address of the last page within the 1K words Program Memory of the microcontroller. The table pointer low byte register is setup here to have an initial value of "06H". This will ensure that the first data read from the data table will be at the Program Memory address "306H" or 6 locations after the start of the last page. Note that the value for the table pointer is referenced to the specified address pointed by the TBLP register in the present page if the "TABRD [m]" instruction is being used. The high byte of the table data which in this case is equal to zero will be transferred to the TBLH register automatically when the "TABRD [m]" instruction is executed.

Because the TBLH register is a read-only register and cannot be restored, care should be taken to ensure its protection if both the main routine and Interrupt Service Routine use table read instructions. If using the table read instructions, the Interrupt Service Routines may change the value of the TBLH and subsequently cause errors if used again by the main routine. As a rule it is recommended that simultaneous use of the table read instructions should be avoided. However, in situations where simultaneous use cannot be avoided, the interrupts should be disabled prior to the execution of any main routine table-read instructions. Note that all table related instructions require two instruction cycles to complete their operation.

Table Read Program Example

```
tempreg1 db ?      ; temporary register #1
tempreg2 db ?      ; temporary register #2
:
mov a, 06h         ; initialise low table pointer - note that this address
mov tblp, a        ; is referenced to the last page or present page
:
tabrdl tempreg1    ; transfers value in table referenced by table pointer
                   ; data at program memory address "306H" transferred
                   ; to tempreg1 and TBLH
dec tblp           ; reduce value of table pointer by one
tabrdl tempreg2    ; transfers value in table referenced by table pointer
                   ; data at program memory address "305H" transferred to tempreg2 and
                   ; TBLH, in this example the data 1AH is transferred to tempreg1 and
                   ; data "0FH" to register tempreg2
                   ; the value "00H" will be transferred to the high byte register TBLH
:
org 300h           ; sets initial address of program memory
dc 00Ah, 00Bh, 00Ch, 00Dh, 00Eh, 00Fh, 01Ah, 01Bh
:
```

In Circuit Programming – ICP

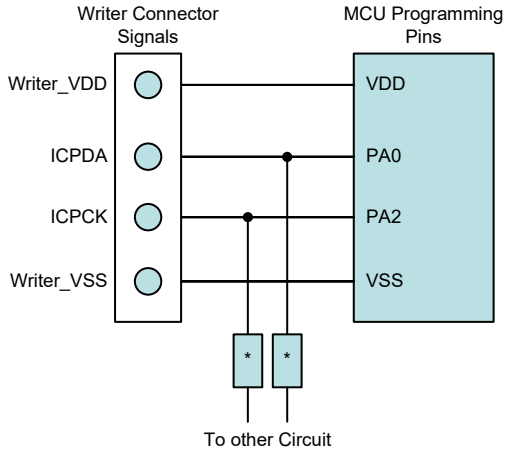
The provision of Flash Type Program Memory provides the user with a means of convenient and easy upgrades and modifications to their programs on the same device. As an additional convenience, Holtek has provided a means of programming the microcontroller in-circuit using a 4-pin interface. This provides manufacturers with the possibility of manufacturing their circuit boards complete with a programmed or un-programmed microcontroller, and then programming or upgrading the program at a later stage. This enables product manufacturers to easily keep their manufactured products supplied with the latest program releases without removal and re-insertion of the device.

The Holtek Flash MCU to Writer Programming Pin correspondence table is as follows:

Holtek Writer Pins	MCU Programming Pins	Pin Description
ICPDA	PA0	Programming Serial Data/Address
ICPCK	PA2	Programming Clock
VDD	VDD	Power Supply
VSS	VSS	Ground

The Program Memory can be programmed serially in-circuit using this 4-wire interface. Data is downloaded and uploaded serially on a single pin with an additional line for the clock. Two additional lines are required for the power supply. The technical details regarding the in-circuit programming of the device are beyond the scope of this document and will be supplied in supplementary literature.

During the programming process, taking control of the ICPDA and ICPCK pins for data and clock programming purposes. The user must there take care to ensure that no other outputs are connected to these two pins.



Note: * may be resistor or capacitor. The resistance of * must be greater than 1kΩ or the capacitance of * must be less than 1nF.

On-Chip Debug Support – OCDS

There is an EV chip named BA45V6720 which is used to emulate the BA45F6720 device. The EV chip device also provides an "On-Chip Debug" function to debug the real MCU device during the development process. The EV chip and the real MCU device are almost functionally compatible except for the "On-Chip Debug" function and the package type. Users can use the EV chip device to emulate the real chip device behavior by connecting the OCDSDA and OCDSCK pins to the Holtek HT-IDE development tools. The OCDSDA pin is the OCDS Data/Address input/output pin while the OCDSCK pin is the OCDS clock input pin. For more detailed OCDS description, refer to the corresponding document named "Holtek e-Link for 8-bit MCU OCDS User's Guide".

Holtek e-Link Pins	EV Chip Pins	Pin Description
OCDSDA	OCDSDA	On-chip Debug Support Data/Address input/output
OCDSCK	OCDSCK	On-chip Debug Support Clock input
VDD	VDD	Power Supply
VSS	VSS	Ground

Data Memory

The Data Memory is a volatile area of 8-bit wide RAM internal memory and is the location where temporary information is stored.

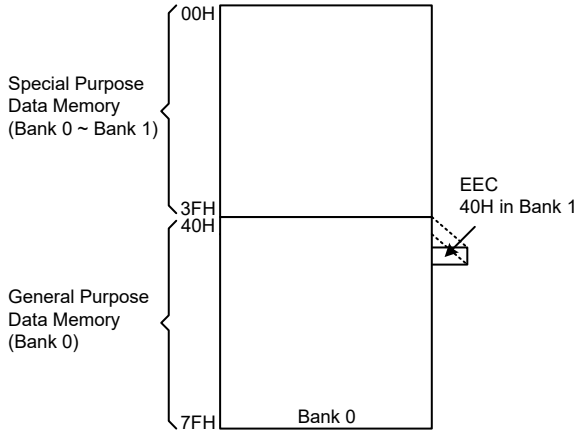
Structure

Categorized into two types, the first of these is an area of RAM, known as the Special Function Data Memory. These registers have fixed locations and are necessary for correct operation of the device. Many of these registers can be read from and written to directly under program control, however, some remain protected from user manipulation. The second area of Data Memory is known as the General Purpose Data Memory, which is reserved for general purpose use. All locations within this area are read and write accessible under program control.

The overall Data Memory is subdivided into two banks, which are Bank 0 and Bank 1 and implemented in 8-bit wide Memory. The special purpose registers are accessible in Bank 0, with the exception of the EEC register at address 40H, which is only accessible in Bank 1. Switching between the different Data Memory banks is achieved by setting the Bank Pointer to the correct value.

Special Purpose Data Memory	General Purpose Data Memory	
Located Banks	Capacity	Bank: Address
Bank 0: 00H~3FH Bank 1: 40H	64×8	Bank 0: 40H~7FH

Data Memory Summary



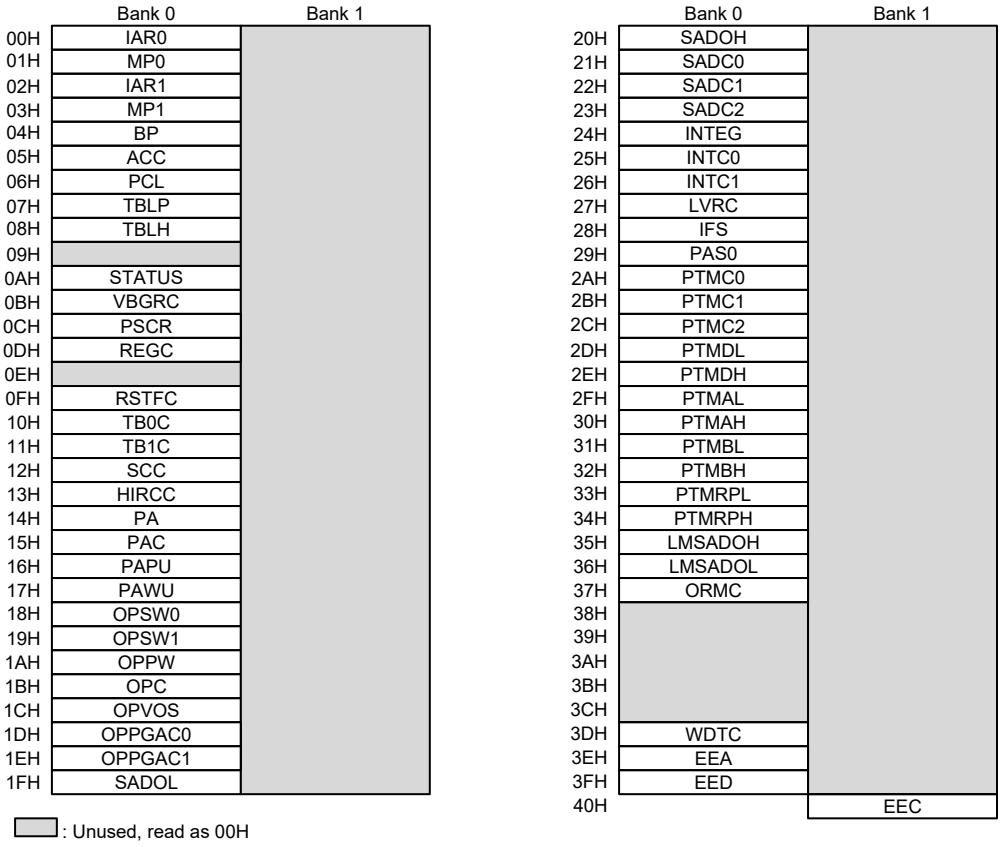
Data Memory Structure

General Purpose Data Memory

All microcontroller programs require an area of read/write memory where temporary data can be stored and retrieved for use later. It is this area of RAM memory that is known as General Purpose Data Memory. This area of Data Memory is fully accessible by the user programing for both reading and writing operations. By using the bit operation instructions individual bits can be set or reset under program control giving the user a large range of flexibility for bit manipulation in the Data Memory.

Special Purpose Data Memory

This area of Data Memory is where registers, necessary for the correct operation of the microcontroller, are stored. Most of the registers are both readable and writeable but some are protected and are readable only, the details of which are located under the relevant Special Function Register section. Note that for locations that are unused, any read instruction to these addresses will return the value “00H”.



Special Purpose Data Memory

Special Function Register Description

Most of the Special Function Register details will be described in the relevant functional sections, however several registers require a separate description in this section.

Indirect Addressing Register – IAR0, IAR1

The Indirect Addressing Registers, IAR0 and IAR1, although having their locations in normal RAM register space, do not actually physically exist as normal registers. The method of indirect addressing for RAM data manipulation uses these Indirect Addressing Registers and Memory Pointers, in contrast to direct memory addressing, where the actual memory address is specified. Actions on the IAR0 and IAR1 registers will result in no actual read or write operation to these registers but rather to the memory location specified by their corresponding Memory Pointers, MP0 or MP1. Acting as a pair, IAR0 and MP0 can together access data from Bank 0 while the IAR1 and MP1 register pair can access data from any bank. As the Indirect Addressing Registers are not physically implemented, reading the Indirect Addressing Registers indirectly will return a result of "00H" and writing to the registers indirectly will result in no operation.

Memory Pointers – MP0, MP1

Two Memory Pointers, known as MP0 and MP1 are provided. These Memory Pointers are physically implemented in the Data Memory and can be manipulated in the same way as normal registers providing a convenient way with which to address and track data. When any operation to

the relevant Indirect Addressing Registers is carried out, the actual address that the microcontroller is directed to is the address specified by the related Memory Pointer. MP0 together with Indirect Addressing Register, IAR0, are used to access data from Bank 0, while MP1 and IAR1 are used to access data from all banks according to the BP register. Direct Addressing can only be used with Bank 0, all other Banks must be addressed indirectly using MP1 and IAR1.

The following example shows how to clear a section of four Data Memory locations already defined as locations adres1 to adres4.

Indirect Addressing Program Example

```
data .section ´data´
adres1 db ?
adres2 db ?
adres3 db ?
adres4 db ?
block  db ?
code .section at 0 ´code´
org 00h
start:
     mov a,04h              ; setup size of block
     mov block,a
     mov a,offset adres1    ; Accumulator loaded with first RAM address
     mov MP0,a              ; setup memory pointer with first RAM address
loop:
     clr IAR0               ; clear the data at address defined by MP0
     inc MP0                ; increment memory pointer
     sdz block              ; check if last memory location has been cleared
     jmp loop
continue:
:
```

The important point to note here is that in the example shown above, no reference is made to specific Data Memory addresses.

Bank Pointer – BP

For this device, the Data Memory is divided into two banks, Bank0 and Bank1. Selecting the required Data Memory area is achieved using the Bank Pointer. Bit 0 of the Bank Pointer is used to select Data Memory Bank 0~1.

The Data Memory is initialised to Bank 0 after a reset, except for a WDT time-out reset in the SLEEP or IDLE Mode, in which case, the Data Memory bank remains unaffected. It should be noted that the Special Function Data Memory is not affected by the bank selection, which means that the Special Function Registers can be accessed from within any bank. Directly addressing the Data Memory will always result in Bank 0 being accessed irrespective of the value of the Bank Pointer. Accessing data from banks other than Bank 0 must be implemented using Indirect Addressing.

- **BP Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	—	DMBP0
R/W	—	—	—	—	—	—	—	R/W
POR	—	—	—	—	—	—	—	0

Bit 7~1 Unimplemented, read as “0”

Bit 0 **DMBP0**: Select Data Memory Banks
0: Bank 0
1: Bank 1

Accumulator – ACC

The Accumulator is central to the operation of any microcontroller and is closely related with operations carried out by the ALU. The Accumulator is the place where all intermediate results from the ALU are stored. Without the Accumulator it would be necessary to write the result of each calculation or logical operation such as addition, subtraction, shift, etc., to the Data Memory resulting in higher programming and timing overheads. Data transfer operations usually involve the temporary storage function of the Accumulator; for example, when transferring data between one user defined register and another, it is necessary to do this by passing the data through the Accumulator as no direct transfer between two registers is permitted.

Program Counter Low Register – PCL

To provide additional program control functions, the low byte of the Program Counter is made accessible to programmers by locating it within the Special Purpose area of the Data Memory. By manipulating this register, direct jumps to other program locations are easily implemented. Loading a value directly into this PCL register will cause a jump to the specified Program Memory location. However, as the register is only 8-bit wide, only jumps within the current Program Memory page are permitted. When such operations are used, note that a dummy cycle will be inserted.

Look-up Table Registers – TBLP, TBLH

These two special function registers are used to control operation of the look-up table which is stored in the Program Memory. TBLP is the table pointer and indicates the location where the table data is located. Its value must be setup before any table read commands are executed. Its value can be changed, for example using the "INC" or "DEC" instructions, allowing for easy table data pointing and reading. TBLH is the location where the high order byte of the table data is stored after a table read data instruction has been executed. Note that the lower order table data byte is transferred to a user defined location.

Option Memory Mapping Register – ORMC

The ORMC register is used to enable Option Memory Mapping function. The Option Memory capacity is 32 words. When a specific pattern of 55H and AAH is consecutively written into this register, the Option Memory Mapping function will be enabled and then the Option Memory code can be read by using the table read instruction. The Option Memory addresses 00H~1FH will be mapped to Program Memory last page addresses E0H~FFH.

To successfully enable the Option Memory Mapping function, the specific pattern of 55H and AAH must be written into the ORMC register in two consecutive instruction cycles. It is therefore recommended that the global interrupt bit EMI should first be cleared before writing the specific pattern, and then set high again at a proper time according to users' requirements after the pattern is successfully written. An internal timer will be activated when the pattern is successfully written. The mapping operation will be automatically finished after a period of $4\times t_{LIRC}$. Therefore, users should read the data in time, otherwise the Option Memory Mapping function needs to be restarted. After the completion of each consecutive write operation to the ORMC register, the timer will recount.

When the table read instructions are used to read the Option Memory code, both "TABRD [m]" and "TABRDL [m]" instructions can be used. However, care must be taken if the "TABRD [m]" instruction is used, the table pointer defined by the TBHP register must be referenced to the last page. Refer to corresponding sections about the table read instruction for more details.

• **ORMC Register**

Bit	7	6	5	4	3	2	1	0
Name	ORMC7	ORMC6	ORMC5	ORMC4	ORMC3	ORMC2	ORMC1	ORMC0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **ORMC7~ORMC0**: Option Memory Mapping specific pattern
When a specific pattern of 55H and AAH is written into this register, the Option Memory Mapping function will be enabled. Note that the register content will be cleared after the MCU is woken up from the IDLE/SLEEP mode.

Status Register – STATUS

This 8-bit register contains the zero flag (Z), carry flag (C), auxiliary carry flag (AC), overflow flag (OV), power down flag (PDF), and watchdog time-out flag (TO). These arithmetic/logical operation and system management flags are used to record the status and operation of the microcontroller.

With the exception of the TO and PDF flags, bits in the status register can be altered by instructions like most other registers. Any data written into the status register will not change the TO or PDF flag. In addition, operations related to the status register may give different results due to the different instruction operations. The TO flag can be affected only by a system power-up, a WDT time-out or by executing the "CLR WDT" or "HALT" instruction. The PDF flag is affected only by executing the "HALT" or "CLR WDT" instruction or during a system power-up.

The Z, OV, AC and C flags generally reflect the status of the latest operations.

- C is set if an operation results in a carry during an addition operation or if a borrow does not take place during a subtraction operation; otherwise C is cleared. C is also affected by a rotate through carry instruction.
- AC is set if an operation results in a carry out of the low nibbles in addition, or no borrow from the high nibble into the low nibble in subtraction; otherwise AC is cleared.
- Z is set if the result of an arithmetic or logical operation is zero; otherwise Z is cleared.
- OV is set if an operation results in a carry into the highest-order bit but not a carry out of the highest-order bit, or vice versa; otherwise OV is cleared.
- PDF is cleared by a system power-up or executing the "CLR WDT" instruction. PDF is set by executing the "HALT" instruction.
- TO is cleared by a system power-up or executing the "CLR WDT" or "HALT" instruction. TO is set by a WDT time-out.

In addition, on entering an interrupt sequence or executing a subroutine call, the status register will not be pushed onto the stack automatically. If the contents of the status registers are important and if the subroutine can corrupt the status register, precautions must be taken to correctly save it.

• **STATUS Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	TO	PDF	OV	Z	AC	C
R/W	—	—	R	R	R/W	R/W	R/W	R/W
POR	—	—	0	0	x	x	x	x

"x": Unknown

Bit 7~6 Unimplemented, read as "0"

Bit 5 **TO**: Watchdog Time-Out flag
0: After power up or executing the "CLR WDT" or "HALT" instruction
1: A watchdog time-out occurred.

Bit 4 **PDF**: Power down flag
0: After power up or executing the "CLR WDT" instruction
1: By executing the "HALT" instruction

Bit 3 **OV**: Overflow flag
0: No overflow
1: An operation results in a carry into the highest-order bit but not a carry out of the highest-order bit or vice versa.

Bit 2 **Z**: Zero flag
0: The result of an arithmetic or logical operation is not zero
1: The result of an arithmetic or logical operation is zero

Bit 1 **AC**: Auxiliary flag
0: No auxiliary carry
1: An operation results in a carry out of the low nibbles in addition, or no borrow from the high nibble into the low nibble in subtraction

Bit 0 **C**: Carry flag
0: No carry-out
1: An operation results in a carry during an addition operation or if a borrow does not take place during a subtraction operation

The C flag is also affected by a rotate through carry instruction.

EEPROM Data Memory

The device contains an area of internal EEPROM Data Memory. EEPROM is by its nature a non-volatile form of re-programmable memory, with data retention even when its power supply is removed. By incorporating this kind of data memory, a whole new host of application possibilities are made available to the designer. The availability of EEPROM storage allows information such as product identification numbers, calibration values, specific user data, system setup data or other product information to be stored directly within the product microcontroller. The process of reading and writing data to the EEPROM memory has been reduced to a very trivial affair.

EEPROM Data Memory Structure

The EEPROM Data Memory capacity is 32×8 bits. Unlike the Program Memory and RAM Data Memory, the EEPROM Data Memory is not directly mapped into memory space and is therefore not directly addressable in the same way as the other types of memory. Read and Write operations to the EEPROM are carried out in single byte operations using an address and a data register in Bank 0 and a single control register in Bank 1.

EEPROM Registers

Three registers control the overall operation of the internal EEPROM Data Memory. These are the address register, EEA, the data register, EED and a single control register, EEC. As both the EEA and EED registers are located in Bank 0, they can be directly accessed in the same way as any other Special Function Register. The EEC register however, being located in only Bank 1, cannot be directly addressed and can only be read from or written to indirectly using the MP1 Memory Pointer and Indirect Addressing Register, IAR1. Because the EEC control register is located at address 40H in Bank 1, the MP1 Memory Pointer must first be set to the value 40H and the Bank Pointer register, BP, set to the value, 01H, before any operations on the EEC register are executed.

Register Name	Bit							
	7	6	5	4	3	2	1	0
EEA	—	—	—	EEA4	EEA3	EEA2	EEA1	EEA0
EED	D7	D6	D5	D4	D3	D2	D1	D0
EEC	D7	—	—	—	WREN	WR	RDEN	RD

EEPROM Register List

- **EEA Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	EEA4	EEA3	EEA2	EEA1	EEA0
R/W	—	—	—	R/W	R/W	R/W	R/W	R/W
POR	—	—	—	0	0	0	0	0

Bit 7~5 Unimplemented, read as "0"

Bit 4~0 **EEA4~EEA0**: Data EEPROM address bit 4 ~ bit 0

- **EED Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: Data EEPROM data bit 7 ~ bit 0

- **EEC Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	—	—	—	WREN	WR	RDEN	RD
R/W	R/W	—	—	—	R/W	R/W	R/W	R/W
POR	0	—	—	—	0	0	0	0

Bit 7 **D7**: Reserved, must be fixed at "0"

Bit 6~4 Unimplemented, read as "0"

Bit 3 **WREN**: Data EEPROM Write Enable
0: Disable
1: Enable
This is the Data EEPROM Write Enable Bit which must be set high before Data EEPROM write operations are carried out. Clearing this bit to zero will inhibit Data EEPROM write operations.

Bit 2 **WR**: EEPROM Write Control
0: Write cycle has finished
1: Activate a write cycle
This is the Data EEPROM Write Control Bit and when set high by the application program will activate a write cycle. This bit will be automatically reset to zero by hardware after the write cycle has finished. Setting this bit high will have no effect if the WREN has not first been set high.

Bit 1 **RDEN**: Data EEPROM Read Enable
0: Disable
1: Enable
This is the Data EEPROM Read Enable Bit which must be set high before Data EEPROM read operations are carried out. Clearing this bit to zero will inhibit Data EEPROM read operations.

Bit 0 **RD**: EEPROM Read Control
0: Read cycle has finished
1: Activate a read cycle
This is the Data EEPROM Read Control Bit and when set high by the application program will activate a read cycle. This bit will be automatically reset to zero by hardware after the read cycle has finished. Setting this bit high will have no effect if the RDEN has not first been set high.

Note: 1. The WREN, WR, RDEN and RD cannot be set high at the same time in one instruction. The WR and RD cannot be set high at the same time.
2. Ensure that the f_{SUB} clock is stable before executing the write operation.
3. Ensure that the write operation is totally complete before changing the EEC register content.

Reading Data from the EEPROM

To read data from the EEPROM, the EEPROM address of the data to be read must first be placed in the EEA register. Then the read enable bit, RDEN, in the EEC register must be set high to enable the read function. If the RD bit in the EEC register is now set high, a read cycle will be initiated. Setting the RD bit high will not initiate a read operation if the RDEN bit has not been set. When the read cycle terminates, the RD bit will be automatically cleared to zero, after which the data can be read from the EED register. The data will remain in the EED register until another read or write operation is executed. The application program can poll the RD bit to determine when the data is valid for reading.

Writing Data to the EEPROM

To write data to the EEPROM, the EEPROM address of the data to be written must first be placed in the EEA register and the data placed in the EED register. Then the write enable bit, WREN, in the EEC register must be set high to enable the write function. After this, the WR bit in the EEC register must be immediately set high to initiate a write cycle successfully. These two instructions must be executed in two consecutive instruction cycles. The global interrupt bit EMI should also first be cleared before implementing any write operations, and then set high again after the write cycle has started. Note that setting the WR bit high will not initiate a write cycle if the WREN bit has not been set. As the EEPROM write cycle is controlled using an internal timer whose operation is asynchronous to microcontroller system clock, a certain time will elapse before the data will have been written into the EEPROM. Detecting when the write cycle has finished can be implemented either by polling the WR bit in the EEC register or by using the EEPROM interrupt. When the write cycle terminates, the WR bit will be automatically cleared to zero by the microcontroller, informing the user that the data has been written to the EEPROM. The application program can therefore poll the WR bit to determine when the write cycle has ended.

Write Protection

Protection against inadvertent write operation is provided in several ways. After the device is powered-on the Write Enable bit in the control register will be cleared preventing any write operations. Also at power-on the Bank Pointer, BP, will be reset to zero, which means that Data Memory Bank 0 will be selected. As the EEPROM control register is located in Bank 1, this adds a further measure of protection against spurious write operations. During normal program operation, ensuring that the Write Enable bit in the control register is cleared will safeguard against incorrect write operations.

EEPROM Interrupt

The EEPROM write interrupt is generated when an EEPROM write cycle has ended. The EEPROM interrupt must first be enabled by setting the DEE bit in the relevant interrupt register. When an EEPROM write cycle ends, the DEF request flag will be set. If the global, EEPROM interrupts are enabled and the stack is not full, a jump to the associated EEPROM Interrupt vector will take place. When the interrupt is serviced, the EEPROM Interrupt flag, DEF, will be automatically cleared. The EMI bit will also be automatically cleared to disable other interrupts. More details can be obtained in the Interrupt section.

Programming Considerations

Care must be taken that data is not inadvertently written to the EEPROM. Protection can be enhanced by ensuring that the Write Enable bit is normally cleared to zero when not writing. Also the Bank Pointer could be normally cleared to zero as this would inhibit access to Bank 1 where the EEPROM control register exists. Although certainly not necessary, consideration might be given in the application program to the checking of the validity of new write data by a simple read back process.

When writing data, the WR bit must be set high immediately after the WREN bit has been set high, to ensure the write cycle executes correctly. The global interrupt bit EMI should also be cleared before a write cycle is executed and then re-enabled after the write cycle starts. Note that the device should not enter the IDLE or SLEEP mode until the EEPROM read or write operation is totally complete. Otherwise, the EEPROM read or write operation will fail.

Programming Examples

Reading data from the EEPROM – polling method

```
MOV A, EEPROM_ADRES   ; user defined address
MOV EEA, A
MOV A, 040H           ; setup memory pointer MP1
MOV MP1, A            ; MP1 points to EEC register
MOV A, 01H            ; setup Bank Pointer
MOV BP, A
SET IAR1.1            ; set RDEN bit, enable read operations
SET IAR1.0            ; start Read Cycle - set RD bit
BACK:
SZ  IAR1.0            ; check for read cycle end
JMP BACK
CLR IAR1              ; disable EEPROM read if no more read operations are required
CLR BP
MOV A, EED            ; move read data to register
MOV READ_DATA, A
```

Note: For each read operation, the address register should be re-specified followed by setting the RD bit high to activate a read cycle even if the target address is consecutive.

Writing Data to the EEPROM – polling method

```
MOV A, EEPROM_ADRES   ; user defined address
MOV EEA, A
MOV A, EEPROM_DATA    ; user defined data
MOV EED, A
MOV A, 040H           ; setup memory pointer MP1
MOV MP1, A            ; MP1 points to EEC register
MOV A, 01H            ; setup Bank Pointer
MOV BP, A
CLR EMI
```

```
SET IAR1.3            ; set WREN bit, enable write operations
SET IAR1.2            ; start Write Cycle - set WR bit - executed immediately
                      ; after set WREN bit
SET EMI
BACK:
SZ  IAR1.2            ; check for write cycle end
JMP BACK
CLR BP
```

Oscillators

Various oscillator options offer the user a wide range of functions according to their various application requirements. The flexible features of the oscillator functions ensure that the best optimisation can be achieved in terms of speed and power saving. Oscillator selections and operation are selected through the application program by using relevant control registers.

Oscillator Overview

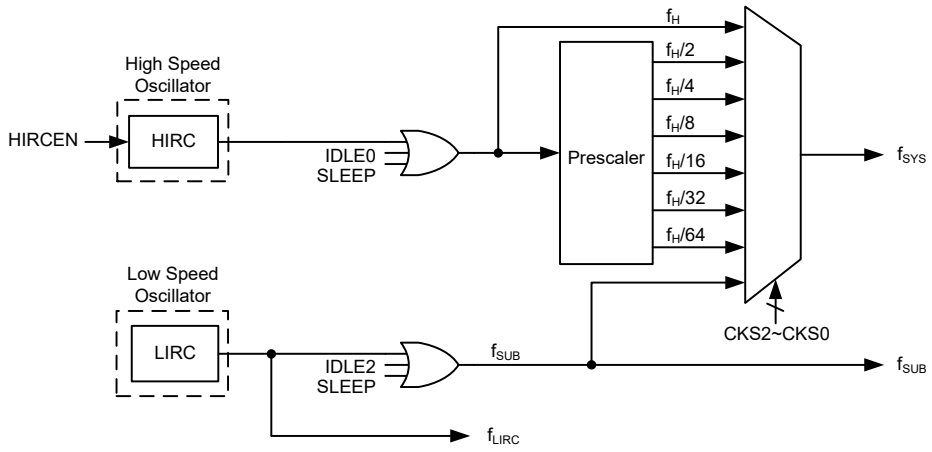
In addition to being the source of the main system clock the oscillators also provide clock sources for the Watchdog Timer. Fully integrated internal oscillators, requiring no external components, are provided to form a wide range of both fast and slow system oscillators. The higher frequency oscillator provides higher performance but carry with it the disadvantage of higher power requirements, while the opposite is of course true for the lower frequency oscillator. With the capability of dynamically switching between fast and slow system clock, the device has the flexibility to optimize the performance/power ratio, a feature especially important in power sensitive portable applications.

Type	Name	Frequency
Internal High Speed RC	HIRC	8MHz
Internal Low Speed RC	LIRC	32kHz

Oscillator Types

System Clock Configurations

There are two methods of generating the system clock, one high speed oscillator and one low speed oscillator. The high speed oscillator is the internal 8MHz RC oscillator, HIRC. The low speed oscillator is the internal 32kHz RC oscillator, LIRC. Selecting whether the low or high speed oscillator is used as the system oscillator is implemented using the CKS2~CKS0 bits in the SCC register and as the system clock can be dynamically selected.



System Clock Configurations

Internal RC Oscillator – HIRC

The internal RC oscillator is a fully integrated system oscillator requiring no external components. The internal RC oscillator has a fixed frequency of 8MHz. Device trimming during the manufacturing process and the inclusion of internal frequency compensation circuits are used to ensure that the influence of the power supply voltage, temperature and process variations on the oscillation frequency are minimised.

Internal 32kHz Oscillator – LIRC

The Internal 32kHz System Oscillator is the low frequency oscillator. It is a fully integrated RC oscillator with a typical frequency of 32kHz, requiring no external components for its implementation. Device trimming during the manufacturing process and the inclusion of internal frequency compensation circuits are used to ensure that the influence of the power supply voltage, temperature and process variations on the oscillation frequency are minimised.

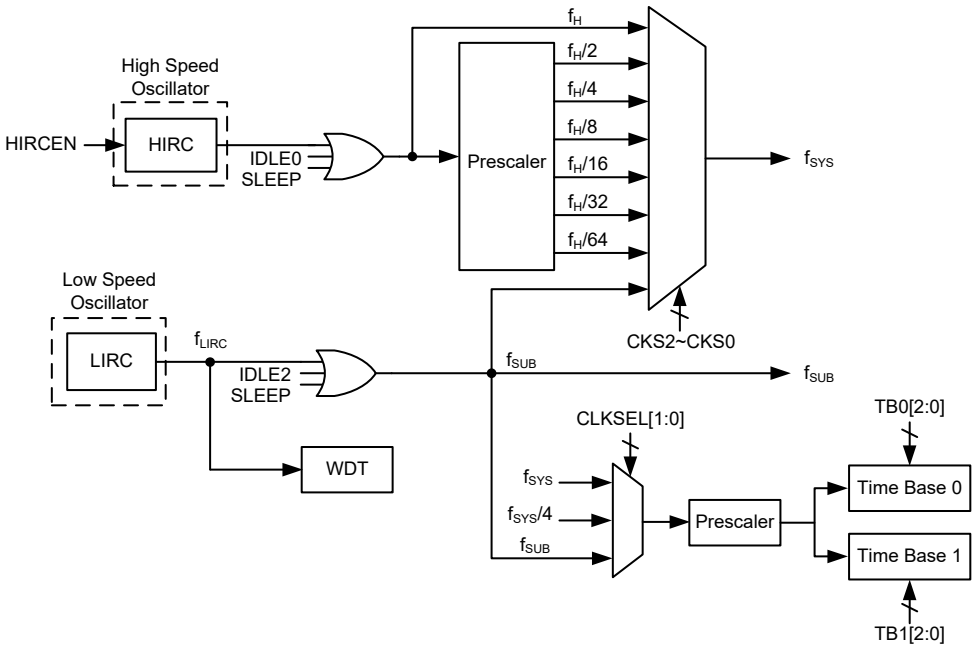
Operating Modes and System Clocks

Present day applications require that their microcontrollers have high performance but often still demand that they consume as little power as possible, conflicting requirements that are especially true in battery powered portable applications. The fast clocks required for high performance will by their nature increase current consumption and of course vice versa, lower speed clocks reduce current consumption. As both high and low speed clock sources are provided the means to switch between them dynamically, the user can optimise the operation of their microcontroller to achieve the best performance/power ratio.

System Clocks

The device has different clock sources for both the CPU and peripheral function operation. By providing the user with a wide range of clock selections using register programming, a clock system can be configured to obtain maximum application performance.

The main system clock, can come from either a high frequency, f_H, or low frequency, f_{SUB}, source, and is selected using the CKS2~CKS0 bits in the SCC register. The high speed system clock is sourced from the HIRC oscillator. The low speed system clock source is sourced from the LIRC oscillator. The other choice, which is a divided version of the high speed system oscillator has a range of $f_H/2$~$f_H/64$.



Device Clock Configurations

Note: When the system clock source f_{SYS} is switched to f_{SUB} from f_H, the high speed oscillator can be stopped to conserve the power or continue to oscillate to provide the clock source, f_H~$f_H/64$, for peripheral circuit to use.

System Operation Modes

There are six different modes of operation for the microcontroller, each one with its own special characteristics and which can be chosen according to the specific performance and power requirements of the application. There are two modes allowing normal operation of the microcontroller, the FAST Mode and SLOW Mode. The remaining four modes, the SLEEP, IDLE0, IDLE1 and IDLE2 Mode are used when the microcontroller CPU is switched off to conserve power.

Operation Mode	CPU	Register Setting			f_{SYS}	f_H	f_{SUB}	f_{LIRC}
		FHIDEN	FSIDEN	CKS2~CKS0				
FAST	On	x	x	000~110	f_H~$f_H/64$	On	On	On
SLOW	On	x	x	111	f_{SUB}	On/Off (1)	On	On
IDLE0	Off	0	1	000~110	Off	Off	On	On
				111	On			
IDLE1	Off	1	1	xxx	On	On	On	On
IDLE2	Off	1	0	000~110	On	On	Off	On
				111	Off			
SLEEP	Off	0	0	xxx	Off	Off	Off	On/Off (2)

"x": Don't care

Note: 1. The f_H clock will be switched on or off by configuring the corresponding oscillator enable bit in the SLOW mode.
2. The f_{LIRC} clock will be switched on or off which is controlled by the WDT function being enabled or disabled in the SLEEP mode.

FAST Mode

This is one of the main operating modes where the microcontroller has all of its functions operational and where the system clock is provided by the high speed oscillator. This mode operates allowing the microcontroller to operate normally with a clock source will come from the HIRC oscillator. The high speed oscillator will however first be divided by a ratio ranging from 1 to 64, the actual ratio being selected by the CKS2~CKS0 bits in the SCC register. Although a high speed oscillator is used, running the microcontroller at a divided clock ratio reduces the operating current.

SLOW Mode

This is also a mode where the microcontroller operates normally although now with a slower speed clock source. The clock source used will be from f_{SUB}. The f_{SUB} clock is derived from the LIRC oscillator.

SLEEP Mode

The SLEEP Mode is entered when a HALT instruction is executed and when the FHIDEN and FSIDEN bit are low. In the SLEEP mode the CPU will be stopped, and the f_{SUB} clock to peripheral will be stopped too. However the f_{LIRC} clock can continues to operate if the WDT function is enabled. The f_{LIRC} clock will be stopped too, if the Watchdog Timer function is disabled.

IDLE0 Mode

The IDLE0 Mode is entered when a HALT instruction is executed and when the FHIDEN bit in the SCC register is low and the FSIDEN bit in the SCC register is high. In the IDLE0 Mode the CPU will be switched off but the low speed oscillator will be turned on to drive some peripheral functions.

IDLE1 Mode

The IDLE1 Mode is entered when a HALT instruction is executed and when the FHIDEN bit in the SCC register is high and the FSIDEN bit in the SCC register is high. In the IDLE1 Mode the CPU will be switched off but both the high and low speed oscillators will be turned on to provide a clock source to keep some peripheral functions operational.

IDLE2 Mode

The IDLE2 Mode is entered when an HALT instruction is executed and when the FHIDEN bit in the SCC register is high and the FSIDEN bit in the SCC register is low. In the IDLE2 Mode the CPU will be switched off but the high speed oscillator will be turned on to provide a clock source to keep some peripheral functions operational.

Control Registers

The registers, SCC and HIRCC, are used to control the system clock and the corresponding oscillator configurations.

Register Name	Bit							
	7	6	5	4	3	2	1	0
SCC	CKS2	CKS1	CKS0	—	—	—	FHIDEN	FSIDEN
HIRCC	—	—	—	—	—	—	HIRCF	HIRCEN

System Operating Mode Control Register List

• **SCC Register**

Bit	7	6	5	4	3	2	1	0
Name	CKS2	CKS1	CKS0	—	—	—	FHIDEN	FSIDEN
R/W	R/W	R/W	R/W	—	—	—	R/W	R/W
POR	0	0	0	—	—	—	0	0

Bit 7~5 **CKS2~CKS0**: System clock selection
000: f_H
001: $f_H/2$
010: $f_H/4$
011: $f_H/8$
100: $f_H/16$
101: $f_H/32$
110: $f_H/64$
111: f_{SUB}
These three bits are used to select which clock is used as the system clock source. In addition to the system clock source directly derived from f_H or f_{SUB}, a divided version of the high speed system oscillator can also be chosen as the system clock source.

Bit 4~2 Unimplemented, read as "0"

Bit 1 **FHIDEN**: High Frequency oscillator control when CPU is switched off
0: Disable
1: Enable
This bit is used to control whether the high speed oscillator is activated or stopped when the CPU is switched off by executing an "HALT" instruction.

Bit 0 **FSIDEN**: Low Frequency oscillator control when CPU is switched off
0: Disable
1: Enable
This bit is used to control whether the low speed oscillator is activated or stopped when the CPU is switched off by executing an "HALT" instruction.

• **HIRCC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	HIRCF	HIRCEN
R/W	—	—	—	—	—	—	R	R/W
POR	—	—	—	—	—	—	0	1

Bit 7~2 Unimplemented, read as "0"

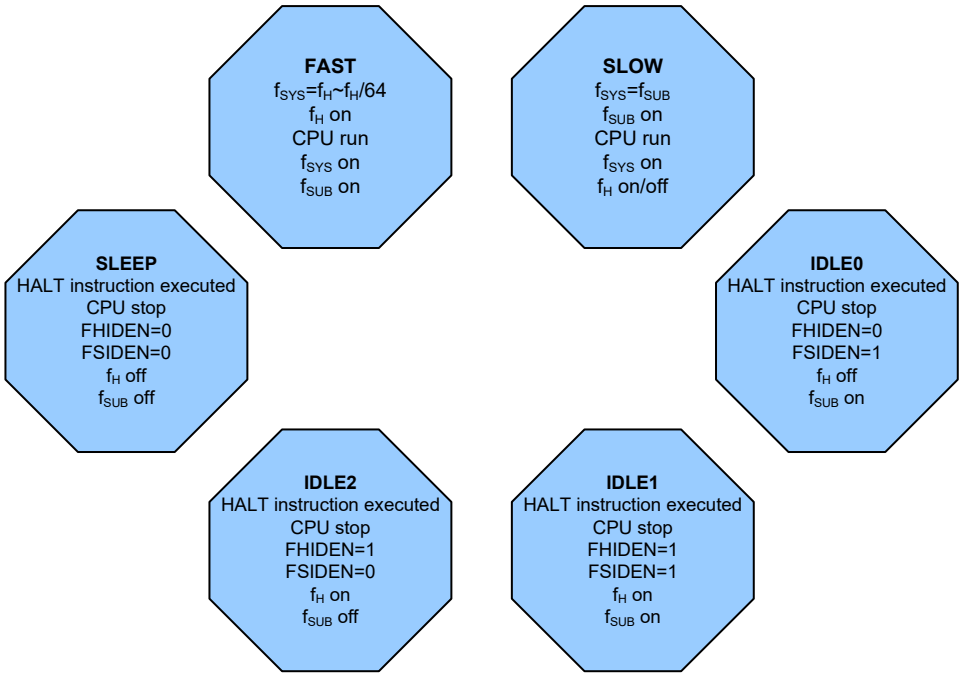
Bit 1 **HIRCF**: HIRC oscillator stable flag
0: HIRC unstable
1: HIRC stable
This bit is used to indicate whether the HIRC oscillator is stable or not. When the HIRCEN bit is set to 1 to enable the HIRC oscillator or the HIRC frequency selection is changed by application program, the HIRCF bit will first be cleared to 0 and then set to 1 after the HIRC oscillator is stable.

Bit 0 **HIRCEN**: HIRC oscillator enable control
0: Disable
1: Enable

Operating Mode Switching

The device can switch between operating modes dynamically allowing the user to select the best performance/power ratio for the present task in hand. In this way microcontroller operations that do not require high performance can be executed using slower clocks thus requiring less operating current and prolonging battery life in portable applications.

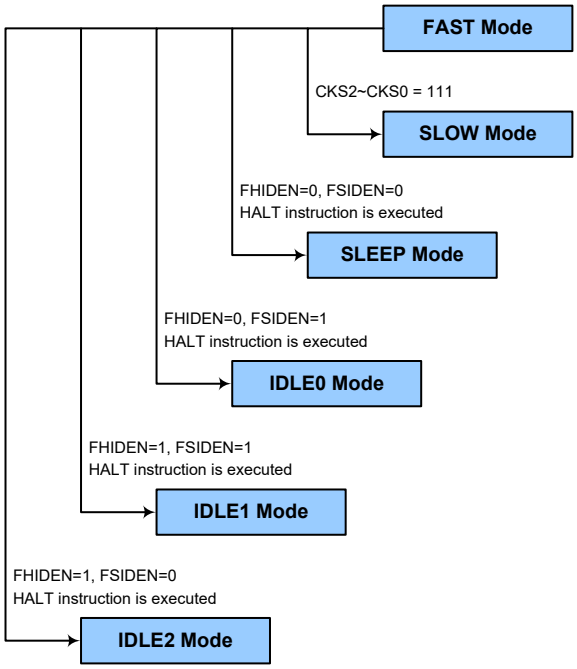
In simple terms, Mode Switching between the FAST Mode and SLOW Mode is executed using the CKS2~CKS0 bits in the SCC register while Mode Switching from the FAST/SLOW Modes to the SLEEP/IDLE Modes is executed via the HALT instruction. When an HALT instruction is executed, whether the device enters the IDLE Mode or the SLEEP Mode is determined by the condition of the FHIDEN and FSIDEN bits in the SCC register.



FAST Mode to SLOW Mode Switching

When running in the FAST Mode, which uses the high speed system oscillator, and therefore consumes more power, the system clock can switch to run in the SLOW Mode by set the CKS2~CKS0 bits to "111" in the SCC register. This will then use the low speed system oscillator which will consume less power. Users may decide to do this for certain operations which do not require high performance and can subsequently reduce power consumption.

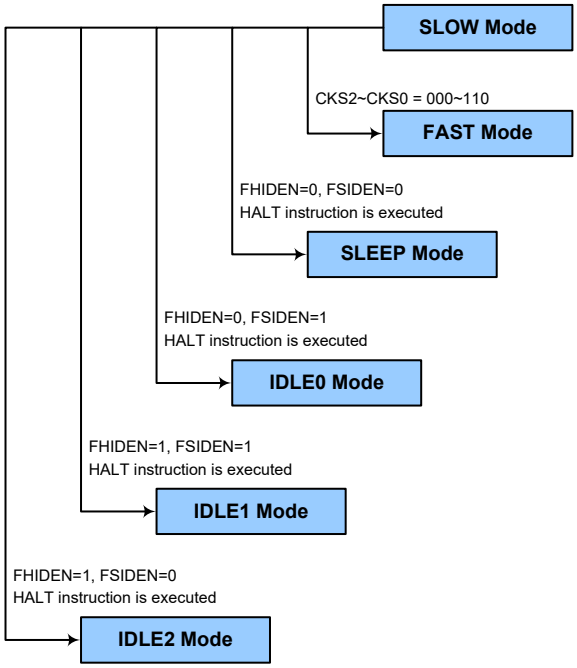
The SLOW Mode is sourced from the LIRC oscillator and therefore requires the oscillator to be stable before full mode switching occurs.



SLOW Mode to FAST Mode Switching

In SLOW mode the system clock is derived from f_{SUB}. When system clock is switched back to the FAST mode from f_{SUB}, the CKS2~CKS0 bits should be set to "000"~"110" and then the system clock will respectively be switched to f_H~f_H/64.

However, if f_H is not used in SLOW mode and thus switched off, it will take some time to re-oscillate and stabilise when switching to the FAST mode from the SLOW Mode. This is monitored using the HIRCF bit in the HIRCC register. The time duration required for the high speed system oscillator stabilization is specified in the relevant characteristics.



Entering the SLEEP Mode

There is only one way for the device to enter the SLEEP Mode and that is to execute the "HALT" instruction in the application program with both the FHIDEN and FSIDEN bits in the SCC register equal to "0". In this mode all the clocks and functions will be switched off except the WDT function. When this instruction is executed under the conditions described above, the following will occur:

- The system clock will be stopped and the application program will stop at the "HALT" instruction.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag PDF will be set, and WDT timeout flag TO will be cleared.
- The WDT will be cleared and resume counting if the WDT function is enabled. If the WDT function is disabled, the WDT will be cleared and then stopped.

Entering the IDLE0 Mode

There is only one way for the device to enter the IDLE0 Mode and that is to execute the "HALT" instruction in the application program with the FHIDEN bit in the SCC register equal to "0" and the FSIDEN bit in the SCC register equal to "1". When this instruction is executed under the conditions described above, the following will occur:

- The f_H clock will be stopped and the application program will stop at the "HALT" instruction, but the f_{SUB} clock will be on.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag PDF will be set, and WDT timeout flag TO will be cleared.
- The WDT will be cleared and resume counting if the WDT function is enabled. If the WDT function is disabled, the WDT will be cleared and then stopped.

Entering the IDLE1 Mode

There is only one way for the device to enter the IDLE1 Mode and that is to execute the "HALT" instruction in the application program with both the FHIDEN and FSIDEN bits in the SCC register equal to "1". When this instruction is executed under the conditions described above, the following will occur:

- The f_H and f_{SUB} clocks will be on but the application program will stop at the "HALT" instruction.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag PDF will be set, and WDT timeout flag TO will be cleared.
- The WDT will be cleared and resume counting if the WDT function is enabled. If the WDT function is disabled, the WDT will be cleared and then stopped.

Entering the IDLE2 Mode

There is only one way for the device to enter the IDLE2 Mode and that is to execute the "HALT" instruction in the application program with the FHIDEN bit in the SCC register equal to "1" and the FSIDEN bit in the SCC register equal to "0". When this instruction is executed under the conditions described above, the following will occur:

- The f_H clock will be on but the f_{SUB} clock will be off and the application program will stop at the "HALT" instruction.
- The Data Memory contents and registers will maintain their present condition.
- The I/O ports will maintain their present conditions.
- In the status register, the Power Down flag PDF will be set, and WDT timeout flag TO will be cleared.
- The WDT will be cleared and resume counting if the WDT function is enabled. If the WDT function is disabled, the WDT will be cleared and then stopped.

Standby Current Considerations

As the main reason for entering the SLEEP or IDLE Mode is to keep the current consumption of the device to as low a value as possible, perhaps only in the order of several micro-amps except in the IDLE1 and IDLE2 Mode, there are other considerations which must also be taken into account by the circuit designer if the power consumption is to be minimised. Special attention must be made to the I/O pins on the device. All high-impedance input pins must be connected to either a fixed high or low level as any floating input pins could create internal oscillations and result in increased current consumption. This also applies to devices which have different package types, as there may be unbonded pins. These pins must either be setup as outputs or if setup as inputs must have pull-high resistors connected.

Care must also be taken with the loads, which are connected to I/O pins, which are setup as outputs. These should be placed in a condition in which minimum current is drawn or connected only to external circuits that do not draw current, such as other CMOS inputs.

In the IDLE1 and IDLE2 Mode the high speed oscillator is on, if the peripheral function clock source is derived from the high speed oscillator, the additional standby current will also be perhaps in the order of several hundred micro-amps.

Wake-up

To minimise power consumption the device can enter the SLEEP or any IDLE Mode, where the CPU will be switched off. However, when the device is woken up again, it will take a considerable time for the original system oscillator to restart, stablise and allow normal operation to resume.

After the system enters the SLEEP or IDLE Mode, it can be woken up from one of various sources listed as follows:

- An external falling edge on Port A
- A system interrupt
- A WDT overflow

When the device executes the "HALT" instruction, the PDF flag will be set to 1. The PDF flag will be cleared to 0 if the device experiences a system power-up or executes the clear Watchdog Timer instruction. If the system is woken up by a WDT overflow, a Watchdog Timer reset will be initiated and the TO flag will be set to 1. The TO flag is set if a WDT time-out occurs and causes a wake-up that only resets the Program Counter and Stack Pointer, other flags remain in their original status.

Each pin on Port A can be setup using the PAWU register to permit a negative transition on the pin to wake up the system. When a Port A pin wake-up occurs, the program will resume execution at the instruction following the "HALT" instruction. If the system is woken up by an interrupt, then two possible situations may occur. The first is where the related interrupt is disabled or the interrupt is enabled but the stack is full, in which case the program will resume execution at the instruction following the "HALT" instruction. In this situation, the interrupt which woke up the device will not

be immediately serviced, but will rather be serviced later when the related interrupt is finally enabled or when a stack level becomes free. The other situation is where the related interrupt is enabled and the stack is not full, in which case the regular interrupt response takes place. If an interrupt request flag is set high before entering the SLEEP or IDLE Mode, the wake-up function of the related interrupt will be disabled.

Watchdog Timer

The Watchdog Timer is provided to prevent program malfunctions or sequences from jumping to unknown locations, due to certain uncontrollable external events such as electrical noise.

Watchdog Timer Clock Source

The Watchdog Timer clock source is provided by the internal clock, f_{LIRC}, which is sourced from the LIRC oscillator. The LIRC internal oscillator has an approximate period of 32kHz and this specified internal clock period can vary with V_{DD}, temperature and process variations. The Watchdog Timer source clock is then subdivided by a ratio of 2^8 to 2^{18} to give longer timeouts, the actual value being chosen using the WS2~WS0 bits in the WDTC register.

Watchdog Timer Control Register

A single register, WDTC, controls the required timeout period as well as the enable/disable and reset MCU operation.

- **WDTC Register**

Bit	7	6	5	4	3	2	1	0
Name	WE4	WE3	WE2	WE1	WE0	WS2	WS1	WS0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	1	0	1	0	0	1	1

Bit 7~3 **WE4~WE0**: WDT function software control
10101: Disable
01010: Enable
Other: Reset MCU
When these bits are changed by the environmental noise or software setting to reset the microcontroller, the reset operation will be activated after a delay time, t_{SRESET}, and the WRF bit in the RSTFC register will be set to 1.

Bit 2~0 **WS2~WS0**: WDT time-out period selection
000: $2^8/f_{LIRC}$
001: $2^{10}/f_{LIRC}$
010: $2^{12}/f_{LIRC}$
011: $2^{14}/f_{LIRC}$
100: $2^{15}/f_{LIRC}$
101: $2^{16}/f_{LIRC}$
110: $2^{17}/f_{LIRC}$
111: $2^{18}/f_{LIRC}$

• **RSTFC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	LVRF	LRF	WRF
R/W	—	—	—	—	—	R/W	R/W	R/W
POR	—	—	—	—	—	x	0	0

"x": unknown

Bit 7~3 Unimplemented, read as "0"

Bit 2 **LVRF**: LVR function reset flag
Described elsewhere.

Bit 1 **LRF**: LVR control register software reset flag
Described elsewhere.

Bit 0 **WRF**: WDT control register software reset flag
0: Not occurred
1: Occurred
This bit is set to 1 by the WDT control register software reset and cleared to 0 by the application program. Note that this bit can only be cleared to 0 by the application program.

Watchdog Timer Operation

The Watchdog Timer operates by providing a device reset when its timer overflows. This means that in the application program and during normal operation the user has to strategically clear the Watchdog Timer before it overflows to prevent the Watchdog Timer from executing a reset. This is done using the clear watchdog instruction. If the program malfunctions for whatever reason, jumps to an unknown location, or enters an endless loop, the clear instruction will not be executed in the correct manner, in which case the Watchdog Timer will overflow and reset the device. There are five bits, WE4~WE0, in the WDTC register to offer additional enable/disable and reset control of the Watchdog Timer. The WDT function will be disabled when the WE4~WE0 bits are set to a value of 10101B while the WDT function will be enabled if the WE4~WE0 bits are equal to 01010B. However, if the WE4~WE0 bits are changed to any other values except 01010B and 10101B, which could be caused by adverse environmental conditions such as noise, it will reset the device after a delay time, t_{SRESET}. After power on these bits will have a value of 01010B.

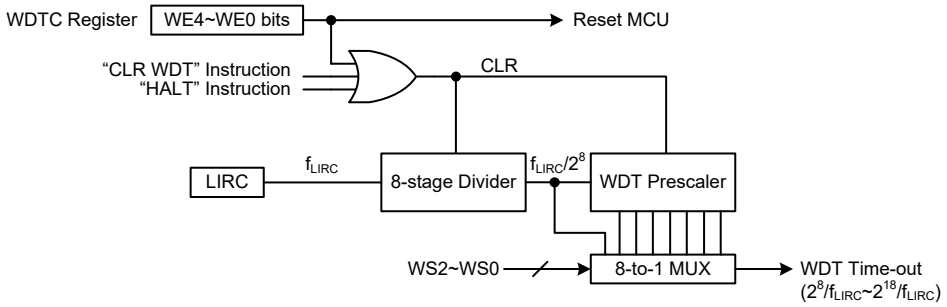
WE4~WE0 Bits	WDT Function
10101B	Disable
01010B	Enable
Any other value	Reset MCU

Watchdog Timer Function Control

Under normal program operation, a Watchdog Timer time-out will initialise a device reset and set the status bit TO. However, if the system is in the SLEEP or IDLE Mode, when a Watchdog Timer time-out occurs, the TO and PDF bits in the status register will be set and only the Program Counter and Stack Pointer will be reset. Three methods can be adopted to clear the contents of the Watchdog Timer. The first is a WDT software reset, which means a certain value except 01010B and 10101B written into the WE4~WE0 bit filed, the second is using the Watchdog Timer software clear instruction and the third is via a HALT instruction.

There is only one method of using software instruction to clear the Watchdog Timer. That is to use the single "CLR WDT" instruction to clear the WDT.

The maximum time out period is when the 2^{18} division ratio is selected. As an example, with a 32kHz LIRC oscillator as its source clock, this will give a maximum watchdog period of around 8 seconds for the 2^{18} division ratio, and a minimum timeout of 8ms for the 2^{8} division ratio.



Watchdog Timer

Reset and Initialisation

A reset function is a fundamental part of any microcontroller ensuring that the device can be set to some predetermined condition irrespective of outside parameters. The most important reset condition is after power is first applied to the microcontroller. In this case, internal circuitry will ensure that the microcontroller, after a short delay, will be in a well-defined state and ready to execute the first program instruction. After this power-on reset, certain important internal registers will be set to defined states before the program commences. One of these registers is the Program Counter, which will be reset to zero forcing the microcontroller to begin program execution from the lowest Program Memory address.

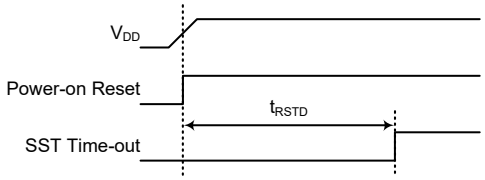
In addition to the power-on reset, another reset exists in the form of a Low Voltage Reset, LVR, where a full reset is implemented in situations where the power supply voltage falls below a certain threshold. Another type of reset is when the Watchdog Timer overflows and resets the microcontroller. All types of reset operations result in different register conditions being setup.

Reset Functions

There are several ways in which a reset can occur, each of which will be described as follows.

Power-on Reset

The most fundamental and unavoidable reset is the one that occurs after power is first applied to the microcontroller. As well as ensuring that the Program Memory begins execution from the first memory address, a power-on reset also ensures that certain other registers are preset to known conditions. All the I/O port and port control registers will power up in a high condition ensuring that all I/O ports will be first set to inputs.

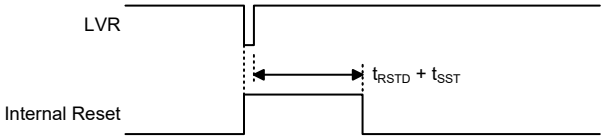


Power-On Reset Timing Chart

Low Voltage Reset – LVR

The microcontroller contains a low voltage reset circuit in order to monitor the supply voltage of the device and provides an MCU reset should the value fall below a certain predefined level. The LVR function can be enabled or disabled by the LVRC control register. If the LVRC control register is configured to enable the LVR function, the LVR function will be always enabled with a specific

LVR voltage V_{LVR} in the FAST or SLOW mode. If the supply voltage of the device drops to within a range of 0.9V~V_{LVR} such as might occur when changing the battery, the LVR will automatically reset the device internally and the LVRF bit in the RSTFC register will also be set to 1. For a valid LVR signal, a low supply voltage, i.e., a voltage in the range between 0.9V~V_{LVR} must exist for a time greater than that specified by t_{LVR} in the LVR Electrical Characteristics. If the low supply voltage state does not exceed this value, the LVR will ignore the low supply voltage and will not perform a reset function. The actual V_{LVR} value is fixed at 2.1V by the LVS7~LVS0 bits in the LVRC register. If the LVS7~LVS0 bits are changed to some different values, other than 01011010B and 10100101B, which may perhaps occur due to adverse environmental conditions such as noise, the LVR will reset the device after a delay time, t_{SRESET}. When this happens, the LRF bit in the RSTFC register will be set to 1. After power on the register will have the value of 01011010B. Note that the LVR function will be automatically disabled when the device enters the SLEEP or IDLE mode.



Low Voltage Reset Timing Chart

- **LVRC Register**

Bit	7	6	5	4	3	2	1	0
Name	LVS7	LVS6	LVS5	LVS4	LVS3	LVS2	LVS1	LVS0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	1	0	1	1	0	1	0

Bit 7~0 **LVS7~LVS0**: LVR voltage select
01011010: 2.1V
10100101: LVR disable
Other values: Generates a MCU reset – register is reset to POR value
When an actual low voltage condition occurs, as specified by the defined LVR voltage value above, an MCU reset will generated. The reset operation will be activated after the low voltage condition keeps more than a t_{LVR} time. In this situation the register contents will remain the same after such a reset occurs.
Any register value, other than 01011010B and 10100101B, will also result in the generation of an MCU reset. The reset operation will be activated after a delay time, t_{SRESET}. However in this situation the register contents will be reset to the POR value.

- **RSTFC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	LVRF	LRF	WRF
R/W	—	—	—	—	—	R/W	R/W	R/W
POR	—	—	—	—	—	x	0	0

"x": unknown

Bit 7~3 Unimplemented, read as "0"

Bit 2 **LVRF**: LVR function reset flag
0: Not occurred
1: Occurred
This bit is set to 1 when a specific low voltage reset condition occurs. Note that this bit can only be cleared to 0 by the application program.

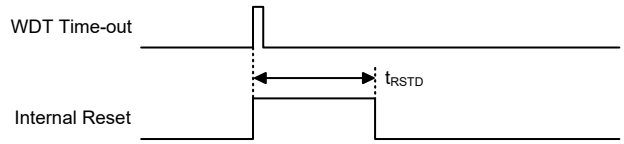
Bit 1 **LRF**: LVR control register software reset flag
0: Not occurred
1: Occurred

This bit is set to 1 by the LVRC control register contains any undefined LVR voltage register values. This in effect acts like a software-reset function. Note that this bit can only be cleared to 0 by the application program.

Bit 0 **WRF**: WDT control register software reset flag
Described elsewhere.

Watchdog Time-out Reset during Normal Operation

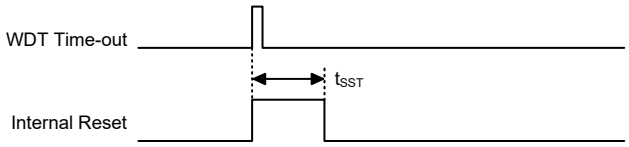
When the Watchdog Time-out Reset during normal operation occurs, the Watchdog time-out flag TO will be set to "1".



WDT Time-out Reset during Normal Operation Timing Chart

Watchdog Time-out Reset during SLEEP or IDLE Mode

The Watchdog Time-out Reset during SLEEP or IDLE Mode is a little different from other kinds of reset. Most of the conditions remain unchanged except that the Program Counter and the Stack Pointer will be cleared to "0" and the TO and PDF flags will be set to "1". Refer to the System Start Up Time Characteristics for t_{SST} details.



WDT Time-out Reset during SLEEP or IDLE Timing Chart

Reset Initial Conditions

The different types of reset described affect the reset flags in different ways. These flags, known as PDF and TO are located in the status register and are controlled by various microcontroller operations, such as the SLEEP or IDLE Mode function or Watchdog Timer. The reset flags are shown in the table:

TO	PDF	Reset Conditions
0	0	Power-on reset
u	u	LVR reset during FAST or SLOW Mode operation
1	u	WDT time-out reset during FAST or SLOW Mode operation
1	1	WDT time-out reset during IDLE or SLEEP Mode operation

"u": Unchanged

The following table indicates the way in which the various components of the microcontroller are affected after a power-on reset occurs.

Item	Condition after Reset
Program Counter	Reset to zero
Interrupts	All interrupts will be disabled
WDT, Time Bases	Clear after reset, WDT begins counting
Timer Module	Timer Module will be turned off
Input/Output Ports	I/O ports will be setup as inputs
Stack Pointer	Stack Pointer will point to the top of the stack

The different kinds of resets all affect the internal registers of the microcontroller in different ways. To ensure reliable continuation of normal program execution after a reset occurs, it is important to know what condition the microcontroller is in after a particular reset occurs. The following table describes how each type of reset affects each of the microcontroller internal registers.

Register	Reset (Power On)	WDT Time-out (Normal Operation)	WDT Time-out (IDLE/SLEEP)
IAR0	xxxx xxxx	uuuu uuuu	uuuu uuuu
MP0	xxxx xxxx	uuuu uuuu	uuuu uuuu
IAR1	xxxx xxxx	uuuu uuuu	uuuu uuuu
MP1	xxxx xxxx	uuuu uuuu	uuuu uuuu
BP	---- ---0	---- ---0	---- ---u
ACC	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	0000 0000	0000 0000	0000 0000
TBLP	xxxx xxxx	uuuu uuuu	uuuu uuuu
TBLH	--xx xxxx	--uu uuuu	--uu uuuu
STATUS	--00 xxxx	--1u uuuu	--11 uuuu
VBGRC	---- ---0	---- ---0	---- ---u
PSCR	---- --00	---- --00	---- --uu
REGC	0--- -000	0--- -000	u--- -uuu
RSTFC	---- -x00	---- -uuu	---- -uuu
TB0C	0--- -000	0--- -000	u--- -uuu
TB1C	0--- -000	0--- -000	u--- -uuu
SCC	000- --00	000- --00	uuu- --uu
HIRCC	---- --01	---- --01	---- --uu
PA	---- 1111	---- 1111	---- uuuu
PAC	---- 1111	---- 1111	---- uuuu
PAPU	---- 0000	---- 0000	---- uuuu
PAWU	---- 0000	---- 0000	---- uuuu
OPSW0	0000 0000	0000 0000	uuuu uuuu
OPSW1	---- ---0	---- ---0	---- ---u
OPPW	---- --00	---- --00	---- --uu
OPC	-00- --00	-00- --00	-uu- --uu
OPVOS	0010 0000	0010 0000	uuuu uuuu
OPPGAC0	0000 0000	0000 0000	uuuu uuuu
OPPGAC1	---- ---0	---- ---0	---- ---u
SADOL	xxxx ----	xxxx ----	uuuu ---- (ADRFS=0) uuuu uuuu (ADRFS=1)
SADOH	xxxx xxxx	xxxx xxxx	uuuu uuuu (ADRFS=0) ---- uuuu (ADRFS=1)
SADC0	0000 0000	0000 0000	uuuu uuuu
SADC1	0000 0000	0000 0000	uuuu uuuu
SADC2	---- --10	---- --10	---- --uu
INTEG	---- --00	---- --00	---- --uu
INTC0	-000 0000	-000 0000	-uuu uuuu
INTC1	0000 0000	0000 0000	uuuu uuuu
LVRC	0101 1010	0101 1010	uuuu uuuu

Register	Reset (Power On)	WDT Time-out (Normal Operation)	WDT Time-out (IDLE/SLEEP)
IFS	---- ---0	---- ---0	---- ---u
PAS0	0000 0000	0000 0000	uuuu uuuu
PTMC0	0000 0---	0000 0---	uuuu u---
PTMC1	0000 0000	0000 0000	uuuu uuuu
PTMC2	---- -000	---- -000	---- -uuu
PTMDL	0000 0000	0000 0000	uuuu uuuu
PTMDH	---- --00	---- --00	---- --uu
PTMAL	0000 0000	0000 0000	uuuu uuuu
PTMAH	---- --00	---- --00	---- --uu
PTMBL	0000 0000	0000 0000	uuuu uuuu
PTMBH	---- --00	---- --00	---- --uu
PTMRPL	0000 0000	0000 0000	uuuu uuuu
PTMRPH	---- --00	---- --00	---- --uu
LMSADOH	xxxx xxxx	uuuu uuuu	uuuu uuuu
LMSADOL	xxxx ----	uuuu ----	uuuu ----
ORMC	0000 0000	0000 0000	0000 0000
WDTC	0101 0011	0101 0011	uuuu uuuu
EEA	---0 0000	---0 0000	---u uuuu
EED	0000 0000	0000 0000	uuuu uuuu
EEC	0--- 0000	0--- 0000	u--- uuuu

Note: “u” stands for unchanged
“x” stands for unknown
“-” stands for unimplemented

Input/Output Ports

Holtek microcontrollers offer considerable flexibility on their I/O ports. With the input or output designation of every pin fully under user program control, pull-high selections for all ports and wake-up selections on certain pins, the user is provided with an I/O structure to meet the needs of a wide range of application possibilities.

The device provides bidirectional input/output lines labeled with port names PA. These I/O ports are mapped to the RAM Data Memory with specific addresses as shown in the Special Purpose Data Memory table. All of these I/O ports can be used for input and output operations. For input operation, these ports are non-latching, which means the inputs must be ready at the T2 rising edge of instruction “MOV A, [m]”, where m denotes the port address. For output operation, all the data is latched and remains unchanged until the output latch is rewritten.

Register Name	Bit							
	7	6	5	4	3	2	1	0
PA	—	—	—	—	PA3	PA2	PA1	PA0
PAC	—	—	—	—	PAC3	PAC2	PAC1	PAC0
PAPU	—	—	—	—	PAPU3	PAPU2	PAPU1	PAPU0
PAWU	—	—	—	—	PAWU3	PAWU2	PAWU1	PAWU0

“—”: Unimplemented, read as “0”

I/O Logic Function Register List

Pull-high Resistors

Many product applications require pull-high resistors for their switch inputs usually requiring the use of an external resistor. To eliminate the need for these external resistors, all I/O pins, when configured as an input have the capability of being connected to an internal pull-high resistor. These pull-high resistors are selected using registers PAPU and are implemented using weak PMOS transistors.

Note that the pull-high resistor can be controlled by the relevant pull-high control register only when the pin-shared functional pin is selected as a digital input or NMOS output. Otherwise, the pull-high resistors cannot be enabled.

• **PAPU Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	PAPU3	PAPU2	PAPU1	PAPU0
R/W	—	—	—	—	R/W	R/W	R/W	R/W
POR	—	—	—	—	0	0	0	0

Bit 7~4 Unimplemented, read as "0"

Bit 3~0 **PAPU3~PAPU0**: PA3~PA0 pin pull-high function control
0: Disable
1: Enable

Port A Wake-up

The HALT instruction forces the microcontroller into the SLEEP or IDLE Mode which preserves power, a feature that is important for battery and other low-power applications. Various methods exist to wake-up the microcontroller, one of which is to change the logic condition on one of the Port A pins from high to low. This function is especially suitable for applications that can be woken up via external switches. Each pin on Port A can be selected individually to have this wake-up feature using the PAWU register.

Note that the wake-up function can be controlled by the wake-up control registers only when the pin is selected as a general purpose input and the MCU enters the IDLE or SLEEP mode.

• **PAWU Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	PAWU3	PAWU2	PAWU1	PAWU0
R/W	—	—	—	—	R/W	R/W	R/W	R/W
POR	—	—	—	—	0	0	0	0

Bit 7~4 Unimplemented, read as "0"

Bit 3~0 **PAWU3~PAWU0**: PA3~PA0 pin Wake-up Control
0: Disable
1: Enable

I/O Port Control Registers

The I/O port has its own control register known as PAC, to control the input/output configuration. With this control register, each CMOS output or input can be reconfigured dynamically under software control. Each pin of the I/O ports is directly mapped to a bit in its associated port control register. For the I/O pin to function as an input, the corresponding bit of the control register must be written as a "1". This will then allow the logic state of the input pin to be directly read by instructions. When the corresponding bit of the control register is written as a "0", the I/O pin will be setup as a CMOS output. If the pin is currently setup as an output, instructions can still be used to read the output register. However, it should be noted that the program will in fact only read the status of the output data latch and not the actual logic status of the output pin.

• **PAC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	PAC3	PAC2	PAC1	PAC0
R/W	—	—	—	—	R/W	R/W	R/W	R/W
POR	—	—	—	—	1	1	1	1

Bit 7~4 Unimplemented, read as "0"

Bit 3~0 **PAC3~PAC0**: I/O Port PA3~PA0 pin type selection
0: Output
1: Input

Pin-shared Functions

The flexibility of the microcontroller range is greatly enhanced by the use of pins that have more than one function. Limited numbers of pins can force serious design constraints on designers but by supplying pins with multi-functions, many of these difficulties can be overcome. For these pins, the desired function of the multi-function I/O pins is selected by a series of registers via the application program control.

Pin-shared Function Selection Registers

The limited number of supplied pins in a package can impose restrictions on the amount of functions a certain device can contain. However by allowing the same pins to share several different functions and providing a means of function selection, a wide range of different functions can be incorporated into even relatively small package sizes. The device includes an Output Function Selection register, labeled as PAS0, and an Input Function Selection register, labeled as IFS, which can select the desired functions of the multi-function pin-shared pins.

The most important point to note is to make sure that the desired pin-shared function is properly selected and also deselected. For most pin-shared functions, to select the desired pin-shared function, the pin-shared function should first be correctly selected using the corresponding pin-shared control register. After that the corresponding peripheral functional setting should be configured and then the peripheral function can be enabled. However, a special point must be noted for some digital input pins, such as INT, PTCK etc., which share the same pin-shared control configuration with their corresponding general purpose I/O functions when setting the relevant pin-shared control bit fields. To select these pin functions, in addition to the necessary pin-shared control and peripheral functional setup aforementioned, they must also be setup as an input by setting the corresponding bit in the I/O port control register. To correctly deselect the pin-shared function, the peripheral function should first be disabled and then the corresponding pin-shared function control register can be modified to select other pin-shared functions.

• **PAS0 Register**

Bit	7	6	5	4	3	2	1	0
Name	PAS07	PAS06	PAS05	PAS04	PAS03	PAS02	PAS01	PAS00
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **PAS07~PAS06**: PA3 Pin-shared function selection
00: PA3/PTPI
01: AN3
10: PA3/PTPI
11: PA3/PTPI

Bit 5~4 **PAS05~PAS04**: PA2 Pin-shared function selection
00: PA2/INT
01: PTPB
10: AN0
11: PA2/INT

Bit 3~2 **PAS03~PAS02**: PA1 Pin-shared function selection
00: PA1/PTCK
01: AN1
10: PA1/PTCK
11: PA1/PTCK

Bit 1~0 **PAS01~PAS00**: PA0 Pin-shared function selection
00: PA0/INT
01: PTP
10: AN2
11: PA0/INT

• **IFS Register**

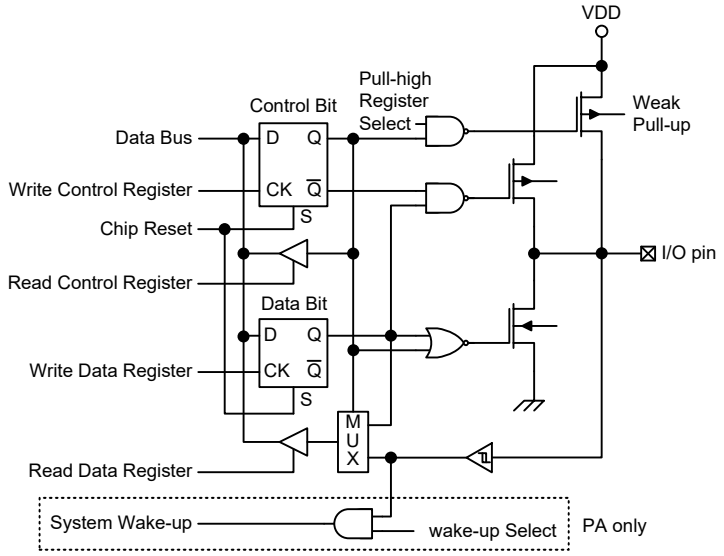
Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	—	IFS0
R/W	—	—	—	—	—	—	—	R/W
POR	—	—	—	—	—	—	—	0

Bit 7~1 Unimplemented, read as "0"

Bit 0 **IFS0**: INT input source pin selection
0: PA2
1: PA0

I/O Pin Structures

The accompanying diagram illustrates the internal structures of the I/O logic function. As the exact logical construction of the I/O pin will differ from this diagram, it is supplied as a guide only to assist with the functional understanding of the logic function I/O pins. The wide range of pin-shared structures does not permit all types to be shown.



Logic Function Input/Output Structure

Programming Considerations

Within the user program, one of the first things to consider is port initialisation. After a reset, all of the I/O data and port control registers will be set high. This means that all I/O pins will default to an input state, the level of which depends on the other connected circuitry and whether pull-high selections have been chosen. If the port control registers are then programmed to setup some pins as outputs, these output pins will have an initial high output value unless the associated port data registers are first programmed. Selecting which pins are inputs and which are outputs can be achieved byte-wide by loading the correct values into the appropriate port control register or by programming individual bits in the port control register using the "SET [m].i" and "CLR [m].i" instructions. Note that when using these bit control instructions, a read-modify-write operation takes place. The microcontroller must first read in the data on the entire port, modify it to the required new bit values and then rewrite this data back to the output ports.

Port A has the additional capability of providing wake-up functions. When the device is in the SLEEP or IDLE Mode, various methods are available to wake the device up. One of these is a high to low transition of any of the Port A pins. Single or multiple pins on Port A can be setup to have this function.

Timer Modules – TM

One of the most fundamental functions in any microcontroller devices is the ability to control and measure time. To implement time related functions the device includes a Timer Module, generally abbreviated to the name TM. The TM is multi-purpose timing units and serve to provide operations such as Timer/Counter, Input Capture, Compare Match Output and Single Pulse Output as well as being the functional unit for the generation of PWM signals. The TM has two interrupts. The addition of input and output pins for the TM ensures that users are provided with timing units with a wide and flexible range of features.

The brief features of the Periodic Type TM are described here with more detailed information provided in the individual Periodic Type TM section.

Introduction

The device contains one 10-bit Periodic Type TM with a reference name of PTM. The main features of the PTM are summarised in the accompanying table.

TM Function	PTM
Timer/Counter	√
Input Capture	√
Compare Match Output	√
PWM Output	√
Single Pulse Output	√
PWM Alignment	Edge
PWM Adjustment Period & Duty	Duty or Period

TM Function Summary

TM Operation

The Periodic Type TM offers a diverse range of functions, from simple timing operations to PWM signal generation. The key to understanding how the TM operates is to see it in terms of a free running count-up counter whose value is then compared with the value of pre-programmed internal comparators. When the free running count-up counter has the same value as the pre-programmed comparator, known as a compare match situation, a TM interrupt signal will be generated which

can clear the counter and perhaps also change the condition of the TM output pin. The internal TM counter is driven by a user selectable clock source, which can be an internal clock or an external pin.

TM Clock Source

The clock source which drives the main counter in the TM can originate from various sources. The selection of the required clock source is implemented using the PTCK2~PTCK0 bits in the PTM control register. The clock source can be a ratio of the system clock, f_{SYS}, or the internal high clock, f_H, the f_{SUB} clock source or the external PTCK pin. The PTCK pin clock source is used to allow an external signal to drive the TM as an external clock source for event counting.

TM Interrupts

The Periodic Type TM has two internal interrupt, one for each of the internal comparator A or comparator P, which generate a TM interrupt when a compare match condition occurs. When a TM interrupt is generated, it can be used to clear the counter and also to change the state of the TM output pin.

TM External Pins

The Periodic Type TM has two TM input pins, with the label PTCK and PTPI respectively. The PTM input pin, PTCK, is essentially a clock source for the PTM and is selected using the PTCK2~PTCK0 bits in the PTMC0 register. This external TM input pin allows an external clock source to drive the internal TM. The PTCK input pin can be chosen to have either a rising or falling active edge. The PTCK pin is also used as the external trigger input pin in single pulse output mode.

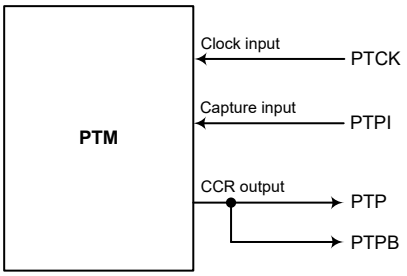
The other PTM input pin, PTPI, is the capture input whose active edge can be a rising edge, a falling edge or both rising and falling edges and the active edge transition type is selected using the PTIO1~PTIO0 bits in the PTMC1 register. There is another capture input, PTCK, for PTM capture input mode, which can be used as the external trigger input source except the PTPI pin.

The Periodic Type TM has two output pins, PTP and PTPB, the PTPB pin outputs the inverted signal of the PTP. When the TM is in the Compare Match Output Mode, these pins can be controlled by the TM to switch to a high or low level or to toggle when a compare match situation occurs. The external PTP and PTPB output pins are also the pins where the TM generates the PWM output waveform.

As the TM input and output pins are pin-shared with other functions, the TM input and output functions must first be setup using relevant pin-shared function selection register. The details of the pin-shared function selection are described in the pin-shared function section.

PTM	
Input	**Output**
PTCK, PTPI	PTP, PTPB

TM External Pins

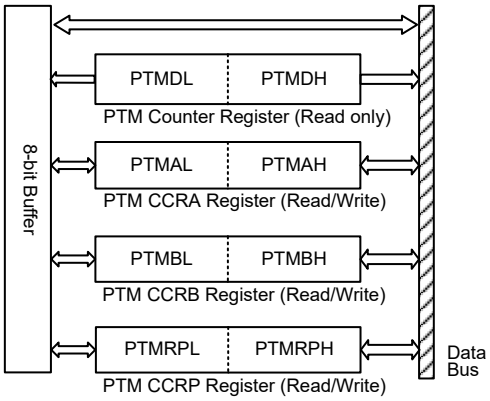


PTM Function Pin Block Diagram

Programming Considerations

The TM Counter Registers and the Capture/Compare CCRA registers as well as the CCRB register, all have a low and high byte structure. The high bytes can be directly accessed, but as the low bytes can only be accessed via an internal 8-bit buffer, reading or writing to these register pairs must be carried out in a specific way. The important point to note is that data transfer to and from the 8-bit buffer and its related low byte only takes place when a write or read operation to its corresponding high byte is executed.

As the CCRA, CCRP and CCRB registers are implemented in the way shown in the following diagram and accessing these register pairs is carried out in a specific way as described above, it is recommended to use the "MOV" instruction to access the CCRA, CCRP and CCRB low byte registers, named PTMAL, PTMRPL, PTMBL, using the following access procedures. Accessing the CCRA, CCRP or CCRB low byte registers without following these access procedures will result in unpredictable values.

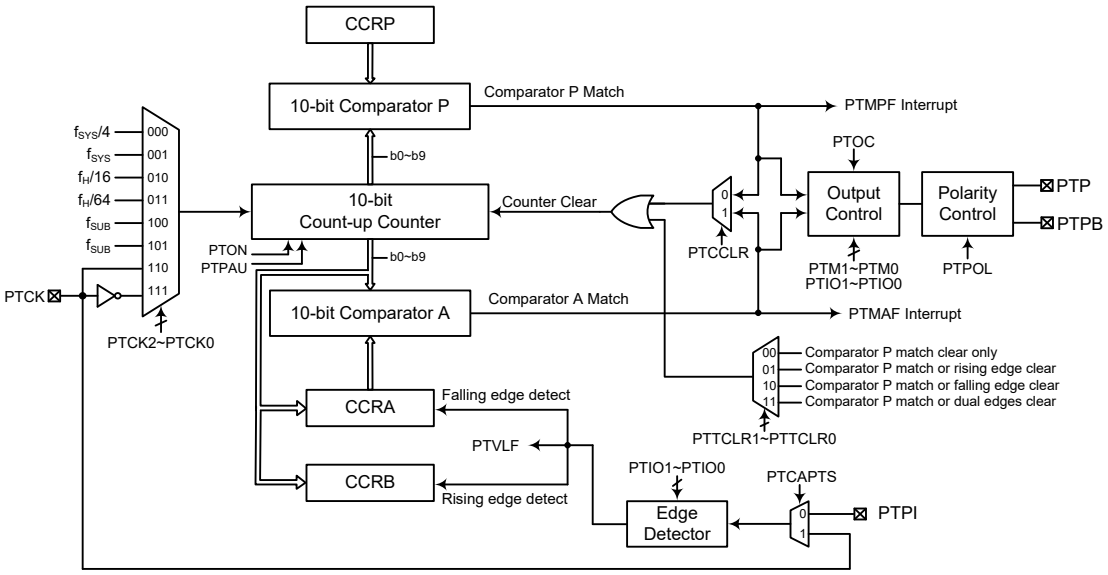


The following steps show the read and write procedures:

- Writing Data to CCRA, CCRB or CCRP
  - Step 1. Write data to Low Byte PTMAL, PTMBL or PTMRPL
    - Note that here data is only written to the 8-bit buffer.
  - Step 2. Write data to High Byte PTMAH, PTMBH or PTMRPH
    - Here data is written directly to the high byte registers and simultaneously data is latched from the 8-bit buffer to the Low Byte registers.
- Reading Data from the Counter Registers and CCRA, CCRB or CCRP
  - Step 1. Read data from the High Byte PTMDH, PTMAH, PTMBH or PTMRPH
    - Here data is read directly from the High Byte registers and simultaneously data is latched from the Low Byte register into the 8-bit buffer.
  - Step 2. Read data from the Low Byte PTMDL, PTMAL, PTMBL or PTMRPL
    - This step reads data from the 8-bit buffer.

Periodic Type TM – PTM

The Periodic Type TM contains five operating modes, which are Compare Match Output, Timer/ Event Counter, Capture Input, Single Pulse Output and PWM Output modes. The Periodic Type TM can be controlled with two external input pins and can drive two external output pins.



Note: 1. The PTPB pin is the inverted output of the PTP pin.
2. The PTM external pins are pin-shared with other functions, so before using the PTM function, the pin-shared function registers must be set properly.

10-bit Periodic Type TM Block Diagram

Periodic Type TM Operation

The Periodic Type TM core is a 10-bit count-up counter which is driven by a user selectable internal or external clock source. There are also two internal comparators with the names, Comparator A and Comparator P. These comparators will compare the value in the counter with CCRP and CCRA registers. The CCRA and CCRP comparators are 10-bit wide whose value is respectively compared with all counter bits.

The only way of changing the value of the 10-bit counter using the application program, is to clear the counter by changing the PTON bit from low to high. The counter will also be cleared automatically by a counter overflow or a compare match with one of its associated comparators. When these conditions occur, a PTM interrupt signal will also usually be generated. The Periodic Type TM can operate in a number of different operational modes, can be driven by different clock sources including an input pin and can also control different outputs. All operating setup conditions are selected using relevant internal registers.

Periodic Type TM Register Description

Overall operation of the Periodic Type TM is controlled using a series of registers. A read only register pair exists to store the internal counter 10-bit value, while three read/write register pairs exist to store the internal 10-bit CCRA value, CCRP value and CCRB value. The remaining three registers are control registers which setup the different operating and control modes.

Register Name	Bit							
	7	6	5	4	3	2	1	0
PTMC0	PTPAU	PTCK2	PTCK1	PTCK0	PTON	—	—	—
PTMC1	PTM1	PTM0	PTIO1	PTIO0	PTOC	PTPOL	PTCAPTS	PTCCLR
PTMC2	—	—	—	—	—	PTTCLR1	PTTCLR0	PTVLF
PTMDL	D7	D6	D5	D4	D3	D2	D1	D0
PTMDH	—	—	—	—	—	—	D9	D8
PTMAL	D7	D6	D5	D4	D3	D2	D1	D0
PTMAH	—	—	—	—	—	—	D9	D8
PTMBL	D7	D6	D5	D4	D3	D2	D1	D0
PTMBH	—	—	—	—	—	—	D9	D8
PTMRPL	D7	D6	D5	D4	D3	D2	D1	D0
PTMRPH	—	—	—	—	—	—	D9	D8

10-bit Periodic Type TM Register List

- **PTMC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	PTPAU	PTCK2	PTCK1	PTCK0	PTON	—	—	—
R/W	R/W	R/W	R/W	R/W	R/W	—	—	—
POR	0	0	0	0	0	—	—	—

Bit 7 **PTPAU**: PTM Counter Pause control
0: Run
1: Pause
The counter can be paused by setting this bit high. Clearing the bit to zero restores normal counter operation. When in a Pause condition the PTM will remain powered up and continue to consume power. The counter will retain its residual value when this bit changes from low to high and resume counting from this value when the bit changes to a low value again.

Bit 6~4 **PTCK2~PTCK0**: Select PTM Counter clock
000: $f_{SYS}/4$
001: f_{SYS}
010: $f_H/16$
011: $f_H/64$
100: f_{SUB}
101: f_{SUB}
110: PTCK rising edge clock
111: PTCK falling edge clock
These three bits are used to select the clock source for the PTM. The external pin clock source can be chosen to be active on the rising or falling edge. The clock source f_{SYS} is the system clock, while f_H and f_{SUB} are other internal clocks, the details of which can be found in the oscillator section.

Bit 3 **PTON**: PTM Counter on/off control
0: Off
1: On
This bit controls the overall on/off function of the PTM. Setting the bit high enables the counter to run, clearing the bit disables the PTM. Clearing this bit to zero will stop the counter from counting and turn off the PTM which will reduce its power consumption. When the bit changes state from low to high the internal counter value will be reset to zero, however when the bit changes from high to low, the internal counter will retain its residual value until the bit returns high again.
If the PTM is in the Compare Match Output Mode, PWM output Mode or Single Pulse

Output Mode then the PTM output pin will be reset to its initial condition, as specified by the PTOC bit, when the PTON bit changes from low to high.

Bit 2~0 Unimplemented, read as "0"

- **PTMC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	PTM1	PTM0	PTIO1	PTIO0	PTOC	PTPOL	PTCAPTS	PTCCLR
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~6 **PTM1~PTM0**: Select PTM Operating Mode
00: Compare Match Output Mode
01: Capture Input Mode
10: PWM Output Mode or Single Pulse Output Mode
11: Timer/Counter Mode

These bits setup the required operating mode for the PTM. To ensure reliable operation the PTM should be switched off before any changes are made to the PTM1 and PTM0 bits. In the Timer/Counter Mode, the PTM output pin state is undefined.

Bit 5~4 **PTIO1~PTIO0**: Select PTM pin function

Compare Match Output Mode
00: No change
01: Output low
10: Output high
11: Toggle output

PWM Output Mode/Single Pulse Output Mode
00: PWM output inactive state
01: PWM output active state
10: PWM output
11: Single pulse output

Capture Input Mode

PTTCLR[1:0]=00B:
00: Input capture at rising edge of PTPI or PTCK, and the counter value will be latched into CCRA
01: Input capture at falling edge of PTPI or PTCK, and the counter value will be latched into CCRA
10: Input capture at falling/rising edge of PTPI or PTCK, and the counter value will be latched into CCRA
11: Input capture disabled

PTTCLR[1:0]=01B or 10B or 11B:
00: Input capture at rising edge of PTPI or PTCK, and the counter value will be latched into CCRB
01: Input capture at falling edge of PTPI or PTCK, and the counter value will be latched into CCRA
10: Input capture at falling/rising edge of PTPI or PTCK, and the counter value will be latched into CCRA at falling edge and into CCRB at rising edge
11: Input capture disabled

Timer/Counter Mode
Unused

These two bits are used to determine how the PTM operates when a certain condition is reached. The function that these bits select depends upon in which mode the PTM is running.

In the Compare Match Output Mode, the PTIO1 and PTIO0 bits determine how the PTM output pin changes state when a compare match occurs from the Comparator A. The PTM output pin can be setup to switch high, switch low or to toggle its present state when a compare match occurs from the Comparator A. When the bits are both

zero, then no change will take place on the output. The initial value of the PTM output pin should be setup using the PTOC bit in the PTMC1 register. Note that the output level requested by the PTIO1 and PTIO0 bits must be different from the initial value setup using the PTOC bit otherwise no change will occur on the PTM output pin when a compare match occurs. After the PTM output pin changes state, it can be reset to its initial level by changing the level of the PTON bit from low to high.

In the PWM Output Mode, the PTIO1 and PTIO0 bits determine how the PTM output pin changes state when a certain compare match condition occurs. The PWM output function is modified by changing these two bits. It is necessary to only change the values of the PTIO1 and PTIO0 bits after the PTM has been switched off. Unpredictable PWM outputs will occur if the PTIO1 and PTIO0 bits are changed when the PTM is running.

In the Capture Input Mode, the PTIO1 and PTIO0 bits are used to select the active trigger edge on the selected input signal.

Bit 3 **PTOC**: PTM Output control bit

Compare Match Output Mode
0: Initial low
1: Initial high

PWM Output Mode/Single Pulse Output Mode
0: Active low
1: Active high

This is the output control bit for the PTM output pin. Its operation depends upon whether PTM is being used in the Compare Match Output Mode or in the PWM Output Mode/Single Pulse Output Mode. It has no effect if the PTM is in the Timer/Counter Mode. In the Compare Match Output Mode it determines the logic level of the PTM output pin before a compare match occurs. In the PWM Output Mode it determines if the PWM signal is active high or active low. In the Single Pulse Output Mode it determines the logic level of the PTM output pin when the PTON bit changes from low to high.

Bit 2 **PTPOL**: PTM Output polarity control
0: Non-invert
1: Invert

This bit controls the polarity of the output pins. When the bit is set high the PTM output pin will be inverted and not inverted when the bit is zero. It has no effect if the PTM is in the Timer/Counter Mode.

Bit 1 **PTCAPTS**: PTM Capture Trigger Source selection
0: From PTPI pin
1: From PTCK pin

Bit 0 **PTCCLR**: Select PTM Counter clear condition
0: PTM Comparator P match
1: PTM Comparator A match

This bit is used to select the method which clears the counter. Remember that the Periodic Type TM contains two comparators, Comparator A and Comparator P, either of which can be selected to clear the internal counter. With the PTCCLR bit set high, the counter will be cleared when a compare match occurs from the Comparator A. When the bit is low, the counter will be cleared when a compare match occurs from the Comparator P or with a counter overflow. A counter overflow clearing method can only be implemented if the CCRP bits are all cleared to zero. The PTCCLR bit is not used in the PWM Output Mode, Single Pulse Output or Capture Input Mode or Capture Input Mode.

• **PTMC2 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	PTTCLR1	PTTCLR0	PTVLF
R/W	—	—	—	—	—	R/W	R/W	R
POR	—	—	—	—	—	0	0	0

Bit 7~3 Unimplemented, read as "0"

Bit 2~1 **PTTCLR1~PTTCLR0**: Select PTM Timer clear condition (for capture input mode only)
00: Comparator P match clear only
01: Comparator P match clear or PTPI/PTCK rising edge clear
10: Comparator P match clear or PTPI/PTCK falling edge clear
11: Comparator P match clear or PTPI/PTCK dual edges clear

Bit 0 **PTVLF**: PTM Counter Value Latch trigger edge flag
0: Falling edge trigger the counter value latch
1: Rising edge trigger the counter value latch
When setting PTTCLR1~PTTCLR0 bits equal to 00B, ignore this flag status.

• **PTMDL Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R	R	R	R	R	R	R	R
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: PTM Counter Low Byte Register bit 7 ~ bit 0
PTM 10-bit Counter bit 7 ~ bit 0

• **PTMDH Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R	R
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as "0"

Bit 1~0 **D9~D8**: PTM Counter High Byte Register bit 1 ~ bit 0
PTM 10-bit Counter bit 9 ~ bit 8

• **PTMAL Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: PTM CCRA Low Byte Register bit 7 ~ bit 0
PTM 10-bit CCRA bit 7 ~ bit 0

• **PTMAH Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as "0"

Bit 1~0 **D9~D8**: PTM CCRA High Byte Register bit 1 ~ bit 0
PTM 10-bit CCRA bit 9 ~ bit 8

• **PTMBL Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: PTM CCRB Low Byte Register bit 7 ~ bit 0
PTM 10-bit CCRB bit 7 ~ bit 0

• **PTMBH Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as "0"

Bit 1~0 **D9~D8**: PTM CCRB High Byte Register bit 1 ~ bit 0
PTM 10-bit CCRB bit 9 ~ bit 8

• **PTMRPL Register**

Bit	7	6	5	4	3	2	1	0
Name	D7	D6	D5	D4	D3	D2	D1	D0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **D7~D0**: PTM CCRP Low Byte Register bit 7 ~ bit 0
PTM 10-bit CCRP bit 7 ~ bit 0

• **PTMRPH Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D9	D8
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as "0"

Bit 1~0 **D9~D8**: PTM CCRP High Byte Register bit 1 ~ bit 0
PTM 10-bit CCRP bit 9 ~ bit 8

Periodic Type TM Operating Modes

The Periodic Type TM can operate in one of five operating modes, Compare Match Output Mode, PWM Output Mode, Single Pulse Output Mode, Capture Input Mode or Timer/Counter Mode. The operating mode is selected using the PTM1 and PTM0 bits in the PTMC1 register.

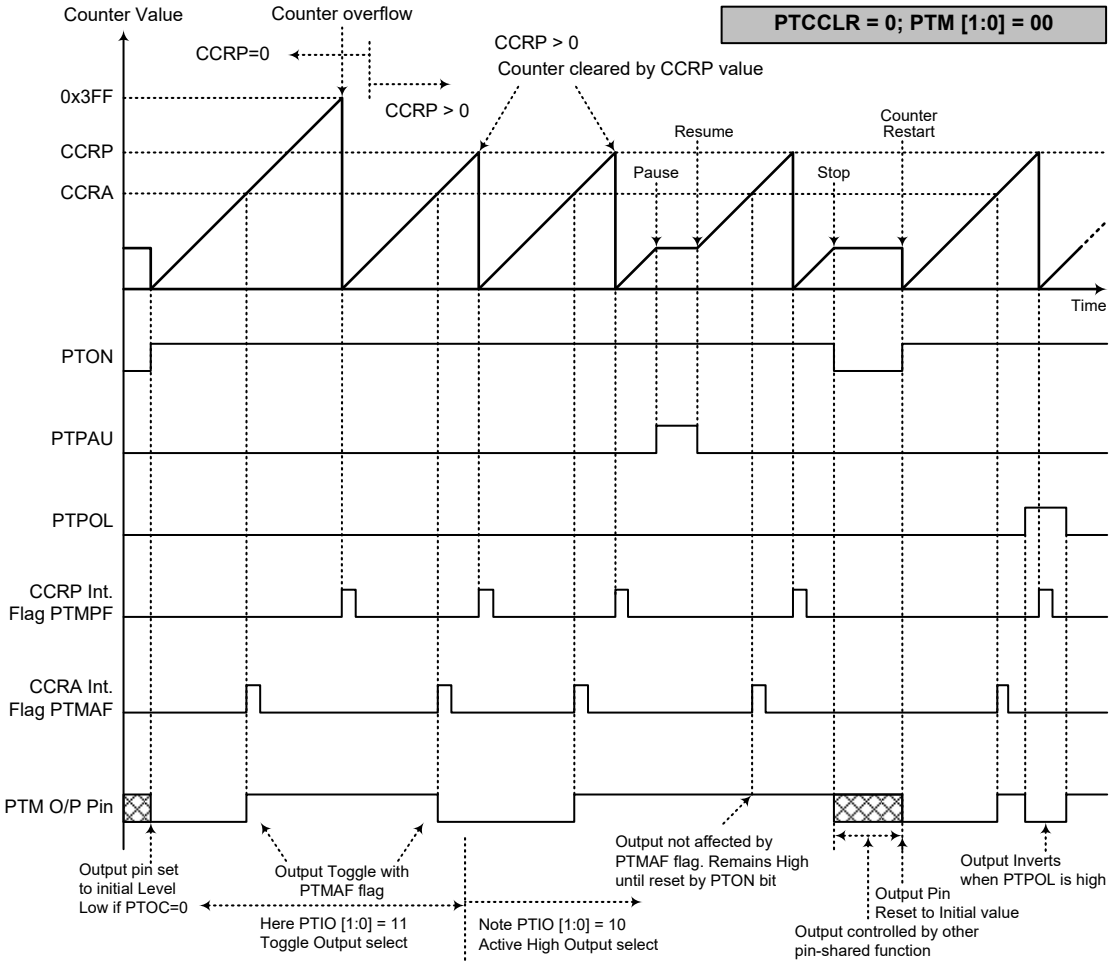
Compare Match Output Mode

To select this mode, bits PTM1 and PTM0 in the PTMC1 register, should be set to 00 respectively. In this mode once the counter is enabled and running it can be cleared by three methods. These are a counter overflow, a compare match from Comparator A and a compare match from Comparator P. When the PTCCLR bit is low, there are two ways in which the counter can be cleared. One is when a compare match from Comparator P, the other is when the CCRP bits are all zero which allows the counter to overflow. Here both PTMAF and PTMPF interrupt request flags for Comparator A and Comparator P respectively, will both be generated.

If the PTCCLR bit in the PTMC1 register is high then the counter will be cleared when a compare match occurs from Comparator A. However, here only the PTMAF interrupt request flag will be generated even if the value of the CCRP bits is less than that of the CCRA registers. Therefore when PTCCLR is high no PTMPF interrupt request flag will be generated. In the Compare Match Output Mode, the CCRA can not be cleared to zero.

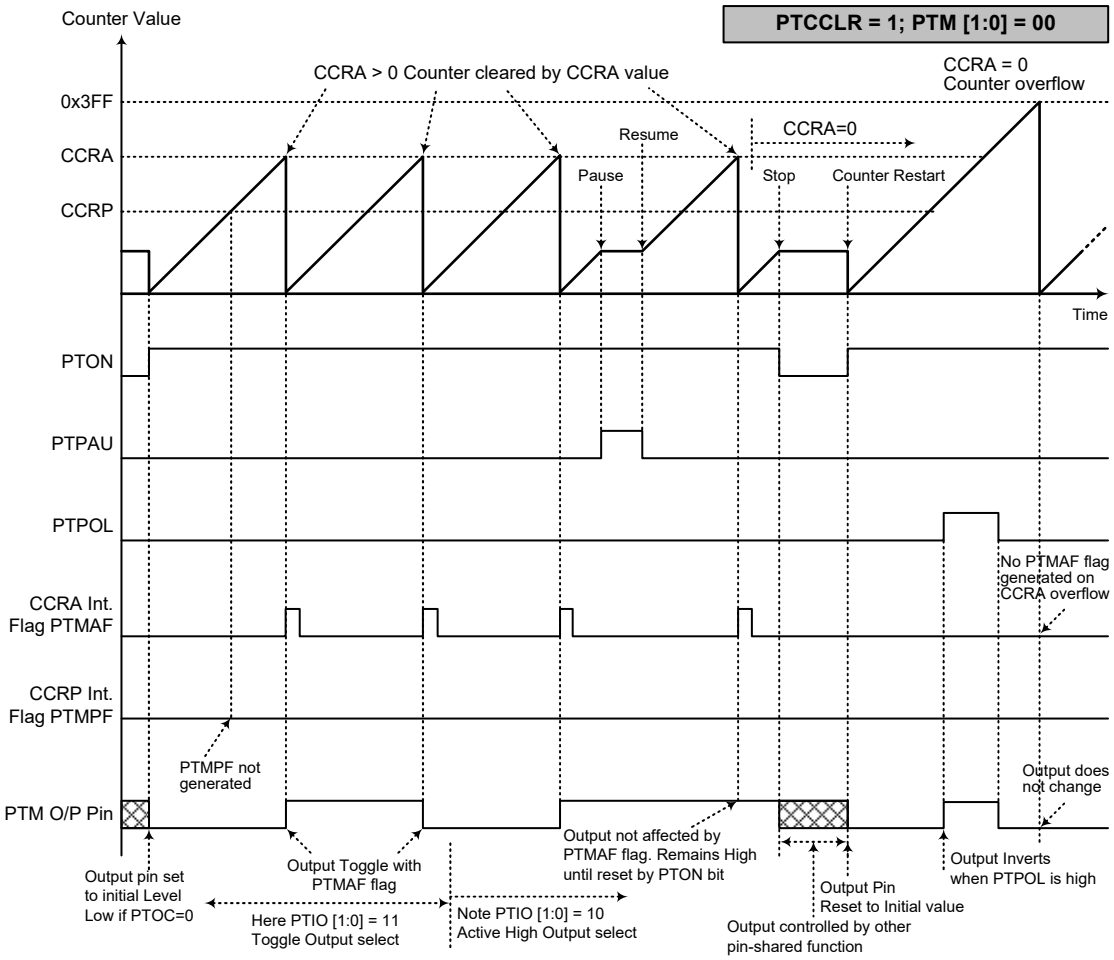
If the CCRA bits are all zero, the counter will overflow when its reaches its maximum value 3FFH, however here the PTMAF interrupt request flag will not be generated.

As the name of the mode suggests, after a comparison is matched, the PTM output pin will change state. The PTM output pin condition however only changes state when a PTMAF interrupt request flag is generated after a compare match occurs from Comparator A. The PTMPF interrupt request flag, generated from a compare match occurs from Comparator P, will have no effect on the PTM output pin. The way in which the PTM output pin changes state are determined by the condition of the PTIO1 and PTIO0 bits in the PTMC1 register. The PTM output pin can be selected using the PTIO1 and PTIO0 bits to go high, to go low or to toggle from its present condition when a compare match occurs from Comparator A. The initial condition of the PTM output pin, which is setup after the PTON bit changes from low to high, is setup using the PTOC bit. Note that if the PTIO1 and PTIO0 bits are zero then no pin change will take place.



Compare Match Output Mode – PTCCLR=0

Note: 1. With PTCCLR=0 a Comparator P match will clear the counter
2. The PTM output pin controlled only by the PTMAF flag
3. The output pin reset to its initial state by a PTON bit rising edge



Compare Match Output Mode – PTCCLR=1

Note: 1. With PTCCLR=1 a Comparator A match clear the counter
2. The PTM output pin controlled only by the PTMAF flag
3. The output pin reset to its initial state by a PTON bit rising edge
4. A PTMPF flag is not generated when PTCCLR=1

Timer/Counter Mode

To select this mode, bits PTM1 and PTM0 in the PTMC1 register should be set to 11 respectively. The Timer/Counter Mode operates in an identical way to the Compare Match Output Mode generating the same interrupt flags. The exception is that in the Timer/Counter Mode the PTM output pins are not used. Therefore the above description and Timing Diagrams for the Compare Match Output Mode can be used to understand its function. As the PTM output pins are not used in this mode, the pins can be used as normal I/O pins or other pin-shared functions.

PWM Output Mode

To select this mode, bits PTM1 and PTM0 in the PTMC1 register should be set to 10 respectively and also the PTIO1 and PTIO0 bits should be set to 10 respectively. The PWM function within the PTM is useful for applications which require functions such as motor control, heating control, illumination control etc. By providing a signal of fixed frequency but of varying duty cycle on the PTM output pin, a square wave AC waveform can be generated with varying equivalent DC RMS values.

As both the period and duty cycle of the PWM waveform can be controlled, the choice of generated waveform is extremely flexible. In the PWM Output Mode, the PTCCLR bit has no effect on the PWM operation. Both of the CCRA and CCRP registers are used to generate the PWM waveform, CCRP register is used to clear the internal counter and thus control the PWM waveform frequency, while CCRA register is used to control the duty cycle. The PWM waveform frequency and duty cycle can therefore be controlled by the values in the CCRA and CCRP registers.

An interrupt flag, one for each of the CCRA and CCRP, will be generated when a compare match occurs from either Comparator A or Comparator P. The PTOC bit in the PTMC1 register is used to select the required polarity of the PWM waveform while the two PTIO1 and PTIO0 bits are used to enable the PWM output or to force the PTM output pin to a fixed high or low level. The PTPOL bit is used to reverse the polarity of the PWM output waveform.

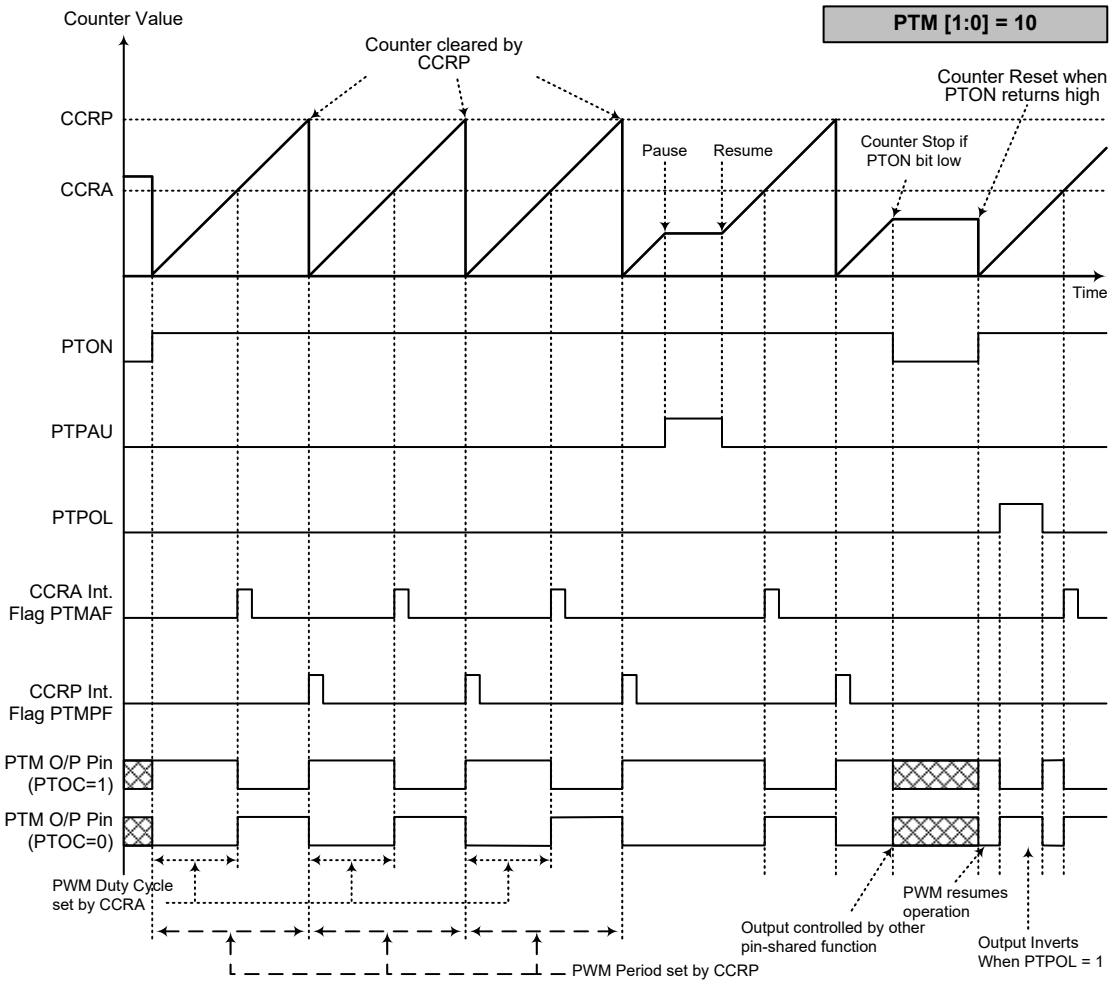
- **10-bit PTM, PWM Output Mode, Edge-aligned Mode**

CCRP	1~1023	0
Period	1~1023	1024
Duty	CCRA	

If f_{SYS}=8MHz, PTM clock source select $f_{SYS}/4$, CCRP=512 and CCRA=128,

The PTM PWM output frequency=($f_{SYS}/4$)/512=$f_{SYS}/2048$=4kHz, duty=128/512=25%.

If the Duty value defined by the CCRA register is equal to or greater than the Period value, then the PWM output duty is 100%.



PWM Output Mode

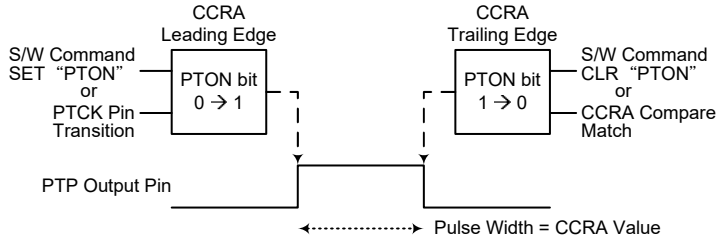
Note: 1. Counter cleared by CCRP
2. A counter clear sets the PWM Period
3. The internal PWM function continues running even when PTIO[1:0]=00 or 01
4. The PTCCLR bit has no influence on PWM operation

Single Pulse Output Mode

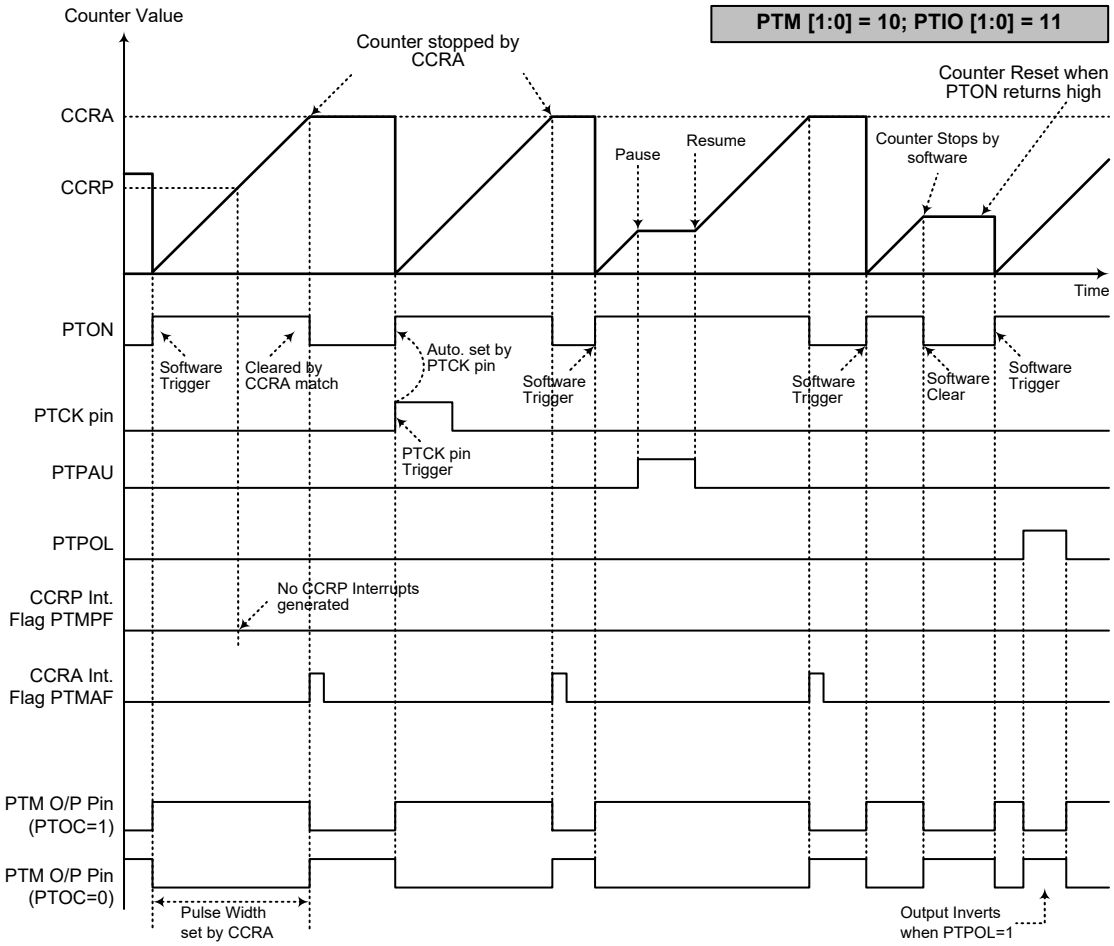
To select this mode, bits PTM1 and PTM0 in the PTMC1 register should be set to 10 respectively and also the PTIO1 and PTIO0 bits should be set to 11 respectively. The Single Pulse Output Mode, as the name suggests, will generate a single shot pulse on the PTM output pin.

The trigger for the pulse output leading edge is a low to high transition of the PTON bit, which can be implemented using the application program. However in the Single Pulse Output Mode, the PTON bit can also be made to automatically change from low to high using the external PTCK pin, which will in turn initiate the Single Pulse output. When the PTON bit transitions to a high level, the counter will start running and the pulse leading edge will be generated. The PTON bit should remain high when the pulse is in its active state. The generated pulse trailing edge will be generated when the PTON bit is cleared to zero, which can be implemented using the application program or when a compare match occurs from Comparator A.

However a compare match from Comparator A will also automatically clear the PTON bit and thus generate the Single Pulse output trailing edge. In this way the CCRA value can be used to control the pulse width. A compare match from Comparator A will also generate a PTM interrupt. The counter can only be reset back to zero when the PTON bit changes from low to high when the counter restarts. In the Single Pulse Output Mode CCRP is not used. The PTCCLR bit is not used in this Mode.



Single Pulse Generation



Single Pulse Output Mode

Note: 1. Counter stopped by CCRA
2. CCRP is not used
3. The pulse is triggered by the PTCK pin or by setting the PTON bit high
4. A PTCK pin active edge will automatically set the PTON bit high
5. In the Single Pulse Output Mode, PTIO[1:0] must be set to “11” and cannot be changed

Capture Input Mode

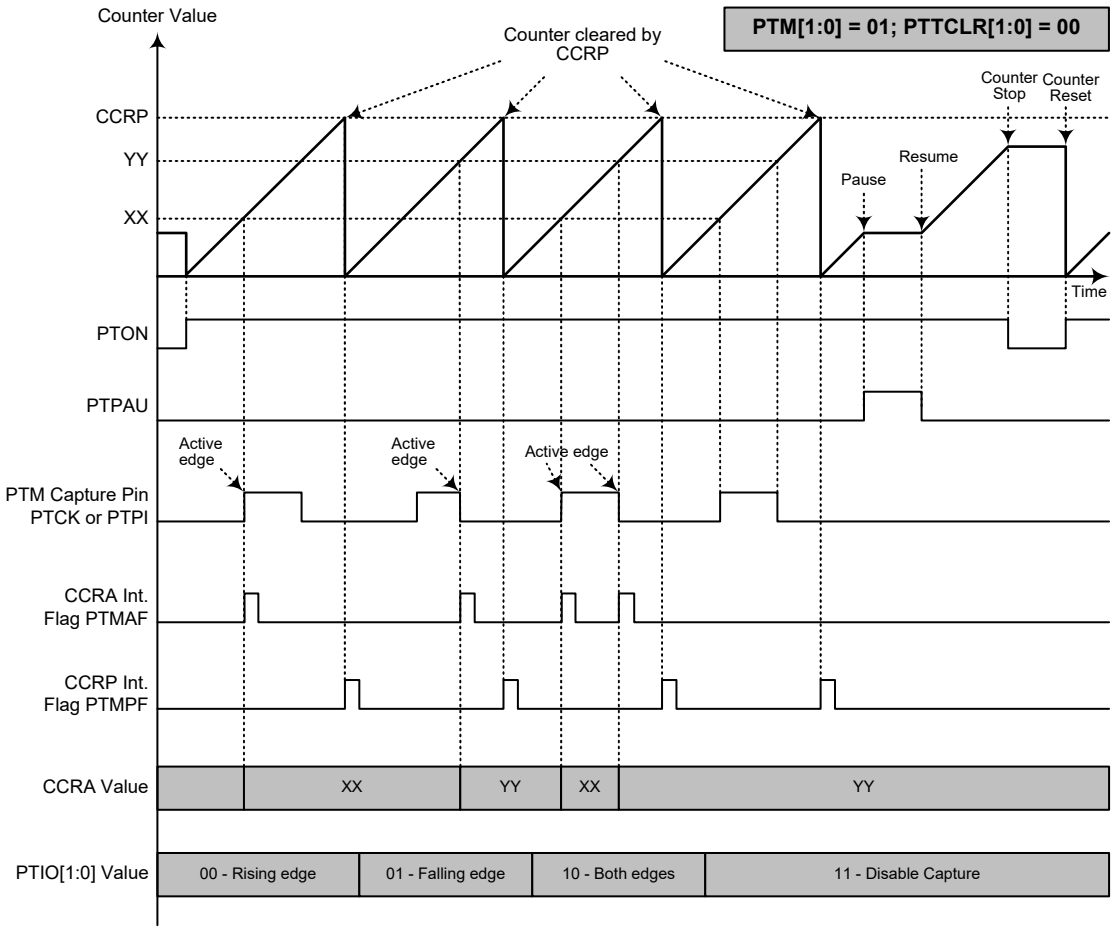
To select this mode bits PTM1 and PTM0 in the PTMC1 register should be set to 01 respectively. This mode enables external signals to capture and store the present value of the internal counter and can therefore be used for applications such as pulse width measurements. The external signal is supplied on the PTPI or PTCK pin which is selected using the PTCAPTS bit in the PTMC1 register. The input pin active edge can be either a rising edge, a falling edge or both rising and falling edges; the active edge transition type is selected using the PTIO1 and PTIO0 bits in the PTMC1 register. The counter is started when the PTON bit changes from low to high which is initiated using the application program.

The PTIO1 and PTIO0 bits decide which active edge transition type to be latched and to generate an interrupt. The PTTCLR1 and PTTCLR0 bits decide the condition that the counter reset back to zero. The present counter value latched into CCRA or CCRB is decided by PTIO1~PTIO0 together with PTTCLR1~PTTCLR0 setting. The PTIO1~PTIO0 and PTTCLR1~PTTCLR0 bits are setup independently on each other.

When the required edge transition appears on the PTPI or PTCK pin, the present value in the counter will be latched into the CCRA or CCRB registers and a PTM interrupt generated. Irrespective of what events occur on the input signal, the counter will continue to free run until the PTON bit changes from high to low. When a CCRP compare match occurs the counter will reset back to zero; in this way the CCRP value can be used to control the maximum counter value. When a CCRP compare match occurs from Comparator P, a PTM interrupt will also be generated. Counting the number of overflow interrupt signals from the CCRP can be a useful method in measuring long pulse widths. The PTIO1 and PTIO0 bits can select the active trigger edge on the PTPI or PTCK pin to be a rising edge, falling edge or both edge types. If the PTIO1 and PTIO0 bits are both set high, then no capture operation will take place irrespective of what happens on the PTPI or PTCK pin, however it must be noted that the counter will continue to run.

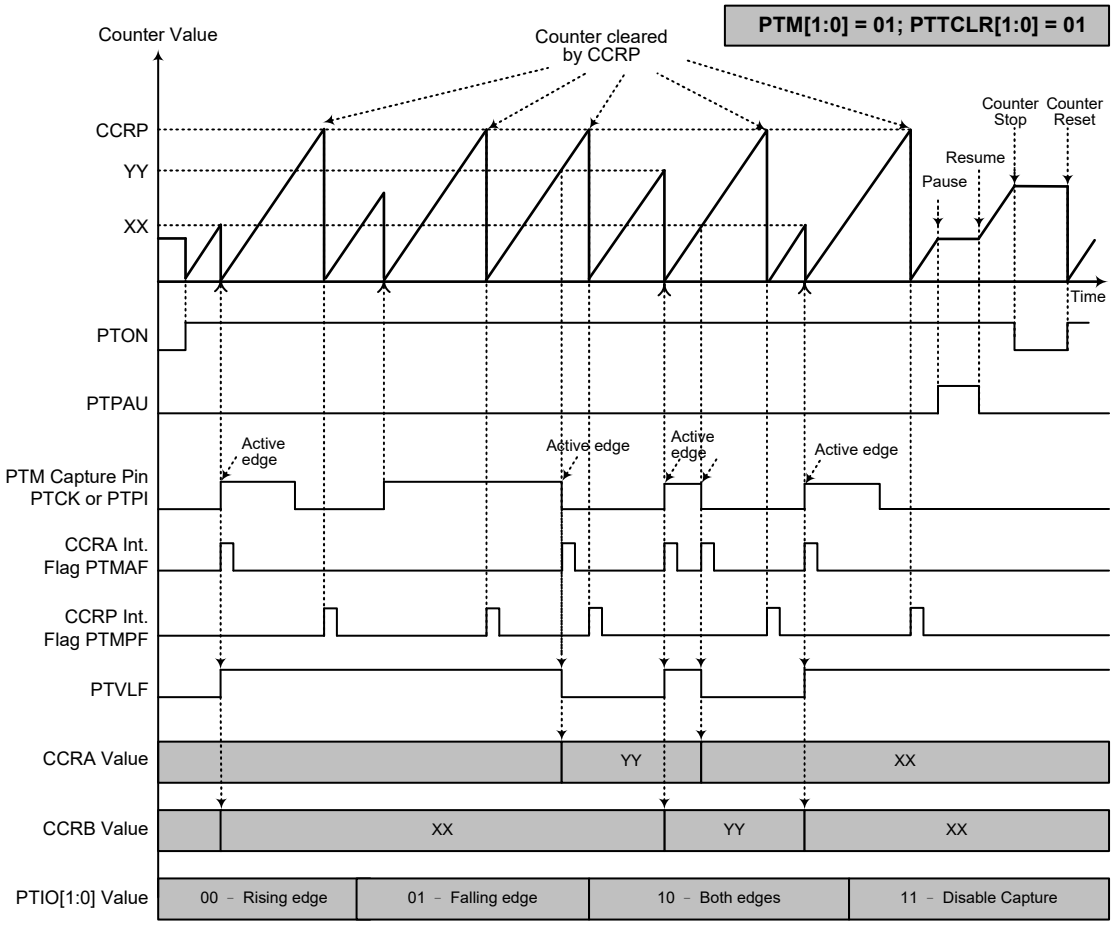
If the capture pulse width is less than two timer clock cycles, it may be ignored by hardware. The timer clock source must be equal to or less than 50MHz, otherwise the counter may fail to count.

The PTCCLR, PTOC and PTPOL bits are not used in this Mode.



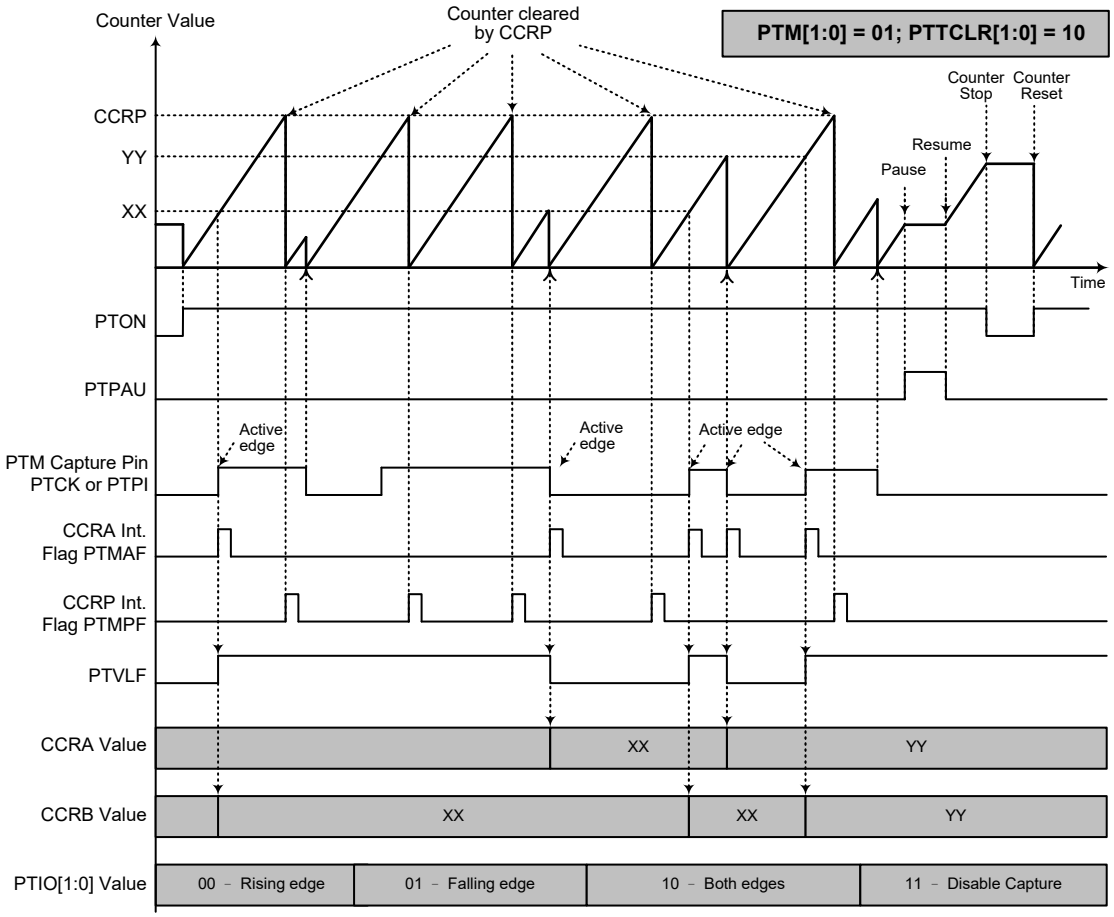
Capture Input Mode – PTTCLR[1:0]=00

Note: 1. PTM[1:0]=01, PTTCLR[1:0]=00 and active edge set by the PTIO[1:0] bits
2. A PTM Capture input pin active edge transfers the counter value to CCRA
3. Comparator P match will clear the counter
4. PTCCLR bit not used
5. No output function – PTOC and PTPOL bits are not used
6. CCRP determines the counter value and the counter has a maximum count value when CCRP is equal to zero
7. Ignore the PTVLF bit status when PTTCLR[1:0]=00



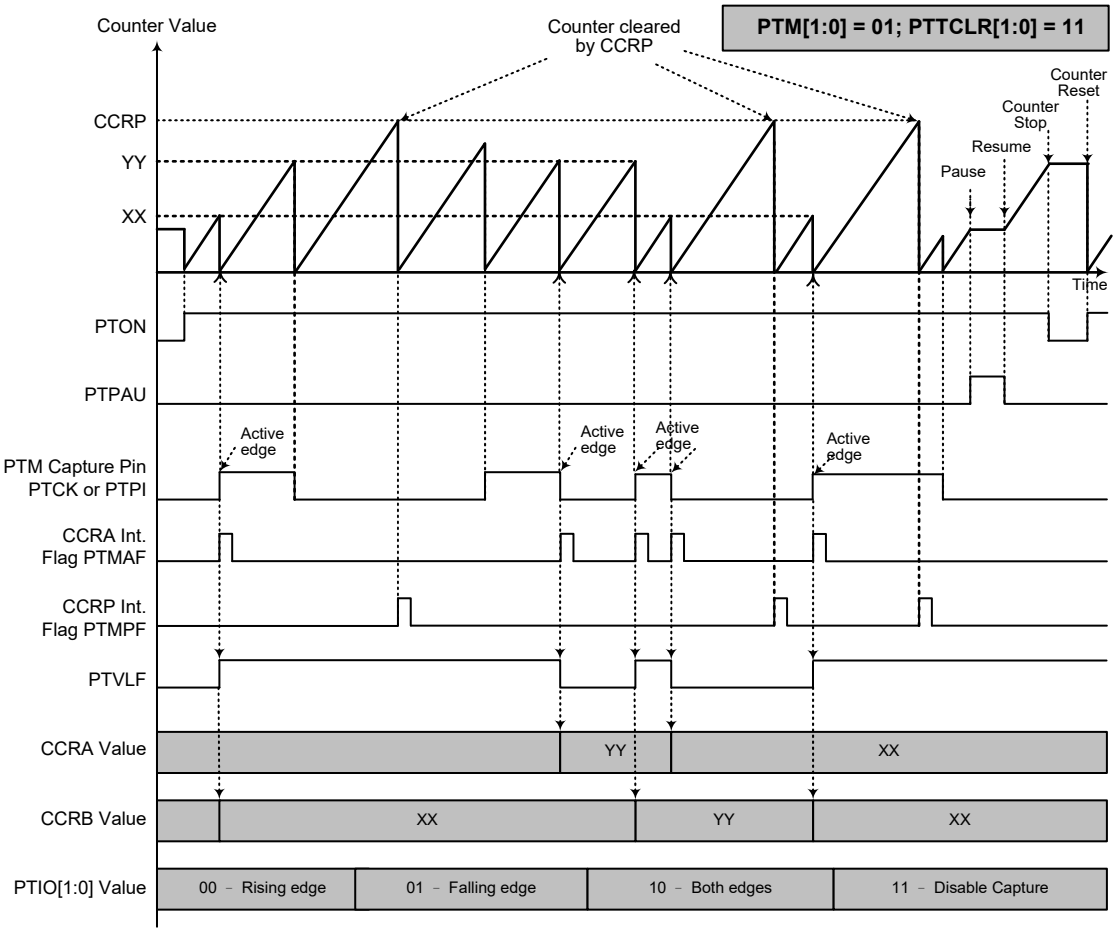
Capture Input Mode – PTTCLR[1:0]=01

Note: 1. PTM[1:0]=01, PTTCLR[1:0]=01 and active edge set by the PTIO[1:0] bits
2. A PTM Capture input pin active edge transfers the counter value to CCRA or CCRB
3. Comparator P match or PTM capture input rising edge will clear the counter
4. PTCCLR bit is not used
5. No output function – PTOC and PTPOL bits are not used
6. CCRP determines the counter value and the counter has a maximum count value when CCRP is equal to zero



Capture Input Mode – PTTCLR[1:0]=10

Note: 1. PTM[1:0]=01, PTTCLR[1:0]=10 and active edge set by the PTIO[1:0] bits
2. A PTM Capture input pin active edge transfers the counter value to CCRA or CCRB
3. Comparator P match or PTM capture input falling edge will clear the counter
4. PTCCLR bit is not used
5. No output function – PTOC and PTPOL bits are not used
6. CCRP determines the counter value and the counter has a maximum count value when CCRP is equal to zero

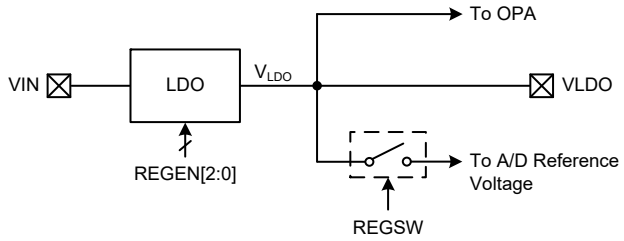


Capture Input Mode – PTTCLR[1:0]=11

Note: 1. PTM[1:0]=01, PTTCLR[1:0]=11 and active edge set by the PTIO[1:0] bits
2. A PTM Capture input pin active edge transfers the counter value to CCRA or CCRB
3. Comparator P match or PTM capture input pin rising or falling edge will clear the counter
4. PTCCLR bit is not used
5. No output function, PTOC and PTPOL bits not used
6. CCRP determines the counter value and the counter has a maximum count value when CCRP is equal to zero

Voltage Regulator – LDO

The device includes a voltage regulator, LDO. The REGC register controls the regulator module to work in five modes. In the Hi-impedance mode, the LDO will be turned off and the VLDO pin will be floating. In the bypass mode, the LDO is turned off and the V_{IN} will bypass the LDO circuit and be connected to the VLDO pin directly. In the third mode the regulator is turned on, when the input voltage is larger than 2.5V, the LDO will output a fixed voltage of 2.2V on the VLDO pin. In the fourth mode the regulator is turned on, when the input voltage is larger than 2.8V, the LDO will output a fixed voltage of 2.5V. In the fifth mode the regulator is turned on, when the input voltage is larger than 3.3V, the LDO will output a fixed voltage of 3.0V. The LDO output can be used as the OPA power supply and A/D converter reference input.



LDO Regulator Block Diagram

- **REGC Register**

Bit	7	6	5	4	3	2	1	0
Name	REGSW	—	—	—	—	REGEN2	REGEN1	REGEN0
R/W	R/W	—	—	—	—	R/W	R/W	R/W
POR	0	—	—	—	—	0	0	0

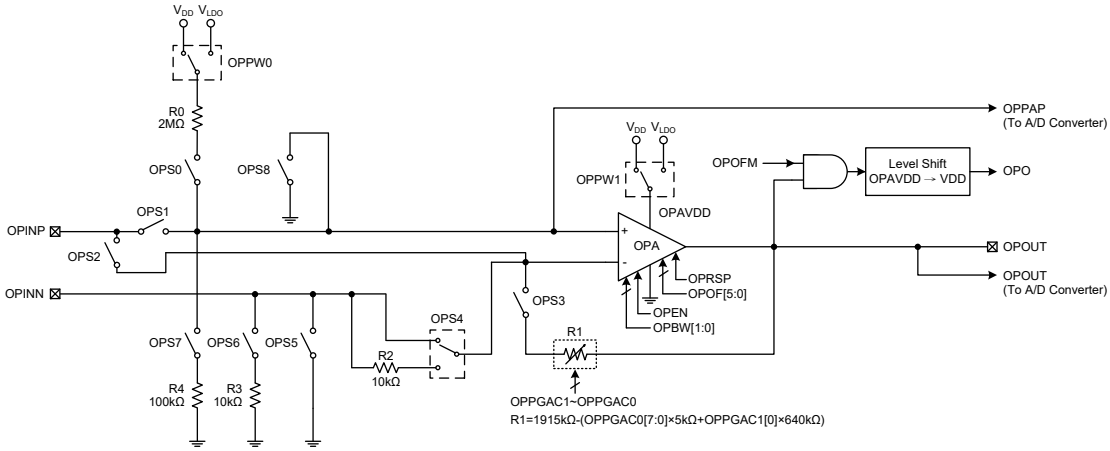
Bit 7 **REGSW**: Switch on/off control
0: Off
1: On
When the A/D converter reference voltage is selected to come from V_{LDO}, this bit should be set high. However when the A/D converter reference voltage is selected to come from any other voltage, other than V_{LDO}, this bit should be cleared to zero to turn off the switch, otherwise V_{LDO} will be connected together with other selected A/D reference voltage to the A/D converter simultaneously, which will result in unpredictable situations such as an irreversible damage.

Bit 6~3 Unimplemented, read as "0"

Bit 2~0 **REGEN2~REGEN0**: Regulator mode selection
x00: Regulator off, Hi-impedance mode, the VLDO pin is floating
x01: Regulator off, Bypass mode, $V_{LDO}=V_{IN}$
010: Regulator on, $V_{LDO}=2.2V$
011: Regulator on, $V_{LDO}=2.5V$
11x: Regulator on, $V_{LDO}=3.0V$

CO/Gas Detector AFE

The device includes a CO/Gas Detector AFE module which is mainly composed of a software configurable resistor and an Operational Amplifier, OPA. The operational amplifier can be used for signal amplification according to specific user requirements. This OPA features include enable/disable control, multiple switch and input path selections, input offset voltage calibration and four bandwidth options. In addition, the positive input and the output of the OPA can be converted using the internal A/D converter.



CO/Gas Detector AFE Block Diagram

CO/Gas Detector AFE Registers

The overall CO/Gas Detector AFE circuits are controlled by a series of registers. The OPSW0~OPSW1 registers are used to configure the paths by controlling a series of switches. The OPPW register is used to select the OPA power supply source and the input end voltage. The OPC register is used for the OPA enable/disable control, output status indication and bandwidth selection. The OPVOS register is used for OPA input offset voltage calibration control. The OPPGAC0~OPPGAC1 registers are used to setup the R1 resistance.

Register Name	Bit							
	7	6	5	4	3	2	1	0
OPSW0	OPS7	OPS6	OPS5	OPS4	OPS3	OPS2	OPS1	OPS0
OPSW1	—	—	—	—	—	—	—	OPS8
OPPW	—	—	—	—	—	—	OPPW1	OPPW0
OPC	—	OPEN	OPO	—	—	—	OPBW1	OPBW0
OPVOS	OPOFM	OPRSP	OPOF5	OPOF4	OPOF3	OPOF2	OPOF1	OPOF0
OPPGAC0	OPPGA7	OPPGA6	OPPGA5	OPPGA4	OPPGA3	OPPGA2	OPPGA1	OPPGA0
OPPGAC1	—	—	—	—	—	—	—	OPPGA8

CO/Gas Detector AFE Register List

• **OPSW0 Register**

Bit	7	6	5	4	3	2	1	0
Name	OPS7	OPS6	OPS5	OPS4	OPS3	OPS2	OPS1	OPS0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7 **OPS7**: OPS7 switch On/Off control
0: Off
1: On

Bit 6 **OPS6**: OPS6 switch On/Off control
0: Off
1: On

Bit 5 **OPS5**: OPS5 switch On/Off control
0: Off
1: On

Bit 4 **OPS4**: OPS4 switch connection selection
0: OPA negative input is connected to OPINN
1: OPA negative input is connected to R2

Bit 3 **OPS3**: OPS3 switch On/Off control.
0: Off
1: On

Bit 2 **OPS2**: OPS2 switch On/Off control
0: Off
1: On

Bit 1 **OPS1**: OPS1 switch On/Off control
0: Off
1: On

Bit 0 **OPS0**: OPS0 switch On/Off control
0: Off
1: On

• **OPSW1 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	—	OPS8
R/W	—	—	—	—	—	—	—	R/W
POR	—	—	—	—	—	—	—	0

Bit 7~1 Unimplemented, read as "0"

Bit 0 **OPS8**: OPS8 switch On/Off control
0: Off
1: On

• **OPPW Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	OPPW1	OPPW0
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as "0"

Bit 1 **OPPW1**: OPA power selection switch 1
0: V_{DD}
1: V_{LDO}

Bit 0 **OPPW0**: OPA power selection switch 0
0: V_{DD}
1: V_{LDO}

• **OPC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	OPEN	OPO	—	—	—	OPBW1	OPBW0
R/W	—	R/W	R	—	—	—	R/W	R/W
POR	—	0	0	—	—	—	0	0

Bit 7 Unimplemented, read as "0"

Bit 6 **OPEN**: OPA enable/disable control
0: Disable
1: Enable

Bit 5 **OPO**: OPA output status (positive logic)
This bit is read only.
When OPOFM=1, the OPO bit value indicates the OPA output status, refer to the "Input Offset Calibration" section. When OPOFM=0, this bit is fixed at 0.

Bit 4~2 Unimplemented, read as "0"

Bit 1~0 **OPBW1~OPBW0**: OPA bandwidth selection
00: 5kHz
01: 40kHz
10: 600kHz
11: 2MHz

When the operational amplifier is used together with the 12-bit A/D converter, its bandwidth selection and A/D converter clock frequency configuration should follow this table to ensure a correct measurement. Refer to the Operational Amplifier Electrical Characteristics for more details. In this table, "√" represents that can be used.

OPBW[1:0]	A/D Converter Clock Frequency (kHz)				
	125	250	500	1000	2000
00	× (Note)	×	×	×	×
01	√	×	×	×	×
10	√	√	√	√	√
11	√	√	√	√	√

Note: When using an electrochemical CO sensor, a 0.1μF capacitor should be connected between OPAOUT pin and GND. If without connect the capacitor, three consecutive ADC conversions will be executed, and the first two converted data are discarded and only the third converted data will be reserved.

• **OPVOS Register**

Bit	7	6	5	4	3	2	1	0
Name	OPOFM	OPRSP	OPOF5	OPOF4	OPOF3	OPOF2	OPOF1	OPOF0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	1	0	0	0	0	0

Bit 7 **OPOFM**: OPA normal operation or input offset calibration mode selection
0: Normal operation mode
1: Input offset calibration mode

Bit 6 **OPRSP**: OPA input offset voltage calibration reference selection
0: OPINN is selected as reference input
1: OPINP is selected as reference input

Bit 5~0 **OPOF5~OPOF0**: OPA input offset voltage calibration value
This bit field is used to perform the OPA input offset calibration operation and the value after the input offset calibration can be restored into this bit field. Refer to the "Input Offset Calibration" section for more detailed information.

• **OPPGAC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	OPPGA7	OPPGA6	OPPGA5	OPPGA4	OPPGA3	OPPGA2	OPPGA1	OPPGA0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~0 **OPPGA7~OPPGA0**: R1 resistance control code bit 7 ~ bit 0
R1=1915kΩ - (OPPGAC0[7:0] × 5kΩ + OPPGAC1[0] × 640kΩ)

• **OPPGAC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	—	OPPGA8
R/W	—	—	—	—	—	—	—	R/W
POR	—	—	—	—	—	—	—	0

Bit 7~1 Unimplemented, read as "0"

Bit 0 **OPPGA8**: R1 resistance control code bit 8
R1=1915kΩ - (OPPGAC0[7:0] × 5kΩ + OPPGAC1[0] × 640kΩ)

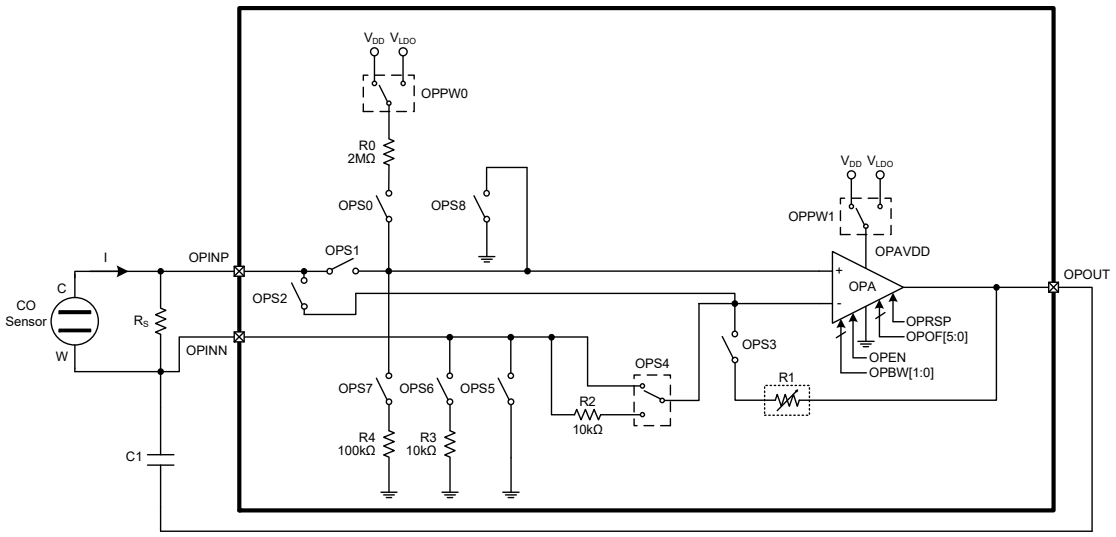
Input Offset Calibration

To operate in the input offset calibration mode, the OPA input pins to be used should first be enabled by setting the OPEN bit high.

- Step1: Set OPOFM=1, the OPA is now under offset calibration mode. To make sure V_{OS} as minimise as possible after calibration, the input reference voltage in calibration mode should be the same as input DC operating voltage in normal mode operation.
- Step2: Set OPOF[5:0]=000000, then read the OPO bit.
- Step3: Let OPOF[5:0]=OPOF[5:0] + 1 then read the OPO bit.
  If the OPO bit state is not changed, repeat Step3 until the OPO bit state is changed.
  If the OPO bit state is changed, record the current OPOF[5:0] data as V_{OS1}, then go to Step4.
- Step4: Set OPOF[5:0]=111111, then read OPO bit.
- Step5: Let OPOF[5:0]=OPOF[5:0] - 1 then read the OPO bit.
  If the OPO bit state is not changed, repeat Step5 until the OPO bit state is changed.
  If the OPO bit state is changed, record the current OPOF[5:0] data as V_{OS2}, then go to Step6.
- Step6: Restore $V_{OS}=(V_{OS1} + V_{OS2})/2$ to OPOF[5:0] bits, the calibration is finished.
  If $(V_{OS1} + V_{OS2})/2$ is not integral, discard the decimal.

CO/Gas Detector AFE Application Description

Together with proper peripheral circuits, this CO/Gas detector AFE module can be used for CO or other gas detector applications. In the application circuit below, a 100kΩ resistor (R_S) is connected to the sensor in parallel by connecting its two ends to the OPINN and OPINP pins respectively. When the sensor has detected the CO or other gases, the current will flow out of the C end. At the same time a same magnitude of current flows from the OPOUT end through the R1 resistor and then to the W end of this CO sensor. The voltage on the OPOUT pin should be equal to (V_{OPINP}+I×R1).



CO/Gas Detector Application Schematic

Analog to Digital Converter

The need to interface to real world analog signals is a common requirement for many electronic systems. However, to properly process these signals by a microcontroller, they must first be converted into digital signals by A/D converters. By integrating the A/D conversion electronic circuitry into the microcontroller, the need for external components is reduced significantly with the corresponding follow-on benefits of lower costs and reduced component space requirements.

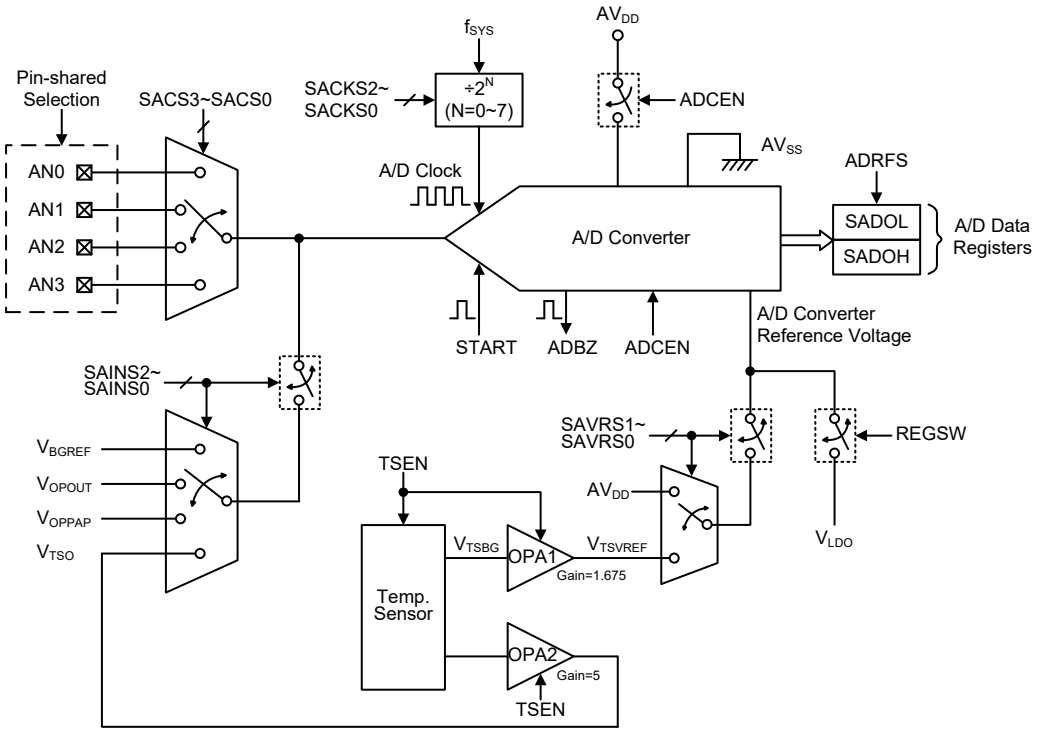
A/D Converter Overview

The device contains a multi-channel analog to digital converter which can directly interface to external analog signals, such as that from external sensors or other control signals and convert these signals directly into a 12-bit digital value. It also can convert the internal signals, such as the bandgap reference voltage or the temperature sensor output, into a 12-bit digital value. The external or internal analog signal to be converted is determined by the SAINS2~SAINS0 bits together with the SACS3~SACS0 bits. More detailed information about the A/D input signal selection is described in the "A/D Converter Control Registers" and "A/D Converter Input Signals" sections respectively.

This A/D converter also includes a temperature sensor circuitry which contains a temperature sensor, two operational amplifiers and an internal reference voltage. The temperature sensor will detect the temperature and output a voltage proportional to the temperature. The output voltage can be amplified by the OPA and then converted to a 12-bit digital data using the A/D converter.

External Input Channels	Internal Input Signals	A/D Input Select Bits
AN0~AN3	V_{BGREF}, V_{TSO}, V_{OPOUT}, V_{OPPAP}	SAINS2~SAINS0, SACS3~SACS0

The accompanying block diagram shows the overall internal structure of the A/D converter with temperature sensor together with its associated registers and control bits.



A/D Converter with Temperature Sensor Diagram

A/D Converter Register Description

Overall operation of the A/D converter with Temperature sensor is controlled using a series of registers. A read only register pair exists to store the A/D converter data 12-bit value. Two registers, SADC0 and SADC1, are control registers which setup the operating and control function of the A/D converter. The SADC2 is the temperature sensor circuitry control register. The VBGRC register is used to enable/disable the A/D converter internal bandgap reference voltage output. The remaining two registers, LMSADOH and LMSADOL, are read only registers and store a 12-bit A/D conversion result of certain temperature.

Register Name	Bit							
	7	6	5	4	3	2	1	0
SADOL (ADRFS=0)	D3	D2	D1	D0	—	—	—	—
SADOL (ADRFS=1)	D7	D6	D5	D4	D3	D2	D1	D0
SADOH (ADRFS=0)	D11	D10	D9	D8	D7	D6	D5	D4
SADOH (ADRFS=1)	—	—	—	—	D11	D10	D9	D8
SADC0	START	ADBZ	ADCEN	ADRFS	SACS3	SACS2	SACS1	SACS0
SADC1	SAINS2	SAINS1	SAINS0	SAVRS1	SAVRS0	SACKS2	SACKS1	SACKS0
SADC2	—	—	—	—	—	—	D1	TSEN
VBGRC	—	—	—	—	—	—	—	VBGREN
LMSADOH	D11	D10	D9	D8	D7	D6	D5	D4
LMSADOL	D3	D2	D1	D0	—	—	—	—

A/D Converter with Temperature Sensor Register List

A/D Converter Data Registers – SADOL, SADOH

As the internal A/D converter provides a 12-bit digital conversion value, it requires two data registers to store the converted value. These are a high byte register, known as SADOH, and a low byte register, known as SADOL. After the conversion process takes place, these registers can be directly read by the microcontroller to obtain the digitised conversion value. As only 12 bits of the 16-bit register space is utilised, the format in which the data is stored is controlled by the ADRFS bit in the SADC0 register as shown in the accompanying table. D0~D11 are the A/D conversion result data bits. Any unused bits will be read as zero. Note that the A/D converter data register contents will be unchanged if the A/D converter is disabled.

ADRFS	SADOH								SADOL							
	7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
0	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	0	0	0	0
1	0	0	0	0	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0

A/D Converter Data Registers

A/D Converter Control Registers – SADC0, SADC1, SADC2

To control the function and operation of the A/D converter, two control registers known as SADC0, SADC1 and SADC2 are provided. These 8-bit registers define functions such as the selection of which analog channel is connected to the internal A/D converter, the digitised data format, the A/D clock source as well as controlling the start function and monitoring the A/D converter busy status. As this device contains only one actual analog to digital converter hardware circuit, each of the external and internal analog signals must be routed to the converter. The SACS3~SACS0 bits in the SADC0 register are used to determine which external channel input is selected to be converted. The SAINS2~SAINS0 bits in the SADC1 register are used to determine that the analog signal to be converted comes from the internal analog signal or external analog channel input.

The relevant pin-shared function selection bits determine which pins on I/O Ports are used as analog inputs for the A/D converter input and which pins are not to be used as the A/D converter input. When the pin is selected to be an A/D input, its original function whether it is an I/O or other pin-shared function will be removed. In addition, any internal pull-high resistor connected to the pin will be automatically removed if the pin is selected to be an A/D converter input.

- **SADC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	START	ADBZ	ADCEN	ADRFS	SACS3	SACS2	SACS1	SACS0
R/W	R/W	R	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7 **START**: Start the A/D conversion
0→1→0: Start
This bit is used to initiate an A/D conversion process. The bit is normally low but if set high and then cleared low again, the A/D converter will initiate a conversion process.

Bit 6 **ADBZ**: A/D converter busy flag
0: No A/D conversion is in progress
1: A/D conversion is in progress
This read only flag is used to indicate whether the A/D conversion is in progress or not. When the START bit is set from low to high and then to low again, the ADBZ flag will be set to 1 to indicate that the A/D conversion is initiated. The ADBZ flag will be cleared to 0 after the A/D conversion is complete.

Bit 5 **ADCEN**: A/D converter function enable control
0: Disable
1: Enable
This bit controls the A/D internal function. This bit should be set to one to enable the A/D converter. If the bit is cleared to zero, then the A/D converter will be switched off reducing the device power consumption. When the A/D converter function is disabled, the contents of the A/D data register pair known as SADOH and SADOL will be unchanged.

Bit 4 **ADRFS**: A/D converter data format selection
0: A/D converter data format → SADOH=D[11:4]; SADOL=D[3:0]
1: A/D converter data format → SADOH=D[11:8]; SADOL=D[7:0]
This bit controls the format of the 12-bit converted A/D value in the two A/D data registers. Details are provided in the A/D data register section.

Bit 3~0 **SACS3~SACS0**: A/D converter external analog input channel selection
0000: AN0
0001: AN1
0010: AN2
0011: AN3
0100~1111: Undefined, input floating if selected

• SADC1 Register

Bit	7	6	5	4	3	2	1	0
Name	SAINS2	SAINS1	SAINS0	SAVRS1	SAVRS0	SACKS2	SACKS1	SACKS0
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7~5 **SAINS2~SAINS0**: A/D converter input signal selection
000: External source – External analog channel intput, ANn
001: Internal source – Internal Bandgap reference voltage, V_{BGREF}
010: Internal source – Internal Temperature Sensor output, V_{TSO}
011: Internal source – Internal OPA output, V_{OPOUT}
100: Internal source – Internal OPA positive input, V_{OPPAP}
101~110: External source – External analog channel intput, ANn
111: Forbidden data, SAINS2~SAINS0 bits cannot be written with "111"
Care must be taken if the SAINS2~SAINS0 bits are set to "001~100" to select the internal analog signal to be converted. When the internal analog signal is selected to be converted, the external input pin must never be selected as the A/D input signal by properly setting the SACS3~SACS0 bits with a value from 0100 to 1111. Otherwise, the external channel input will be connected together with the internal analog signal. This will result in unpredictable situations such as an irreversible damage.

Bit 4~3 **SAVRS1~SAVRS0**: A/D converter reference voltage selection
00: LDO output voltage, V_{LDO}
01: Internal A/D converter power, AV_{DD}
10: Internal Temperature Sensor reference voltage, V_{TSVREF}
11: Internal A/D converter power, AV_{DD}
These bits are used to select the A/D converter reference voltage source. Care must be taken if the SAVRS1~SAVRS0 bits are set to "01~11" to select the internal A/D converter power or Temperature Sensor reference voltage as the reference voltage source. When the internal A/D converter power or Temperature Sensor reference voltage is selected as the reference voltage, the LDO output path to the A/D converter reference voltage must be switched off by clearing the REGSW bit in the REGC register. Otherwise, the LDO output voltage together with the selected internal reference voltage will be simultaneously connected to the A/D converter reference voltage input. This will result in unpredictable situations. Refer to the "A/D Converter Reference Voltage" section for more details.

Bit 2~0 **SACKS2~SACKS0**: A/D converter clock rate selection
000: f_{SYS}
001: $f_{SYS}/2$
010: $f_{SYS}/4$
011: $f_{SYS}/8$
100: $f_{SYS}/16$
101: $f_{SYS}/32$
110: $f_{SYS}/64$
111: $f_{SYS}/128$
These bits are used to select the clock source for the A/D converter. If the internal OPA signal is selected to be converted, care must be taken for the A/D clock rate selection limitation. Refer to the OPC Register description in the CO/Gas Detector AFE section for details.

Bandgap Referenc Voltage Control Register – VBGRC

A high performance bandgap voltage reference is included in the device. It has an accurate voltage reference output, V_{BGREF}, when input supply voltage change or temperature variation. The VBGRC register is used to control the bandgap reference voltage circuit enable or disable.

- **VBGRC Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	—	VBGREN
R/W	—	—	—	—	—	—	—	R/W
POR	—	—	—	—	—	—	—	0

Bit 7~1 Unimplemented, read as "0"

Bit 0 **VBGREN**: Bandgap enable control
0: Disable
1: Enable
This bit is used to enable/disable the internal Bandgap reference circuit. The internal Bandgap reference circuit should first be enabled before the V_{BGREF} voltage is selected to be used. When this bit is cleared to 0, the Bandgap voltage output V_{BGREF} is in a high impedance state.

Temperature Sensor Control Register – SADC2

To control the enable and disable of the integrated temperature sensor circuitry, a control register known as SADC2 is provided.

- **SADC2 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	D1	TSEN
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	1	0

Bit 7~2 Unimplemented, read as "0"

Bit 1 **D1**: Reserved bit, should be fixed at "1"

Bit 0 **TSEN**: Temperature sensor circuitry enable control
0: Disable
1: Enable
This bit controls the internal temperature sensor circuitry. If the temperature sensor output will be converted or the temperature sensor reference voltage will be selected as the A/D conversion reference voltage, the temperature sensor circuitry should be turned on by setting the TSEN bit high first. When the temperature sensor is enabled by setting the TSEN bit to 1, a time named as t_{TSS} should be allowed for the temperature sensor circuit to stabilise before implementing relevant temperature sensor operation.

85°C A/D Conversion Value Registers – LMSADOH, LMSADOL

A pair of read-only registers, LMSADOH and LMSADOL, are provided to store the 12-bit A/D converted value of 85°C temperature.

Register	LMSADOH								LMSADOL							
Bit	7	6	5	4	3	2	1	0	7	6	5	4	3	2	1	0
Name	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	—	—	—	—
R/W	R	R	R	R	R	R	R	R	R	R	R	R	—	—	—	—
POR	85°C A/D Converted Value												—	—	—	—

"—": Unimplemented, read as "0"

85°C A/D Conversion Value Registers

A/D Converter Operation

The START bit in the SADC0 register is used to start the A/D conversion. When the microcontroller sets this bit from low to high and then low again, an analog to digital conversion cycle will be initiated.

The ADBZ bit in the SADC0 register is used to indicate whether the analog to digital conversion process is in progress or not. This bit will be automatically set to 1 by the microcontroller after an A/D conversion is successfully initiated. When the A/D conversion is complete, the ADBZ will be cleared to 0. In addition, the corresponding A/D interrupt request flag will be set in the interrupt control register, and if the interrupts are enabled, an appropriate internal interrupt signal will be generated. This A/D internal interrupt signal will direct the program flow to the associated A/D internal interrupt address for processing. If the A/D internal interrupt is disabled, the microcontroller can poll the ADBZ bit in the SADC0 register to check whether it has been cleared as an alternative method of detecting the end of an A/D conversion cycle.

The clock source for the A/D converter, which originates from the system clock f_{SYS}, can be chosen to be either f_{SYS} or a subdivided version of f_{SYS}. The division ratio value is determined by the SACKS2~SACKS0 bits in the SADC1 register. Although the A/D clock source is determined by the system clock f_{SYS} and by bits SACKS2~SACKS0, there are some limitations on the maximum A/D clock source speed that can be selected. As the recommended range of permissible A/D clock period, t_{ADCK}, is from 0.5μs to 10μs, care must be taken for system clock frequencies. For example, as the system clock operates at a frequency of 8MHz, the SACKS2~SACKS0 bits should not be set to 000, 001 or 111. Doing so will give A/D clock periods that are less than the minimum A/D clock period or greater than the maximum A/D clock period which may result in inaccurate A/D conversion values. Refer to the following table for examples, where values marked with an asterisk * show where, special care must be taken, as the values may exceed the specified minimum A/D Clock Period range.

However, the permissible A/D clock period is from 1μs to 2μs if the input signal to be converted is the temperature sensor output voltage.

f_{SYS}	A/D Clock Period (t_{ADCK})							
	SACKS[2:0] =000 (f_{SYS})	SACKS[2:0] =001 ($f_{SYS}/2$)	SACKS[2:0] =010 ($f_{SYS}/4$)	SACKS[2:0] =011 ($f_{SYS}/8$)	SACKS[2:0] =100 ($f_{SYS}/16$)	SACKS[2:0] =101 ($f_{SYS}/32$)	SACKS[2:0] =110 ($f_{SYS}/64$)	SACKS[2:0] =111 ($f_{SYS}/128$)
1MHz	1μs	2μs	4μs	8μs	16μs *	32μs *	64μs *	128μs *
2MHz	500ns	1μs	2μs	4μs	8μs	16μs *	32μs *	64μs *
4MHz	250ns *	500ns	1μs	2μs	4μs	8μs	16μs *	32μs *
8MHz	125ns *	250ns *	500ns	1μs	2μs	4μs	8μs	16μs *

A/D Clock Period Examples for External Analog Inputs

Controlling the power on/off function of the A/D converter circuitry is implemented using the ADCEN bit in the SADC0 register. This bit must be set high to power on the A/D converter. When the ADCEN bit is set high to power on the A/D converter internal circuitry a certain delay, as indicated in the timing diagram, must be allowed before an A/D conversion is initiated. Even if no pins are selected for use as A/D inputs, if the ADCEN bit is high, then some power will still be consumed. In power conscious applications it is therefore recommended that the ADCEN is set low to reduce power consumption when the A/D converter function is not being used.

A/D Converter Reference Voltage

The actual reference voltage supply to the A/D Converter can be supplied from the LDO output, or from the A/D converter power supply, $AV_{DD,}$ or from the temperature sensor reference voltage, V_{TSVREF}. The choice is made using the SAVRS1 and SAVRS0 bits in the SADC1 register together with other control bits.

If the LDO output is required to use, firstly the SAVRS bit field should be set to "00". Then set the REGEN[2:0] bits in the REGC register to select the required LDO voltage as A/D reference voltage and set the REGSW bit high to switch on the LDO output path to the A/D converter reference voltage.

If the A/D converter power supply, AV_{DD} is required to use, the SAVRS bit field should be set to "01" or "11". If the temperature sensor reference voltage is required to use, the SAVRS bit field should be set to "10". As the temperature sensor circuitry is controlled by the TSEN bit, the TSEN bit should be set high to enable the temperature sensor. However, it is important to note that even when the AV_{DD} or V_{TSVREF} has been selected as the A/D converter reference voltage by correctly setting the SAVRS bit field, the LDO output path to the A/D converter reference voltage must be switched off by properly configuring the REGSW bit. Otherwise these signals may be input to the A/D converter reference simultaneously, which will result in unpredictable situations such as an irreversible damage.

SAVRS[1:0]	Other Relevant Bits	Reference Source	Description
00	REGSW=1 REGEN[2:0]=010/011/11x	V_{LDO}	LDO output voltage
01, 11	REGSW=0	AV_{DD}	Internal A/D converter power supply
10	TSEN=1, REGSW=0	V_{TSVREF}	Internal Temperature Sensor reference voltage

A/D Converter Reference Voltage Selection

A/D Converter Input Signals

All of the external A/D analog input pins are pin-shared with the I/O pins as well as other functions. The corresponding pin-shared function selection bits in the PAS0 register determine whether the external input pins are setup as A/D converter analog channel inputs or whether they have other functions. If the corresponding pin is setup to be an A/D converter analog channel input, the original pin functions will be disabled. In this way, pins can be changed under program control to change their function between A/D inputs and other functions. All pull-high resistors, which are setup through register programming, will be automatically disconnected if the pins are setup as A/D inputs. Note that it is not necessary to first setup the A/D pin as an input in the port control register to enable the A/D input as when the pin-shared function control bits enable an A/D input, the status of the port control register will be overridden.

There are four internal analog signals derived from the V_{BGREF}, V_{TSO}, V_{OPOUT} or V_{OPPAP}, which can be connected to the A/D converter as the analog input signal by configuring the SAINS2~SAINS0 bits. If the SAINS2~SAINS0 bits are set to "000" or "101~110", the external analog channel input is selected to be converted and the SACS3~SACS0 bits can determine which external channel is selected to be converted. If the SAINS2~SAINS0 bits are set to "001~100", one of the internal

signals is selected to be converted. Care must be taken when the internal analog signal is selected to be converted. If the internal analog signal is selected to be converted, the selected external input determined by the SACS3~SACS0 bits must be configured to a floating state by properly setting the SACS3~SACS0 bits to a value from "0100~1111". Otherwise, the external channel input will be connected together with the internal analog signal. This will result in unpredictable situations such as an irreversible damage.

Note that the analog input values must not be allowed to exceed the value of the selected A/D reference voltage.

SAINS[2:0]	SACS[3:0]	Input Signals	Description
000, 101~110	0000~0011	AN0~AN3	External channel analog input
	0100~1111	—	Floating, no channel is selected
001	0100~1111	V_{BGREF}	Internal Bandgap reference voltage
010	0100~1111	V_{TSO}	Internal Temperature Sensor output voltage
011	0100~1111	V_{OPOUT}	Internal OPA output voltage
100	0100~1111	V_{OPPAP}	Internal OPA positive input voltage
111	Forbidden data, SAINS2~SAINS0 bits cannot be written with "111"		

A/D Converter Input Signal Selection

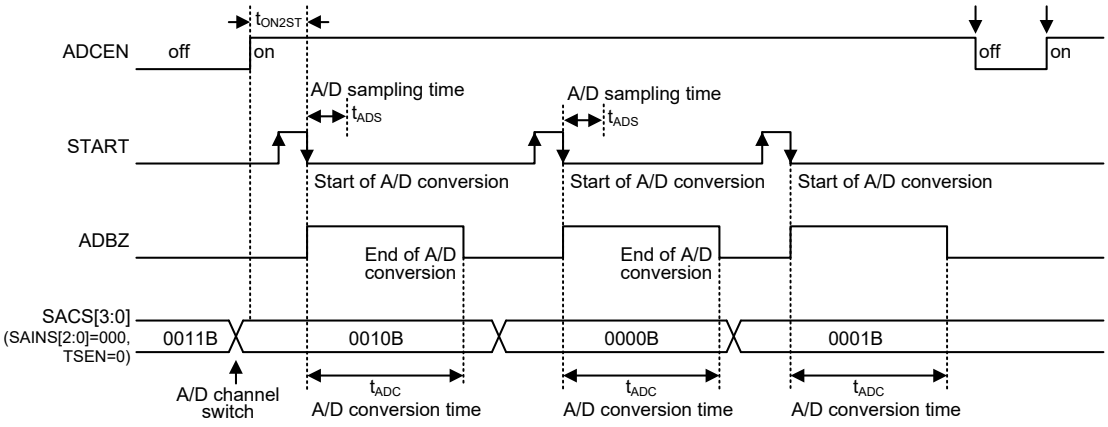
Conversion Rate and Timing Diagram

A complete A/D conversion contains two phases, data sampling and data conversion. If the conversion input signal is not the temperature sensor output, the data sampling which is defined as t_{ADS} takes 4 A/D clock cycles and the data conversion takes 12 A/D clock cycles. Therefore, a total of 16 A/D clock cycles for an A/D conversion which is defined as t_{ADC} are necessary. However, an A/D conversion for an internal temperature sensor signal will take a total of 58 A/D clock cycles, which includes 46 A/D clock cycles for data sampling and 12 A/D clock cycles for data conversion.

Maximum single A/D conversion rate=A/D clock period/16 (Temperature sensor output is not used)

Maximum single A/D conversion rate=A/D clock period/58 (Temperature sensor output is used)

The accompanying diagram shows graphically the various stages involved in an external channel input signal analog to digital conversion process and its associated timing. After an A/D conversion process has been initiated by the application program, the microcontroller internal hardware will begin to carry out the conversion, during which time the program can continue with other functions. The time taken for the A/D conversion is 16 t_{ADCK} clock cycles where t_{ADCK} is equal to the A/D clock period.



A/D Conversion Timing – External Channel Input

Summary of A/D Conversion Steps

The following summarises the individual steps that should be executed in order to implement an A/D conversion process.

- Step 1
  Select the required A/D conversion clock by correctly programming bits SACKS2~SACKS0 in the SADC1 register.
- Step 2
  Enable the A/D by setting the ADCEN bit in the SADC0 register to 1.
- Step 3
  Select which signal is to be connected to the internal A/D converter by correctly configuring the SAINS2~SAINS0 and SACS3~SACS0 bits.
  Select the external channel input to be converted, go to Step 4.
  Select the internal analog signal to be converted, go to Step 5.
- Step 4
  If the A/D input signal comes from the external channel input selected by configuring the SAINS2~SAINS0 bits, the corresponding pins should be configured as A/D input function by configuring the relevant pin-shared function control bits. The desired analog channel then should be selected by configuring the SACS3~SACS0 bits. After this step, go to Step 6.
- Step 5
  Before the A/D input signal is selected to come from the internal analog signal by configuring the SAINS2~SAINS0 bits, the corresponding external input pin must be switched to a non-existed channel input by properly configured the SACS3~SACS0 bits. The desired internal analog signal then can be selected by configuring the SAINS2~SAINS0 bits. After this step, go to Step 6.
- Step 6
  Select the reference voltage source by configuring the SAVRS1~SAVRS0 bits in the SADC1 register. Care should be taken in this step which can refer to the A/D Converter Reference Voltage section for details.
- Step 7
  Select A/D converter output data format by setting the ADRFS bit in the SADC0 register.
- Step 8
  If A/D conversion interrupt is used, the interrupt control registers must be correctly configured to ensure the A/D interrupt function is active. The master interrupt control bit, EMI, and the A/D conversion interrupt control bit, ADE, must both be set high in advance.
- Step 9
  The A/D conversion procedure can now be initialised by setting the START bit from low to high and then low again.
- Step 10
  If A/D conversion is in progress, the ADBZ flag will be set high. After the A/D conversion process is complete, the ADBZ flag will go low and then the output data can be read from SADOH and SADOL registers.

Note: When checking for the end of the conversion process, if the method of polling the ADBZ bit in the SADC0 register is used, the interrupt enable step above can be omitted.

Programming Considerations

During microcontroller operations where the A/D converter is not being used, the A/D internal circuitry can be switched off to reduce power consumption, by clearing bit ADCEN to 0 in the

SADC0 register. When this happens, the internal A/D converter circuits will not consume power irrespective of what analog voltage is applied to their input lines. If the A/D converter input lines are used as normal I/O pins, then care must be taken as if the input voltage is not at a valid logic level, then this may lead to some increase in power consumption.

A/D Conversion Function

As the device contains a 12-bit A/D converter, its full-scale converted digitised value is equal to FFFH. Since the full-scale analog input value is equal to the actual A/D converter reference voltage, V_{REF}, this gives a single bit analog input value of V_{REF} divided by 4096.

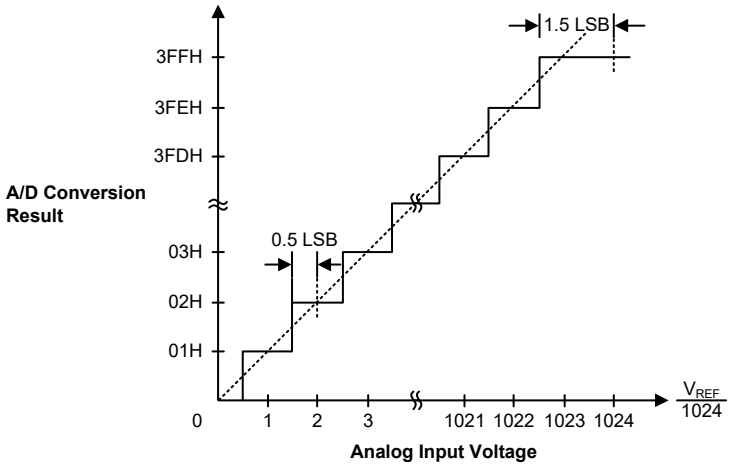
$$1\ LSB=V_{REF} / 4096$$

The A/D Converter input voltage value can be calculated using the following equation:

$$A/D\ input\ voltage=A/D\ output\ digital\ value \times (V_{REF} / 4096)$$

The diagram shows the ideal transfer function between the analog input value and the digitised output value for the A/D converter. Except for the digitised zero value, the subsequent digitised values will change at a point 0.5 LSB below where they would change without the offset, and the last full scale digitised value will change at a point 1.5 LSB below the V_{REF} level.

Note that here the V_{REF} voltage is the actual A/D converter reference voltage determined by the SAVRS1~SAVRS0 bits.



Ideal A/D Transfer Function

Temperature Measurement Function

As the temperature sensor output voltage, V_{TSO}, has a linear relationship with temperature, the V_{TSO} A/D converted data value will also have a linear relationship with temperature. The current temperature Tx can be proportionally calculated from its A/D converted value ADCx using the following formula.

$$Tx\ (°C)=slope \times (ADCx - ADC2) + T2$$

As the device has provided two sets of values which are (ADC1, T1) and (ADC2, T2). The T1 and T2 are two values of temperature and the ADC1 and ADC2 are their A/D converted values respectively. The slope can be calculated using the following formula.

$$slope=(T1 - T2) / (ADC1 - ADC2)$$

For the device, the T1 has a fixed value of 85°C. The ADC1 can be read from the LMSADOH and LMSADOL registers. The ADC2 and T2 code are stored in the Option Memory and can be read

from the Program Memory last page using the table read instructions when the Option Memory mapping function is enabled.

Name	Mapped Address in Program Memory	Description
T1	—	A fixed value of 85°C
ADC1	—	12-bit T1 A/D converted value in LMSADOH & LMSADOL registers
T2	3F5H	T2 code (00H (0°C) ~ FFH (51°C)) Temperature value can be converted from the code with 0.2°C/step
ADC2	3F6H	12-bit T2 A/D converted value bit 11~bit 4
	3F7H	12-bit T2 A/D converted value bit 3~bit 0

Temperature Measurement Reference Items

The Option Memory mapping function is enabled by using the ORMC register. For more details, refer to the "Option Memory Mapping Register – ORMC" in the Special Function Register Description section.

A/D Conversion Programming Examples

The following two programming examples illustrate how to setup and implement an A/D conversion. In the first example, the method of polling the ADBZ bit in the SADC0 register is used to detect when the conversion cycle is complete, whereas in the second example, the A/D interrupt is used to determine when the conversion is complete.

Example: using an ADBZ polling method to detect the end of conversion

```
clr ADE                ; disable ADC interrupt
clr TSEN               ; disable temperature sensor circuitry
mov a,0Bh              ; select fSYS/8 as A/D clock, external channel as A/D input signal
mov SADC1,a            ; and A/D internal power as reference voltage
mov a,20h              ; setup PAS0 register to configure pin AN0
mov PAS0,a
mov a,20h
mov SADC0,a            ; enable and connect AN0 channel to A/D converter
:
start_conversion:
clr START              ; high pulse on start bit to initiate conversion
set START              ; reset A/D
clr START              ; start A/D
polling_EOC:
sz  ADBZ               ; poll the SADC0 register ADBZ bit to detect end of A/D conversion
jmp polling_EOC        ; continue polling
mov a,SADOL            ; read low byte conversion result value
mov SADOL_buffer,a     ; save result to user defined register
mov a,SADOH            ; read high byte conversion result value
mov SADOH_buffer,a     ; save result to user defined register
:
:
jmp start_conversion   ; start next A/D conversion
```

Example: using the interrupt method to detect the end of conversion

```
clr ADE                ; disable ADC interrupt
clr TSEN               ; disable temperature sensor circuitry
mov a,0Bh              ; select fSYS/8 as A/D clock, external channel as A/D input signal
mov SADC1,a            ; and A/D internal power as reference voltage
mov a,20h              ; setup PAS0 register to configure pin AN0
mov PAS0,a
```

```
mov a,20h
mov SADC0,a           ; enable and connect AN0 channel to A/D converter
:
start_conversion:
clr START             ; high pulse on START bit to initiate conversion
set START             ; reset A/D
clr START             ; start A/D
clr ADF               ; clear ADC interrupt request flag
set ADE               ; enable ADC interrupt
set EMI               ; enable global interrupt
:
:
; ADC interrupt service routine
ADC_ISR:
mov acc_stack,a       ; save ACC to user defined memory
mov a,STATUS
mov status_stack,a    ; save STATUS to user defined memory
:
:
mov a,SADOL           ; read low byte conversion result value
mov SADOL_buffer,a    ; save result to user defined register
mov a,SADOH           ; read high byte conversion result value
mov SADOH_buffer,a    ; save result to user defined register
:
:
EXIT_INT_ISR:
mov a,status_stack
mov STATUS,a          ; restore STATUS from user defined memory
mov a,acc_stack       ; restore ACC from user defined memory
reti
```

Interrupts

Interrupts are an important part of any microcontroller system. When an external event or an internal function such as a Timer Module or an A/D converter requires microcontroller attention, their corresponding interrupt will enforce a temporary suspension of the main program allowing the microcontroller to direct attention to their respective needs. The device contains one external interrupt and several internal interrupts functions. The external interrupt is generated by the action of the external INT pin, while the internal interrupts are generated by various internal functions such as Timer Module, Time Bases and the A/D converter.

Interrupt Registers

Overall interrupt control, which basically means the setting of request flags when certain microcontroller conditions occur and the setting of interrupt enable bits by the application program, is controlled by a series of registers, located in the Special Purpose Data Memory, as shown in the accompanying table. The registers fall into two categories. The first is the INTC0~INTC1 registers which setup the primary interrupts, the second is the INTEG register which setups the external interrupt trigger edge type.

Each register contains a number of enable bits to enable or disable individual registers as well as interrupt flags to indicate the presence of an interrupt request. The naming convention of these follows a specific pattern. First is listed an abbreviated interrupt type, then the (optional) number of that interrupt followed by either an “E” for enable/disable bit or “F” for request flag.

Function	Enable Bit	Request Flag	Notes
Global	EMI	—	—
INT Pin	INTE	INTF	—
A/D Converter	ADE	ADF	—
EEPROM	DEE	DEF	—
PTM	PTMPE	PTMPF	—
	PTMAE	PTMAF	
Time Bases	TBnE	TBnF	n=0~1

Interrupt Register Bit Naming Conventions

Register Name	Bit							
	7	6	5	4	3	2	1	0
INTEG	—	—	—	—	—	—	INTS1	INTS0
INTC0	—	DEF	ADF	INTF	DEE	ADE	INTE	EMI
INTC1	TB1F	TB0F	PTMAF	PTMPF	TB1E	TB0E	PTMAE	PTMPE

Interrupt Register List

- **INTEG Register**

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	INTS1	INTS0
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as "0"

Bit 1~0 **INTS1~INTS0**: Interrupt edge control for INT pin
00: Disable
01: Rising edge
10: Falling edge
11: Both rising and falling edges

- **INTC0 Register**

Bit	7	6	5	4	3	2	1	0
Name	—	DEF	ADF	INTF	DEE	ADE	INTE	EMI
R/W	—	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	—	0	0	0	0	0	0	0

Bit 7 Unimplemented, read as "0"

Bit 6 **DEF**: Data EEPROM interrupt request flag
0: No request
1: Interrupt request

Bit 5 **ADF**: A/D Converter interrupt request flag
0: No request
1: Interrupt request

Bit 4 **INTF**: External interrupt request flag
0: No request
1: Interrupt request

Bit 3 **DEE**: Data EEPROM interrupt control
0: Disable
1: Enable

Bit 2 **ADE**: A/D Converter interrupt control
0: Disable
1: Enable

Bit 1 **INTE**: External interrupt control
0: Disable
1: Enable

Bit 0 **EMI**: Global interrupt control
0: Disable
1: Enable

• **INTC1 Register**

Bit	7	6	5	4	3	2	1	0
Name	TB1F	TB0F	PTMAF	PTMPF	TB1E	TB0E	PTMAE	PTMPE
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR	0	0	0	0	0	0	0	0

Bit 7 **TB1F**: Time Base 1 interrupt request flag
0: No request
1: Interrupt request

Bit 6 **TB0F**: Time Base 0 interrupt request flag
0: No request
1: Interrupt request

Bit 5 **PTMAF**: PTM Comparator A match interrupt request flag
0: No request
1: Interrupt request

Bit 4 **PTMPF**: PTM Comparator P match interrupt request flag
0: No request
1: Interrupt request

Bit 3 **TB1E**: Time Base 1 interrupt control
0: Disable
1: Enable

Bit 2 **TB0E**: Time Base 0 interrupt control
0: Disable
1: Enable

Bit 1 **PTMAE**: PTM Comparator A match interrupt control
0: Disable
1: Enable

Bit 0 **PTMPE**: PTM Comparator P match interrupt control
0: Disable
1: Enable

Interrupt Operation

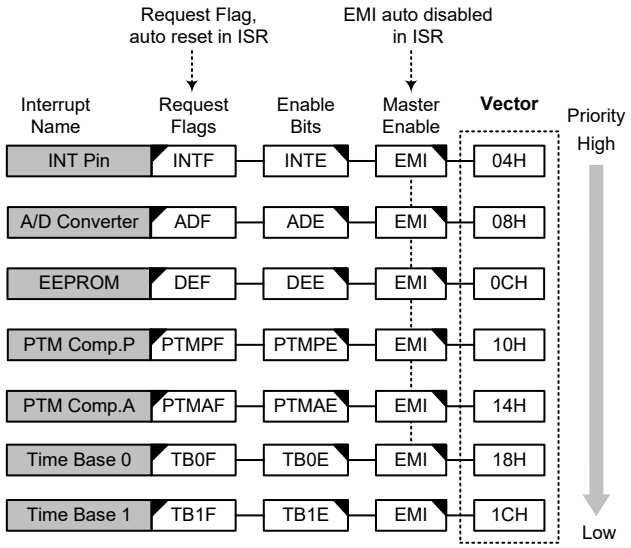
When the conditions for an interrupt event occur, such as a Timer Module compare match or A/D conversion completion etc., the relevant interrupt request flag will be set. Whether the request flag actually generates a program jump to the relevant interrupt vector is determined by the condition of the interrupt enable bit. If the enable bit is set high then the program will jump to its relevant vector, if the enable bit is zero then although the interrupt request flag is set an actual interrupt will not be generated and the program will not jump to the relevant interrupt vector. The global interrupt enable bit, if cleared to zero, will disable all interrupts.

When an interrupt is generated, the Program Counter, which stores the address of the next instruction to be executed, will be transferred onto the stack. The Program Counter will then be loaded with a new address which will be the value of the corresponding interrupt vector. The microcontroller will

then fetch its next instruction from this interrupt vector. The instruction at this vector will usually be a "JMP" which will jump to another section of program which is known as the interrupt service routine. Here is located the code to control the appropriate interrupt. The interrupt service routine must be terminated with an "RETI", which retrieves the original Program Counter address from the stack and allows the microcontroller to continue with normal execution at the point where the interrupt occurred.

The various interrupt enable bits, together with their associated request flags, are shown in the Accompanying diagrams with their order of priority. All interrupt sources have their own individual vector. Once an interrupt subroutine is serviced, all the other interrupts will be blocked, as the global interrupt enable bit, EMI bit will be cleared automatically. This will prevent any further interrupt nesting from occurring. However, if other interrupt requests occur during this interval, although the interrupt will not be immediately serviced, the request flag will still be recorded.

If an interrupt requires immediate servicing while the program is already in another interrupt service routine, the EMI bit should be set after entering the routine, to allow interrupt nesting. If the stack is full, the interrupt request will not be acknowledged, even if the related interrupt is enabled, until the Stack Pointer is decremented. If immediate service is desired, the stack must be prevented from becoming full. In case of simultaneous requests, the accompanying diagram shows the priority that is applied. All of the interrupt request flags when set will wake-up the device if it is in SLEEP or IDLE Mode, however to prevent a wake-up from occurring the corresponding flag should be set before the device is in SLEEP or IDLE Mode.



Interrupt Structure

External Interrupt

The external interrupt is controlled by signal transitions on the INT pin. An external interrupt request will take place when the external interrupt request flag, INTF, is set, which will occur when a transition, whose type is chosen by the edge select bits, appears on the external interrupt pin. To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, and respective external interrupt enable bit, INTE, must first be set. Additionally the correct interrupt edge type must be selected using the related register to enable the external interrupt function and to choose the trigger edge type. As the external interrupt pins are pin-shared with I/O pins, they can only be configured as external interrupt pins if their external interrupt enable bit in

the corresponding interrupt register has been set. The pin must also be setup as an input by setting the corresponding bit in the port control register. When the interrupt is enabled, the stack is not full and the correct transition type appears on the external interrupt pin, a subroutine call to the external interrupt vector, will take place. When the interrupt is serviced, the external interrupt request flag, INTF, will be automatically reset and the EMI bit will be automatically cleared to disable other interrupts. Note that any pull-high resistor selections on the external interrupt pin will remain valid even if the pin is used as an external interrupt input.

The INTEG register is used to select the type of active edge that will trigger the external interrupt. A choice of either rising or falling or both edge types can be chosen to trigger an external interrupt. Note that the INTEG register can also be used to disable the external interrupt function.

A/D Converter Interrupt

The A/D Converter Interrupt is controlled by the termination of an A/D conversion process. An A/D Converter Interrupt request will take place when the A/D Converter Interrupt request flag, ADF, is set, which occurs when the A/D conversion process finishes. To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, and A/D Interrupt enable bit, ADE, must first be set. When the interrupt is enabled, the stack is not full and the A/D conversion process has ended, a subroutine call to the A/D Interrupt vector, will take place. When the A/D Converter Interrupt is serviced, the A/D Interrupt flag, ADF, will be automatically cleared. The EMI bit will also be automatically cleared to disable other interrupts.

EEPROM Interrupt

An EEPROM Interrupt request will take place when the EEPROM Interrupt request flag, DEF, is set, which occurs when an EEPROM Write cycle ends. To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, and the EEPROM Interrupt enable bit, DEE, must first be set. When the interrupt is enabled, the stack is not full and an EEPROM Write cycle ends, a subroutine call to the EEPROM Interrupt vector will take place. When the EEPROM Interrupt is serviced, the interrupt request flag, DEF, will be automatically reset and the EMI bit will be cleared to disable other interrupts.

Timer Module Interrupts

The Periodic type TM has two interrupts, one comes from the comparator A match situation and the other comes from the comparator P match situation. There are two interrupt request flags, PTMPF and PTMAF, and two enable control bits, PTMPE and PTMAE. A TM interrupt request will take place when any of the TM request flags are set, a situation which occurs when a TM comparator P or A match situation happens.

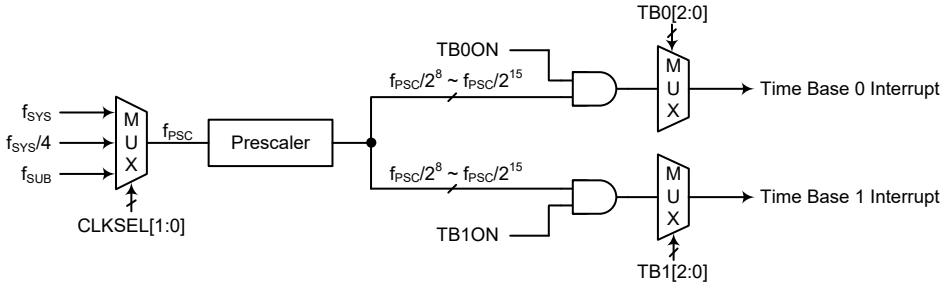
To allow the program to branch to its respective interrupt vector address, the global interrupt enable bit, EMI, and respective TM Interrupt enable bit, must first be set. When the interrupt is enabled, the stack is not full and a TM comparator match situation occurs, a subroutine call to the relevant interrupt vector locations, will take place. When the TM interrupt is serviced, the TM interrupt request flags will be automatically cleared, the EMI bit will also be automatically cleared to disable other interrupts.

Time Base Interrupts

The function of the Time Base Interrupts is to provide regular time signal in the form of an internal interrupt. They are controlled by the overflow signals from their respective timer functions. When these happens their respective interrupt request flags, TB0F or TB1F will be set. To allow the program to branch to their respective interrupt vector addresses, the global interrupt enable bit, EMI

and Time Base enable bits, TB0E or TB1E, must first be set. When the interrupt is enabled, the stack is not full and the Time Base overflows, a subroutine call to their respective vector locations will take place. When the interrupt is serviced, the respective interrupt request flag, TB0F or TB1F, will be automatically reset and the EMI bit will be cleared to disable other interrupts.

The purpose of the Time Base Interrupt is to provide an interrupt signal at fixed time periods. Its clock source, f_{PSC}, originates from the internal clock source f_{SYS}, $f_{SYS}/4$ or f_{SUB} and then passes through a divider, the division ratio of which is selected by programming the appropriate bits in the TB0C and TB1C registers to obtain longer interrupt periods whose value ranges. The clock source which in turn controls the Time Base interrupt period is selected using the CLKSEL1~CLKSEL0 bits in the PSCR register.



Time Base Interrupts

• PSCR Register

Bit	7	6	5	4	3	2	1	0
Name	—	—	—	—	—	—	CLKSEL1	CLKSEL0
R/W	—	—	—	—	—	—	R/W	R/W
POR	—	—	—	—	—	—	0	0

Bit 7~2 Unimplemented, read as "0"

Bit 1~0 **CLKSEL1~CLKSEL0**: Prescaler clock source selection
00: f_{SYS}
01: $f_{SYS}/4$
1x: f_{SUB}

• TB0C Register

Bit	7	6	5	4	3	2	1	0
Name	TB0ON	—	—	—	—	TB02	TB01	TB00
R/W	R/W	—	—	—	—	R/W	R/W	R/W
POR	0	—	—	—	—	0	0	0

Bit 7 **TB0ON**: Time Base 0 Control
0: Disable
1: Enable

Bit 6~3 Unimplemented, read as "0"

Bit 2~0 **TB02~TB00**: Select Time Base 0 Time-out Period
000: $2^8/f_{PSC}$
001: $2^9/f_{PSC}$
010: $2^{10}/f_{PSC}$
011: $2^{11}/f_{PSC}$
100: $2^{12}/f_{PSC}$
101: $2^{13}/f_{PSC}$
110: $2^{14}/f_{PSC}$
111: $2^{15}/f_{PSC}$

• **TB1C Register**

Bit	7	6	5	4	3	2	1	0
Name	TB1ON	—	—	—	—	TB12	TB11	TB10
R/W	R/W	—	—	—	—	R/W	R/W	R/W
POR	0	—	—	—	—	0	0	0

Bit 7 **TB1ON**: Time Base 1 Control
0: Disable
1: Enable

Bit 6~3 Unimplemented, read as "0"

Bit 2~0 **TB12~TB10**: Select Time Base 1 Time-out Period
000: $2^8/f_{PSC}$
001: $2^9/f_{PSC}$
010: $2^{10}/f_{PSC}$
011: $2^{11}/f_{PSC}$
100: $2^{12}/f_{PSC}$
101: $2^{13}/f_{PSC}$
110: $2^{14}/f_{PSC}$
111: $2^{15}/f_{PSC}$

Interrupt Wake-up Function

Each of the interrupt functions has the capability of waking up the microcontroller when in the SLEEP or IDLE Mode. A wake-up is generated when an interrupt request flag changes from low to high and is independent of whether the interrupt is enabled or not. Therefore, even though the device is in the SLEEP or IDLE Mode and its system oscillator stopped, situations such as external edge transitions on the external interrupt pins, a low power supply voltage or comparator input change may cause their respective interrupt flag to be set high and consequently generate an interrupt. Care must therefore be taken if spurious wake-up situations are to be avoided. If an interrupt wake-up function is to be disabled then the corresponding interrupt request flag should be set high before the device enters the SLEEP or IDLE Mode. The interrupt enable bits have no effect on the interrupt wake-up function.

Programming Considerations

By disabling the relevant interrupt enable bits, a requested interrupt can be prevented from being serviced, however, once an interrupt request flag is set, it will remain in this condition in the interrupt register until the corresponding interrupt is serviced or until the request flag is cleared by the application program.

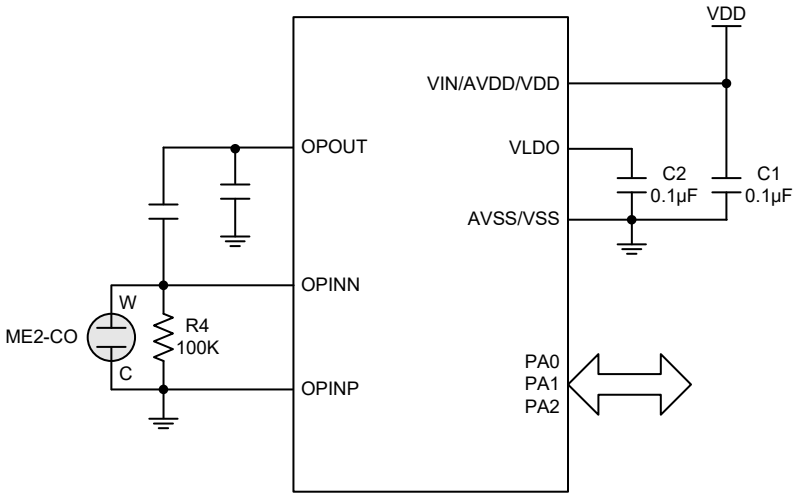
It is recommended that programs do not use the "CALL" instruction within the interrupt service subroutine. Interrupts often occur in an unpredictable manner or need to be serviced immediately. If only one stack is left and the interrupt is not well controlled, the original control sequence will be damaged once a CALL subroutine is executed in the interrupt subroutine.

Every interrupt has the capability of waking up the microcontroller when it is in SLEEP or IDLE Mode, the wake up being generated when the interrupt request flag changes from low to high. If it is required to prevent a certain interrupt from waking up the microcontroller then its respective request flag should be first set high before enter SLEEP or IDLE Mode.

As only the Program Counter is pushed onto the stack, then when the interrupt is serviced, if the contents of the accumulator, status register or other registers are altered by the interrupt service program, their contents should be saved to the memory at the beginning of the interrupt service routine.

To return from an interrupt subroutine, either an RET or RETI instruction may be executed. The RETI instruction in addition to executing a return to the main program also automatically sets the EMI bit high to allow further interrupts. The RET instruction however only executes a return to the main program leaving the EMI bit in its present zero state and therefore disabling the execution of further interrupts.

Application Circuits



Instruction Set

Introduction

Central to the successful operation of any microcontroller is its instruction set, which is a set of program instruction codes that directs the microcontroller to perform certain operations. In the case of Holtek microcontroller, a comprehensive and flexible set of over 60 instructions is provided to enable programmers to implement their application with the minimum of programming overheads.

For easier understanding of the various instruction codes, they have been subdivided into several functional groupings.

Instruction Timing

Most instructions are implemented within one instruction cycle. The exceptions to this are branch, call, or table read instructions where two instruction cycles are required. One instruction cycle is equal to 4 system clock cycles, therefore in the case of an 8MHz system oscillator, most instructions would be implemented within 0.5μs and branch or call instructions would be implemented within 1μs. Although instructions which require one more cycle to implement are generally limited to the JMP, CALL, RET, RETI and table read instructions, it is important to realize that any other instructions which involve manipulation of the Program Counter Low register or PCL will also take one more cycle to implement. As instructions which change the contents of the PCL will imply a direct jump to that new address, one more cycle will be required. Examples of such instructions would be "CLR PCL" or "MOV PCL, A". For the case of skip instructions, it must be noted that if the result of the comparison involves a skip operation then this will also take one more cycle, if no skip is involved then only one cycle is required.

Moving and Transferring Data

The transfer of data within the microcontroller program is one of the most frequently used operations. Making use of three kinds of MOV instructions, data can be transferred from registers to the Accumulator and vice-versa as well as being able to move specific immediate data directly into the Accumulator. One of the most important data transfer applications is to receive data from the input ports and transfer data to the output ports.

Arithmetic Operations

The ability to perform certain arithmetic operations and data manipulation is a necessary feature of most microcontroller applications. Within the Holtek microcontroller instruction set are a range of add and subtract instruction mnemonics to enable the necessary arithmetic to be carried out. Care must be taken to ensure correct handling of carry and borrow data when results exceed 255 for addition and less than 0 for subtraction. The increment and decrement instructions INC, INCA, DEC and DECA provide a simple means of increasing or decreasing by a value of one of the values in the destination specified.

Logical and Rotate Operation

The standard logical operations such as AND, OR, XOR and CPL all have their own instruction within the Holtek microcontroller instruction set. As with the case of most instructions involving data manipulation, data must pass through the Accumulator which may involve additional programming steps. In all logical data operations, the zero flag may be set if the result of the operation is zero. Another form of logical data manipulation comes from the rotate instructions such as RR, RL, RRC and RLC which provide a simple means of rotating one bit right or left. Different rotate instructions exist depending on program requirements. Rotate instructions are useful for serial port programming applications where data can be rotated from an internal register into the Carry bit from where it can be examined and the necessary serial bit set high or low. Another application which rotate data operations are used is to implement multiplication and division calculations.

Branches and Control Transfer

Program branching takes the form of either jumps to specified locations using the JMP instruction or to a subroutine using the CALL instruction. They differ in the sense that in the case of a subroutine call, the program must return to the instruction immediately when the subroutine has been carried out. This is done by placing a return instruction "RET" in the subroutine which will cause the program to jump back to the address right after the CALL instruction. In the case of a JMP instruction, the program simply jumps to the desired location. There is no requirement to jump back to the original jumping off point as in the case of the CALL instruction. One special and extremely useful set of branch instructions are the conditional branches. Here a decision is first made regarding the condition of a certain data memory or individual bits. Depending upon the conditions, the program will continue with the next instruction or skip over it and jump to the following instruction. These instructions are the key to decision making and branching within the program perhaps determined by the condition of certain input switches or by the condition of internal data bits.

Bit Operations

The ability to provide single bit operations on Data Memory is an extremely flexible feature of all Holtek microcontrollers. This feature is especially useful for output port bit programming where individual bits or port pins can be directly set high or low using either the "SET [m].i" or "CLR [m].i" instructions respectively. The feature removes the need for programmers to first read the 8-bit output port, manipulate the input data to ensure that other bits are not changed and then output the port with the correct new data. This read-modify-write process is taken care of automatically when these bit operation instructions are used.

Table Read Operations

Data storage is normally implemented by using registers. However, when working with large amounts of fixed data, the volume involved often makes it inconvenient to store the fixed data in the Data Memory. To overcome this problem, Holtek microcontrollers allow an area of Program Memory to be set as a table where data can be directly stored. A set of easy to use instructions provides the means by which this fixed data can be referenced and retrieved from the Program Memory.

Other Operations

In addition to the above functional instructions, a range of other instructions also exist such as the "HALT" instruction for Power-down operations and instructions to control the operation of the Watchdog Timer for reliable program operations under extreme electric or electromagnetic environments. For their relevant operations, refer to the functional related sections.

Instruction Set Summary

The following table depicts a summary of the instruction set categorised according to function and can be consulted as a basic instruction reference using the following listed conventions.

Table Conventions

x: Bits immediate data
m: Data Memory address
A: Accumulator
i: 0~7 number of bits
addr: Program memory address

Mnemonic	Description	Cycles	Flag Affected
Arithmetic			
ADD A,[m]	Add Data Memory to ACC	1	Z, C, AC, OV
ADDM A,[m]	Add ACC to Data Memory	1Note	Z, C, AC, OV
ADD A,x	Add immediate data to ACC	1	Z, C, AC, OV
ADC A,[m]	Add Data Memory to ACC with Carry	1	Z, C, AC, OV
ADCM A,[m]	Add ACC to Data memory with Carry	1Note	Z, C, AC, OV
SUB A,x	Subtract immediate data from the ACC	1	Z, C, AC, OV
SUB A,[m]	Subtract Data Memory from ACC	1	Z, C, AC, OV
SUBM A,[m]	Subtract Data Memory from ACC with result in Data Memory	1Note	Z, C, AC, OV
SBC A,[m]	Subtract Data Memory from ACC with Carry	1	Z, C, AC, OV
SBCM A,[m]	Subtract Data Memory from ACC with Carry, result in Data Memory	1Note	Z, C, AC, OV
DAA [m]	Decimal adjust ACC for Addition with result in Data Memory	1Note	C
Logic Operation			
AND A,[m]	Logical AND Data Memory to ACC	1	Z
OR A,[m]	Logical OR Data Memory to ACC	1	Z
XOR A,[m]	Logical XOR Data Memory to ACC	1	Z
ANDM A,[m]	Logical AND ACC to Data Memory	1Note	Z
ORM A,[m]	Logical OR ACC to Data Memory	1Note	Z
XORM A,[m]	Logical XOR ACC to Data Memory	1Note	Z
AND A,x	Logical AND immediate Data to ACC	1	Z
OR A,x	Logical OR immediate Data to ACC	1	Z
XOR A,x	Logical XOR immediate Data to ACC	1	Z
CPL [m]	Complement Data Memory	1Note	Z
CPLA [m]	Complement Data Memory with result in ACC	1	Z
Increment & Decrement			
INCA [m]	Increment Data Memory with result in ACC	1	Z
INC [m]	Increment Data Memory	1Note	Z
DECA [m]	Decrement Data Memory with result in ACC	1	Z
DEC [m]	Decrement Data Memory	1Note	Z
Rotate			
RRA [m]	Rotate Data Memory right with result in ACC	1	None
RR [m]	Rotate Data Memory right	1Note	None
RRCA [m]	Rotate Data Memory right through Carry with result in ACC	1	C
RRC [m]	Rotate Data Memory right through Carry	1Note	C
RLA [m]	Rotate Data Memory left with result in ACC	1	None
RL [m]	Rotate Data Memory left	1Note	None
RLCA [m]	Rotate Data Memory left through Carry with result in ACC	1	C
RLC [m]	Rotate Data Memory left through Carry	1Note	C

Mnemonic	Description	Cycles	Flag Affected
Data Move			
MOV A,[m]	Move Data Memory to ACC	1	None
MOV [m],A	Move ACC to Data Memory	1Note	None
MOV A,x	Move immediate data to ACC	1	None
Bit Operation			
CLR [m].i	Clear bit of Data Memory	1Note	None
SET [m].i	Set bit of Data Memory	1Note	None
Branch Operation			
JMP addr	Jump unconditionally	2	None
SZ [m]	Skip if Data Memory is zero	1Note	None
SZA [m]	Skip if Data Memory is zero with data movement to ACC	1Note	None
SZ [m].i	Skip if bit i of Data Memory is zero	1Note	None
SNZ [m].i	Skip if bit i of Data Memory is not zero	1Note	None
SIZ [m]	Skip if increment Data Memory is zero	1Note	None
SDZ [m]	Skip if decrement Data Memory is zero	1Note	None
SIZA [m]	Skip if increment Data Memory is zero with result in ACC	1Note	None
SDZA [m]	Skip if decrement Data Memory is zero with result in ACC	1Note	None
CALL addr	Subroutine call	2	None
RET	Return from subroutine	2	None
RET A,x	Return from subroutine and load immediate data to ACC	2	None
RETI	Return from interrupt	2	None
Table Read Operation			
TABRD [m]	Read table (specific page or current page) to TBLH and Data Memory	2Note	None
TABRDL [m]	Read table (last page) to TBLH and Data Memory	2Note	None
Miscellaneous			
NOP	No operation	1	None
CLR [m]	Clear Data Memory	1Note	None
SET [m]	Set Data Memory	1Note	None
CLR WDT	Clear Watchdog Timer	1	TO, PDF
SWAP [m]	Swap nibbles of Data Memory	1Note	None
SWAPA [m]	Swap nibbles of Data Memory with result in ACC	1	None
HALT	Enter power down mode	1	TO, PDF

Note: 1. For skip instructions, if the result of the comparison involves a skip then two cycles are required, if no skip takes place only one cycle is required.
2. Any instruction which changes the contents of the PCL will also require 2 cycles for execution.

Instruction Definition

ADC A,[m] Add Data Memory to ACC with Carry

Description: The contents of the specified Data Memory, Accumulator and the carry flag are added. The result is stored in the Accumulator.

Operation: ACC ← ACC + [m] + C

Affected flag(s): OV, Z, AC, C

ADCM A,[m] Add ACC to Data Memory with Carry

Description: The contents of the specified Data Memory, Accumulator and the carry flag are added. The result is stored in the specified Data Memory.

Operation: [m] ← ACC + [m] + C

Affected flag(s): OV, Z, AC, C

ADD A,[m] Add Data Memory to ACC

Description: The contents of the specified Data Memory and the Accumulator are added. The result is stored in the Accumulator.

Operation: ACC ← ACC + [m]

Affected flag(s): OV, Z, AC, C

ADD A,x Add immediate data to ACC

Description: The contents of the Accumulator and the specified immediate data are added. The result is stored in the Accumulator.

Operation: ACC ← ACC + x

Affected flag(s): OV, Z, AC, C

ADDM A,[m] Add ACC to Data Memory

Description: The contents of the specified Data Memory and the Accumulator are added. The result is stored in the specified Data Memory.

Operation: [m] ← ACC + [m]

Affected flag(s): OV, Z, AC, C

AND A,[m] Logical AND Data Memory to ACC

Description: Data in the Accumulator and the specified Data Memory perform a bitwise logical AND operation. The result is stored in the Accumulator.

Operation: ACC ← ACC "AND" [m]

Affected flag(s): Z

AND A,x Logical AND immediate data to ACC

Description: Data in the Accumulator and the specified immediate data perform a bit wise logical AND operation. The result is stored in the Accumulator.

Operation: ACC ← ACC "AND" x

Affected flag(s): Z

ANDM A,[m] Logical AND ACC to Data Memory

Description: Data in the specified Data Memory and the Accumulator perform a bitwise logical AND operation. The result is stored in the Data Memory.

Operation: [m] ← ACC "AND" [m]

Affected flag(s): Z

CALL addr Subroutine call

Description Unconditionally calls a subroutine at the specified address. The Program Counter then increments by 1 to obtain the address of the next instruction which is then pushed onto the stack. The specified address is then loaded and the program continues execution from this new address. As this instruction requires an additional operation, it is a two cycle instruction.

Operation Stack ← Program Counter + 1
Program Counter ← addr

Affected flag(s) None

CLR [m] Clear Data Memory

Description Each bit of the specified Data Memory is cleared to 0.

Operation [m] ← 00H

Affected flag(s) None

CLR [m].i Clear bit of Data Memory

Description Bit i of the specified Data Memory is cleared to 0.

Operation [m].i ← 0

Affected flag(s) None

CLR WDT Clear Watchdog Timer

Description The TO, PDF flags and the WDT are all cleared.

Operation WDT cleared
TO ← 0
PDF ← 0

Affected flag(s) TO, PDF

CPL [m] Complement Data Memory

Description Each bit of the specified Data Memory is logically complemented (1′s complement). Bits which previously contained a 1 are changed to 0 and vice versa.

Operation [m] ← $\overline{[m]}$

Affected flag(s) Z

CPLA [m] Complement Data Memory with result in ACC

Description Each bit of the specified Data Memory is logically complemented (1′s complement). Bits which previously contained a 1 are changed to 0 and vice versa. The complemented result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation ACC ← $\overline{[m]}$

Affected flag(s) Z

DAA [m] Decimal-Adjust ACC for addition with result in Data Memory

Description Convert the contents of the Accumulator value to a BCD (Binary Coded Decimal) value resulting from the previous addition of two BCD variables. If the low nibble is greater than 9 or if AC flag is set, then a value of 6 will be added to the low nibble. Otherwise the low nibble remains unchanged. If the high nibble is greater than 9 or if the C flag is set, then a value of 6 will be added to the high nibble. Essentially, the decimal conversion is performed by adding 00H, 06H, 60H or 66H depending on the Accumulator and flag conditions. Only the C flag may be affected by this instruction which indicates that if the original BCD sum is greater than 100, it allows multiple precision decimal addition.

Operation [m] ← ACC + 00H or
[m] ← ACC + 06H or
[m] ← ACC + 60H or
[m] ← ACC + 66H

Affected flag(s) C

DEC [m] Decrement Data Memory

Description: Data in the specified Data Memory is decremented by 1.

Operation: [m] ← [m] − 1

Affected flag(s): Z

DECA [m] Decrement Data Memory with result in ACC

Description: Data in the specified Data Memory is decremented by 1. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.

Operation: ACC ← [m] − 1

Affected flag(s): Z

HALT Enter power down mode

Description: This instruction stops the program execution and turns off the system clock. The contents of the Data Memory and registers are retained. The WDT and prescaler are cleared. The power down flag PDF is set and the WDT time-out flag TO is cleared.

Operation: TO ← 0
PDF ← 1

Affected flag(s): TO, PDF

INC [m] Increment Data Memory

Description: Data in the specified Data Memory is incremented by 1.

Operation: [m] ← [m] + 1

Affected flag(s): Z

INCA [m] Increment Data Memory with result in ACC

Description: Data in the specified Data Memory is incremented by 1. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.

Operation: ACC ← [m] + 1

Affected flag(s): Z

JMP addr Jump unconditionally

Description: The contents of the Program Counter are replaced with the specified address. Program execution then continues from this new address. As this requires the insertion of a dummy instruction while the new address is loaded, it is a two cycle instruction.

Operation: Program Counter ← addr

Affected flag(s): None

MOV A,[m] Move Data Memory to ACC

Description: The contents of the specified Data Memory are copied to the Accumulator.

Operation: ACC ← [m]

Affected flag(s): None

MOV A,x Move immediate data to ACC

Description: The immediate data specified is loaded into the Accumulator.

Operation: ACC ← x

Affected flag(s): None

MOV [m],A Move ACC to Data Memory

Description: The contents of the Accumulator are copied to the specified Data Memory.

Operation: [m] ← ACC

Affected flag(s): None

NOP No operation

Description No operation is performed. Execution continues with the next instruction.

Operation No operation

Affected flag(s) None

OR A,[m] Logical OR Data Memory to ACC

Description Data in the Accumulator and the specified Data Memory perform a bitwise logical OR operation. The result is stored in the Accumulator.

Operation ACC ← ACC "OR" [m]

Affected flag(s) Z

OR A,x Logical OR immediate data to ACC

Description Data in the Accumulator and the specified immediate data perform a bitwise logical OR operation. The result is stored in the Accumulator.

Operation ACC ← ACC "OR" x

Affected flag(s) Z

ORM A,[m] Logical OR ACC to Data Memory

Description Data in the specified Data Memory and the Accumulator perform a bitwise logical OR operation. The result is stored in the Data Memory.

Operation [m] ← ACC "OR" [m]

Affected flag(s) Z

RET Return from subroutine

Description The Program Counter is restored from the stack. Program execution continues at the restored address.

Operation Program Counter ← Stack

Affected flag(s) None

RET A,x Return from subroutine and load immediate data to ACC

Description The Program Counter is restored from the stack and the Accumulator loaded with the specified immediate data. Program execution continues at the restored address.

Operation Program Counter ← Stack
ACC ← x

Affected flag(s) None

RETI Return from interrupt

Description The Program Counter is restored from the stack and the interrupts are re-enabled by setting the EMI bit. EMI is the master interrupt global enable bit. If an interrupt was pending when the RETI instruction is executed, the pending Interrupt routine will be processed before returning to the main program.

Operation Program Counter ← Stack
EMI ← 1

Affected flag(s) None

RL [m] Rotate Data Memory left

Description The contents of the specified Data Memory are rotated left by 1 bit with bit 7 rotated into bit 0.

Operation [m].(i+1) ← [m].i; (i=0~6)
[m].0 ← [m].7

Affected flag(s) None

RLA [m] Rotate Data Memory left with result in ACC

Description The contents of the specified Data Memory are rotated left by 1 bit with bit 7 rotated into bit 0. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation ACC.(i+1) ← [m].i; (i=0~6)
ACC.0 ← [m].7

Affected flag(s) None

RLC [m] Rotate Data Memory left through Carry

Description The contents of the specified Data Memory and the carry flag are rotated left by 1 bit. Bit 7 replaces the Carry bit and the original carry flag is rotated into bit 0.

Operation [m].(i+1) ← [m].i; (i=0~6)
[m].0 ← C
C ← [m].7

Affected flag(s) C

RLCA [m] Rotate Data Memory left through Carry with result in ACC

Description Data in the specified Data Memory and the carry flag are rotated left by 1 bit. Bit 7 replaces the Carry bit and the original carry flag is rotated into the bit 0. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation ACC.(i+1) ← [m].i; (i=0~6)
ACC.0 ← C
C ← [m].7

Affected flag(s) C

RR [m] Rotate Data Memory right

Description The contents of the specified Data Memory are rotated right by 1 bit with bit 0 rotated into bit 7.

Operation [m].i ← [m].(i+1); (i=0~6)
[m].7 ← [m].0

Affected flag(s) None

RRA [m] Rotate Data Memory right with result in ACC

Description Data in the specified Data Memory is rotated right by 1 bit with bit 0 rotated into bit 7.
The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation ACC.i ← [m].(i+1); (i=0~6)
ACC.7 ← [m].0

Affected flag(s) None

RRC [m] Rotate Data Memory right through Carry

Description The contents of the specified Data Memory and the carry flag are rotated right by 1 bit. Bit 0 replaces the Carry bit and the original carry flag is rotated into bit 7.

Operation [m].i ← [m].(i+1); (i=0~6)
[m].7 ← C
C ← [m].0

Affected flag(s) C

RRCA [m] Rotate Data Memory right through Carry with result in ACC

Description: Data in the specified Data Memory and the carry flag are rotated right by 1 bit. Bit 0 replaces the Carry bit and the original carry flag is rotated into bit 7. The rotated result is stored in the Accumulator and the contents of the Data Memory remain unchanged.

Operation:
ACC.i ← [m].(i+1); (i=0~6)
ACC.7 ← C
C ← [m].0

Affected flag(s): C

SBC A,[m] Subtract Data Memory from ACC with Carry

Description: The contents of the specified Data Memory and the complement of the carry flag are subtracted from the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation: ACC ← ACC − [m] − $\overline{C}$

Affected flag(s): OV, Z, AC, C

SBCM A,[m] Subtract Data Memory from ACC with Carry and result in Data Memory

Description: The contents of the specified Data Memory and the complement of the carry flag are subtracted from the Accumulator. The result is stored in the Data Memory. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation: [m] ← ACC − [m] − $\overline{C}$

Affected flag(s): OV, Z, AC, C

SDZ [m] Skip if decrement Data Memory is 0

Description: The contents of the specified Data Memory are first decremented by 1. If the result is 0 the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation:
[m] ← [m] − 1
Skip if [m]=0

Affected flag(s): None

SDZA [m] Skip if decrement Data Memory is zero with result in ACC

Description: The contents of the specified Data Memory are first decremented by 1. If the result is 0, the following instruction is skipped. The result is stored in the Accumulator but the specified Data Memory contents remain unchanged. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0, the program proceeds with the following instruction.

Operation:
ACC ← [m] − 1
Skip if ACC=0

Affected flag(s): None

SET [m] Set Data Memory

Description: Each bit of the specified Data Memory is set to 1.

Operation: [m] ← FFH

Affected flag(s): None

SET [m].i Set bit of Data Memory

Description: Bit i of the specified Data Memory is set to 1.

Operation: [m].i ← 1

Affected flag(s): None

SIZ [m] Skip if increment Data Memory is 0

Description The contents of the specified Data Memory are first incremented by 1. If the result is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation [m] ← [m] + 1
Skip if [m]=0

Affected flag(s) None

SIZA [m] Skip if increment Data Memory is zero with result in ACC

Description The contents of the specified Data Memory are first incremented by 1. If the result is 0, the following instruction is skipped. The result is stored in the Accumulator but the specified Data Memory contents remain unchanged. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation ACC ← [m] + 1
Skip if ACC=0

Affected flag(s) None

SNZ [m].i Skip if bit i of Data Memory is not 0

Description If bit i of the specified Data Memory is not 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is 0 the program proceeds with the following instruction.

Operation Skip if [m].i ≠ 0

Affected flag(s) None

SUB A,[m] Subtract Data Memory from ACC

Description The specified Data Memory is subtracted from the contents of the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation ACC ← ACC − [m]

Affected flag(s) OV, Z, AC, C

SUBM A,[m] Subtract Data Memory from ACC with result in Data Memory

Description The specified Data Memory is subtracted from the contents of the Accumulator. The result is stored in the Data Memory. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation [m] ← ACC − [m]

Affected flag(s) OV, Z, AC, C

SUB A,x Subtract immediate data from ACC

Description The immediate data specified by the code is subtracted from the contents of the Accumulator. The result is stored in the Accumulator. Note that if the result of subtraction is negative, the C flag will be cleared to 0, otherwise if the result is positive or zero, the C flag will be set to 1.

Operation ACC ← ACC − x

Affected flag(s) OV, Z, AC, C

SWAP [m] Swap nibbles of Data Memory

Description The low-order and high-order nibbles of the specified Data Memory are interchanged.

Operation [m].3~[m].0 ↔ [m].7~[m].4

Affected flag(s) None

SWAPA [m] Swap nibbles of Data Memory with result in ACC

Description The low-order and high-order nibbles of the specified Data Memory are interchanged. The result is stored in the Accumulator. The contents of the Data Memory remain unchanged.

Operation ACC.3~ACC.0 ← [m].7~[m].4
ACC.7~ACC.4 ← [m].3~[m].0

Affected flag(s) None

SZ [m] Skip if Data Memory is 0

Description If the contents of the specified Data Memory is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation Skip if [m]=0

Affected flag(s) None

SZA [m] Skip if Data Memory is 0 with data movement to ACC

Description The contents of the specified Data Memory are copied to the Accumulator. If the value is zero, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0 the program proceeds with the following instruction.

Operation ACC ← [m]
Skip if [m]=0

Affected flag(s) None

SZ [m].i Skip if bit i of Data Memory is 0

Description If bit i of the specified Data Memory is 0, the following instruction is skipped. As this requires the insertion of a dummy instruction while the next instruction is fetched, it is a two cycle instruction. If the result is not 0, the program proceeds with the following instruction.

Operation Skip if [m].i=0

Affected flag(s) None

TABRD [m] Read table (specific page or current page) to TBLH and Data Memory

Description The low byte of the program code addressed by the table pointer (TBHP and TBLP or only TBLP if no TBHP) is moved to the specified Data Memory and the high byte moved to TBLH.

Operation [m] ← program code (low byte)
TBLH ← program code (high byte)

Affected flag(s) None

TABRDL [m] Read table (last page) to TBLH and Data Memory

Description The low byte of the program code (last page) addressed by the table pointer (TBLP) is moved to the specified Data Memory and the high byte moved to TBLH.

Operation [m] ← program code (low byte)
TBLH ← program code (high byte)

Affected flag(s) None

XOR A,[m] Logical XOR Data Memory to ACC

Description Data in the Accumulator and the specified Data Memory perform a bitwise logical XOR operation. The result is stored in the Accumulator.

Operation ACC ← ACC ″XOR″ [m]

Affected flag(s) Z

XORM A,[m]	Logical XOR ACC to Data Memory
Description	Data in the specified Data Memory and the Accumulator perform a bitwise logical XOR operation. The result is stored in the Data Memory.
Operation	[m] ← ACC ″XOR″ [m]
Affected flag(s)	Z

XOR A,x	Logical XOR immediate data to ACC
Description	Data in the Accumulator and the specified immediate data perform a bitwise logical XOR operation. The result is stored in the Accumulator.
Operation	ACC ← ACC ″XOR″ x
Affected flag(s)	Z

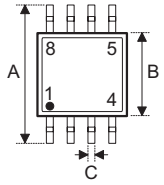
Package Information

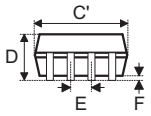
Note that the package information provided here is for consultation purposes only. As this information may be updated at regular intervals users are reminded to consult the Holtek website for the latest version of the Package/Carton Information.

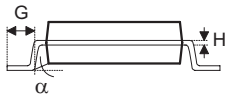
Additional supplementary information with regard to packaging is listed below. Click on the relevant section to be transferred to the relevant website page.

- Package Information (include Outline Dimensions, Product Tape and Reel Specifications)
- The Operation Instruction of Packing Materials
- Carton information

8-pin SOP (150mil) Outline Dimensions



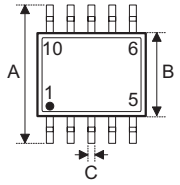


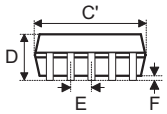


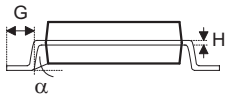
Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	—	0.236 BSC	—
B	—	0.154 BSC	—
C	0.012	—	0.020
C′	—	0.193 BSC	—
D	—	—	0.069
E	—	0.050 BSC	—
F	0.004	—	0.010
G	0.016	—	0.050
H	0.004	—	0.010
α	0°	—	8°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	—	6.00 BSC	—
B	—	3.90 BSC	—
C	0.31	—	0.51
C′	—	4.90 BSC	—
D	—	—	1.75
E	—	1.27 BSC	—
F	0.10	—	0.25
G	0.40	—	1.27
H	0.10	—	0.25
α	0°	—	8°

10-pin SOP (150mil) Outline Dimensions



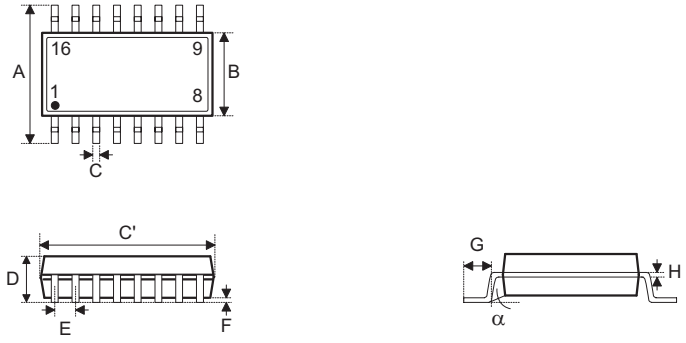




Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	—	0.236 BSC	—
B	—	0.154 BSC	—
C	0.012	—	0.018
C′	—	0.193 BSC	—
D	—	—	0.069
E	—	0.039 BSC	—
F	0.004	—	0.010
G	0.016	—	0.050
H	0.004	—	0.010
α	0°	—	8°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	—	6.00 BSC	—
B	—	3.90 BSC	—
C	0.30	—	0.45
C′	—	4.90 BSC	—
D	—	—	1.75
E	—	1.00 BSC	—
F	0.10	—	0.25
G	0.40	—	1.27
H	0.10	—	0.25
α	0°	—	8°

16-pin NSOP (150mil) Outline Dimensions



Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	—	0.236 BSC	—
B	—	0.154 BSC	—
C	0.012	—	0.020
C’	—	0.390 BSC	—
D	—	—	0.069
E	—	0.050 BSC	—
F	0.004	—	0.010
G	0.016	—	0.050
H	0.004	—	0.010
α	0°	—	8°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	—	6.00 BSC	—
B	—	3.90 BSC	—
C	0.31	—	0.51
C’	—	9.90 BSC	—
D	—	—	1.75
E	—	1.27 BSC	—
F	0.10	—	0.25
G	0.40	—	1.27
H	0.10	—	0.25
α	0°	—	8°